

FIG. 1

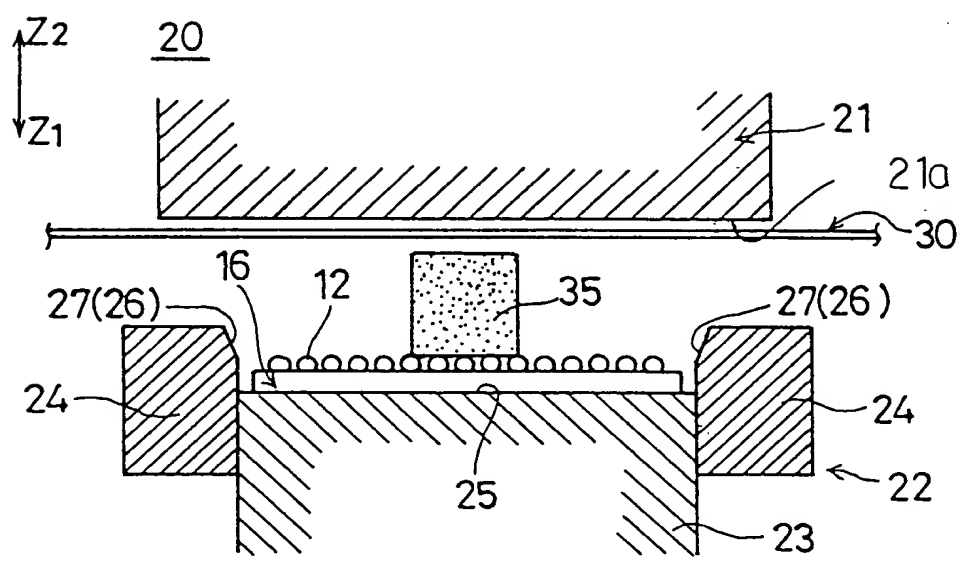


FIG. 1A

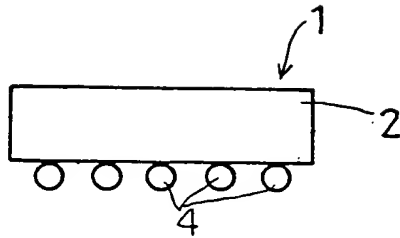


FIG. 1B

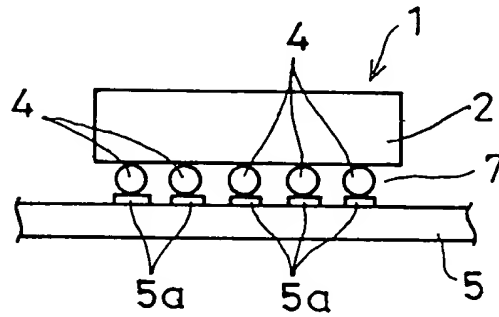


FIG. 1C

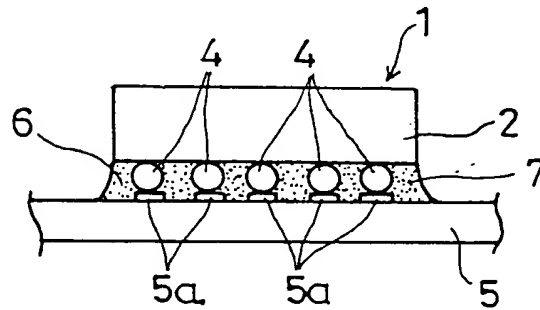


FIG. 2

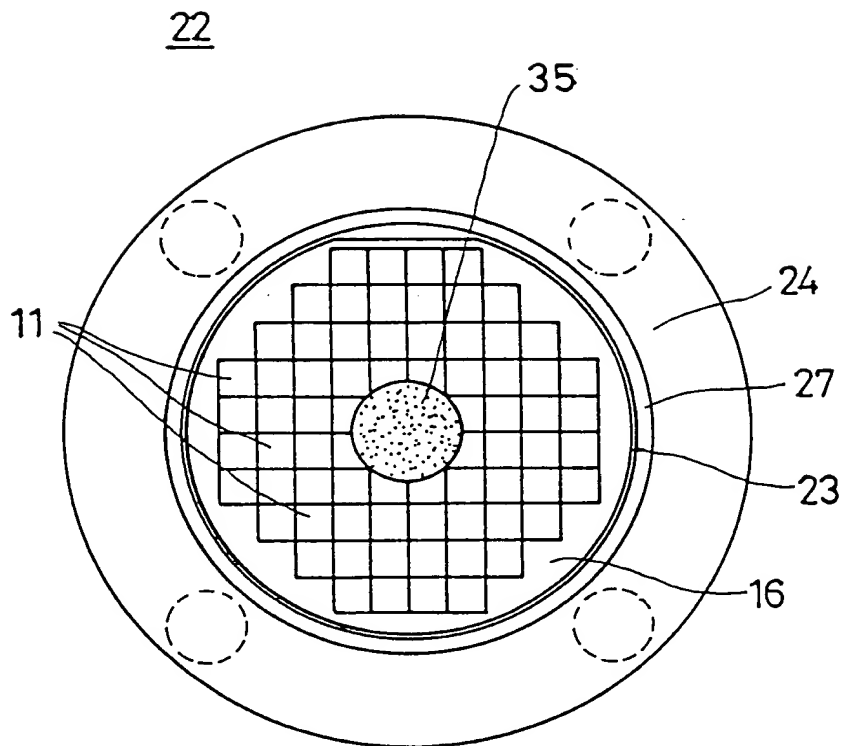


FIG. 3

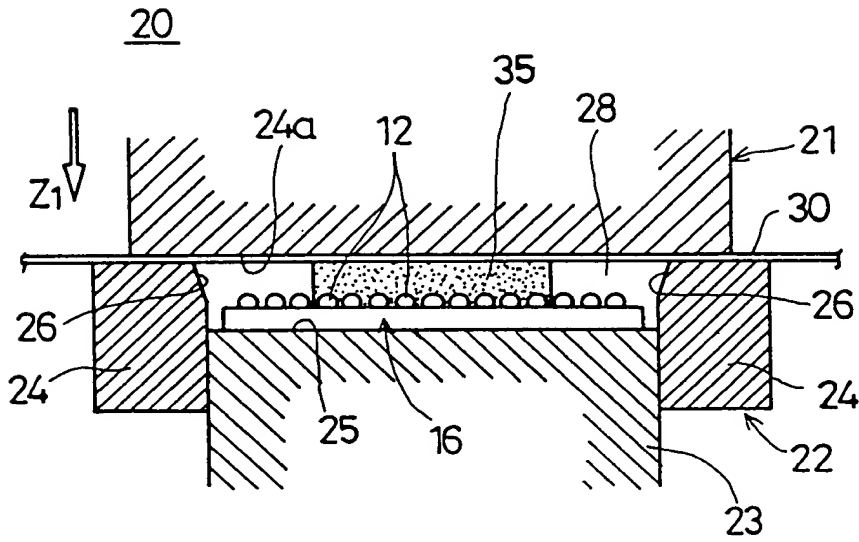


FIG. 4

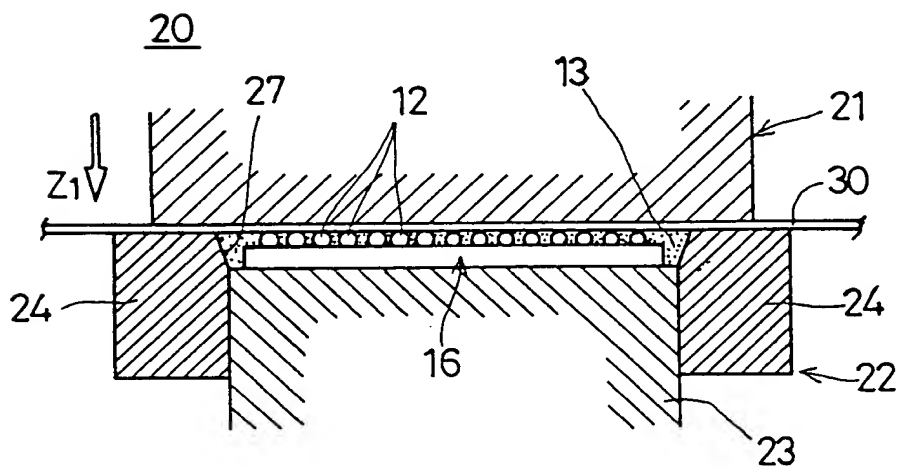
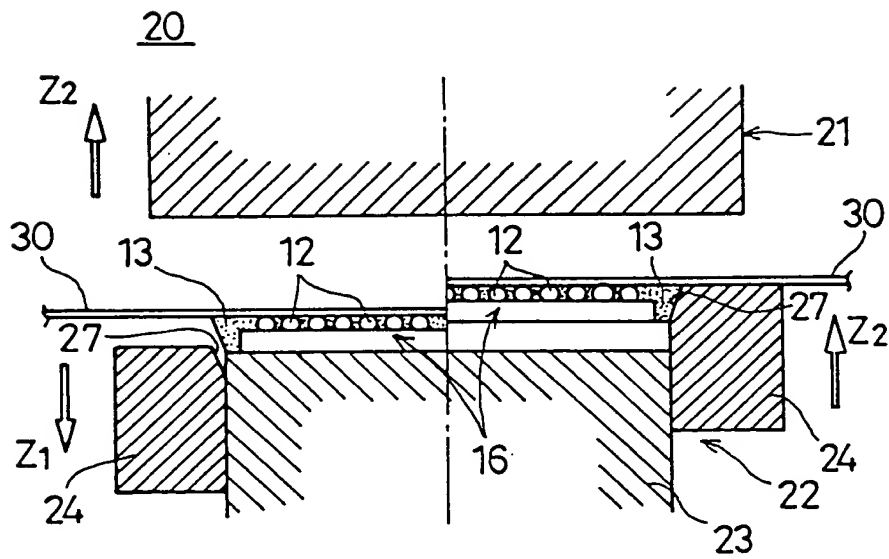
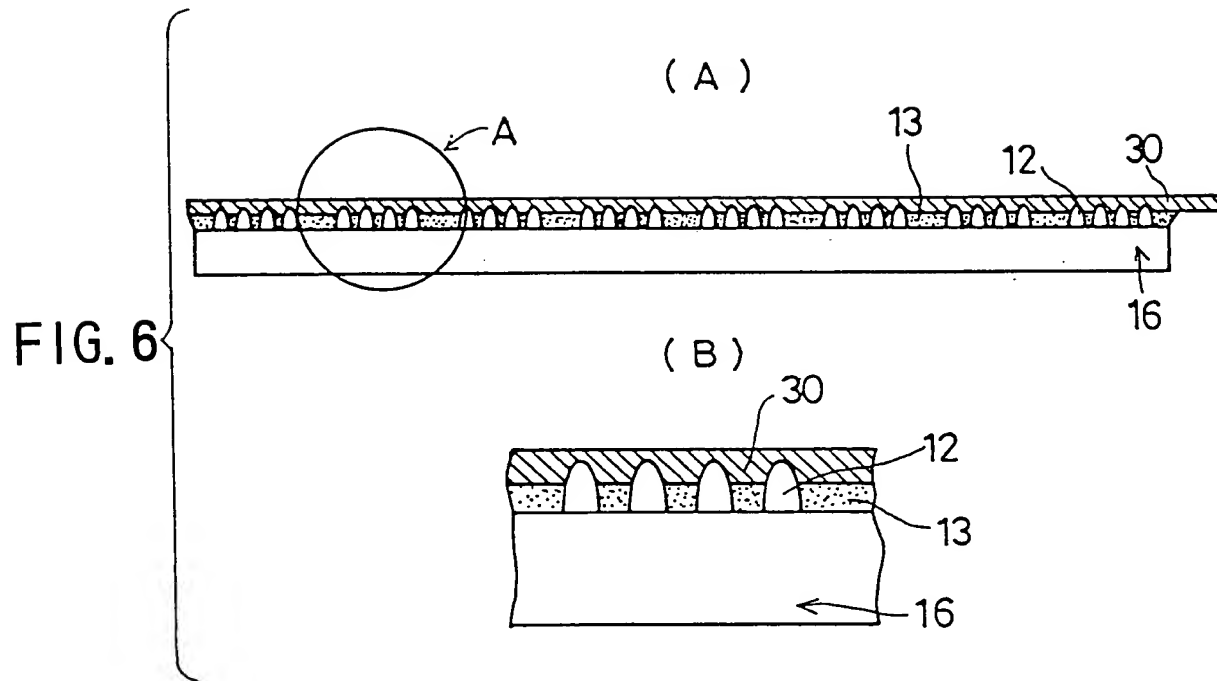


FIG. 5





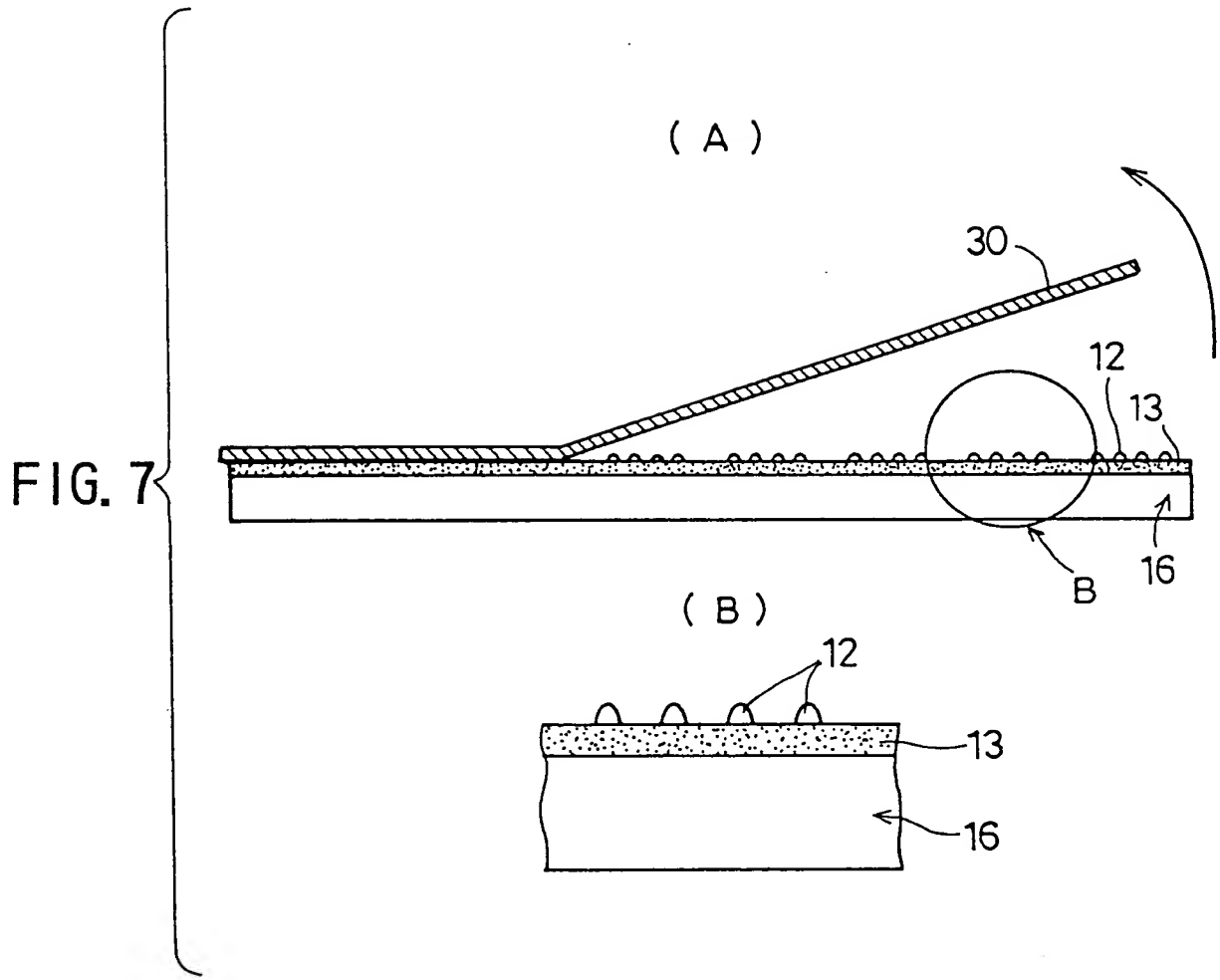


FIG. 8

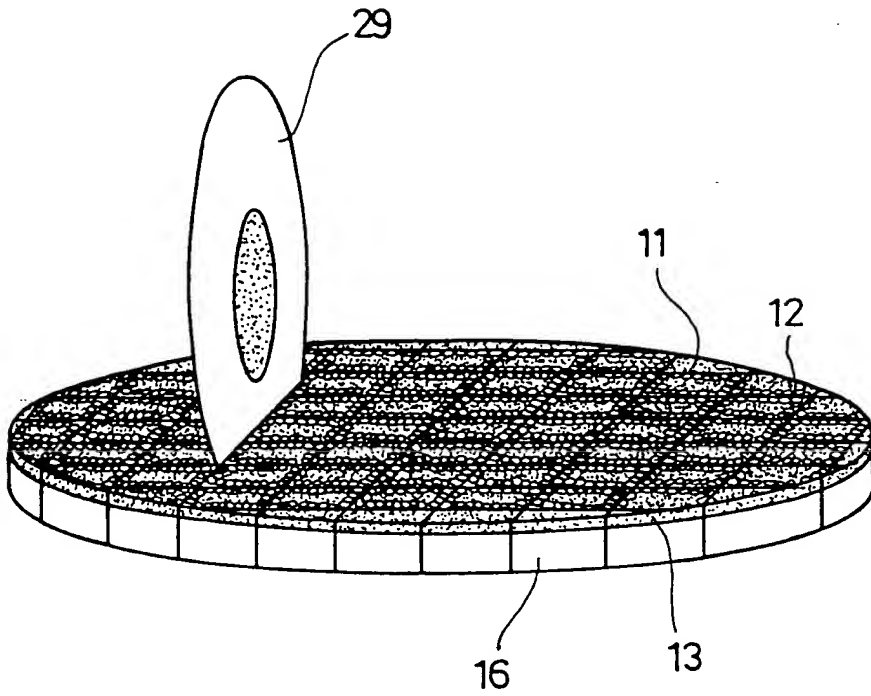


FIG. 9

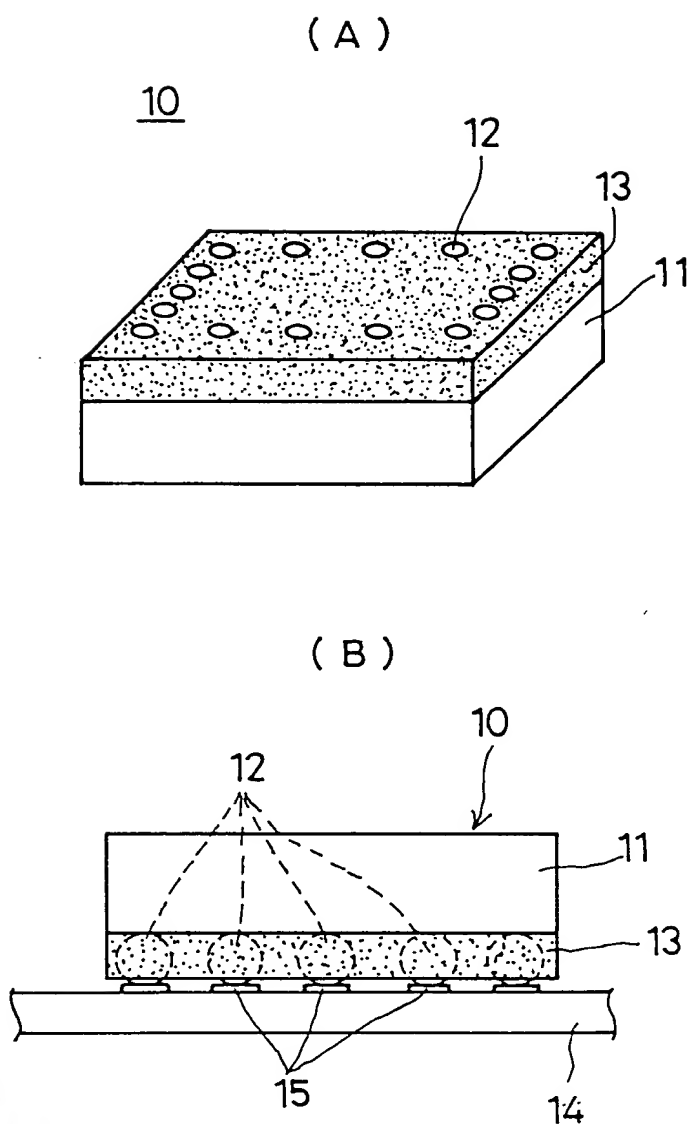




FIG. 11

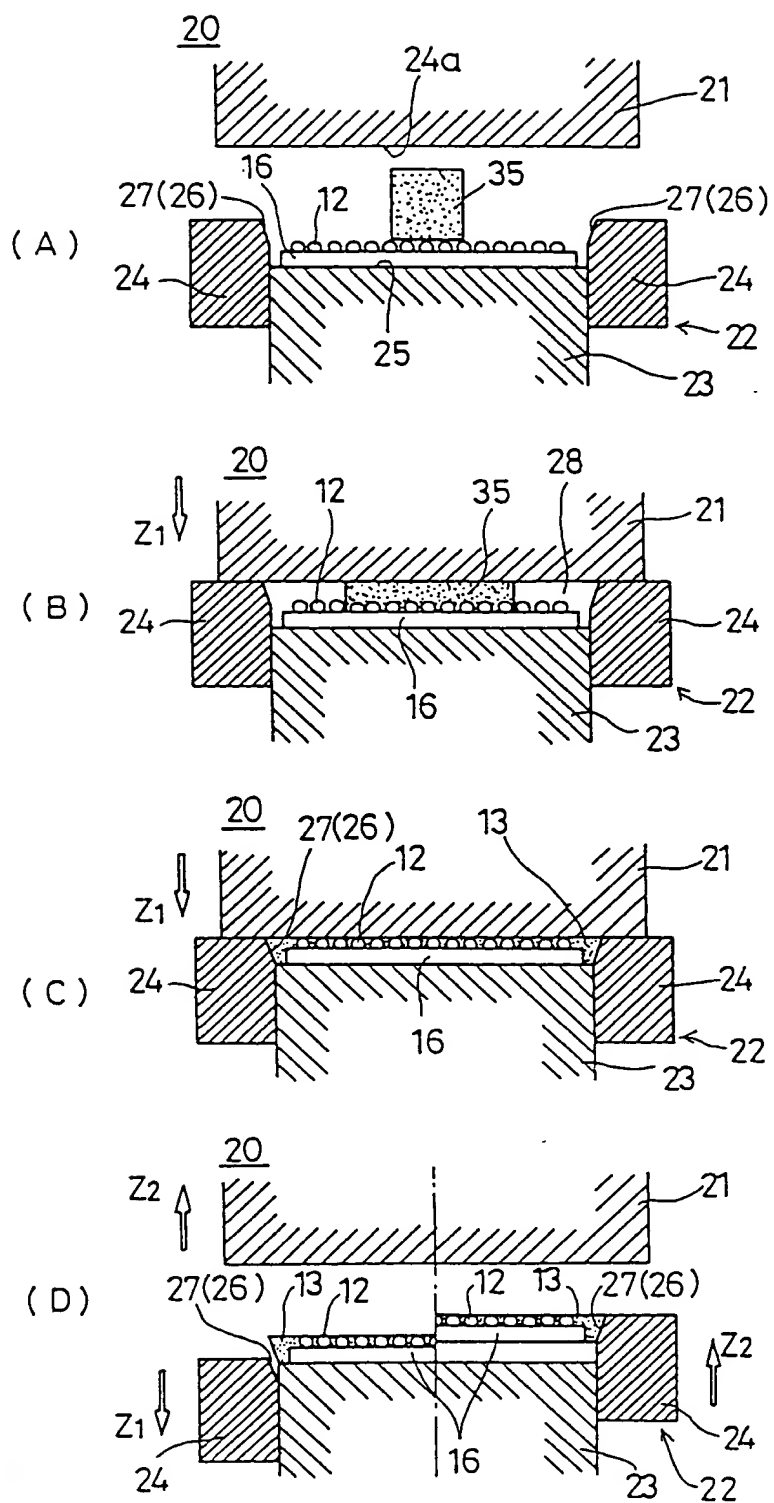


FIG. 12

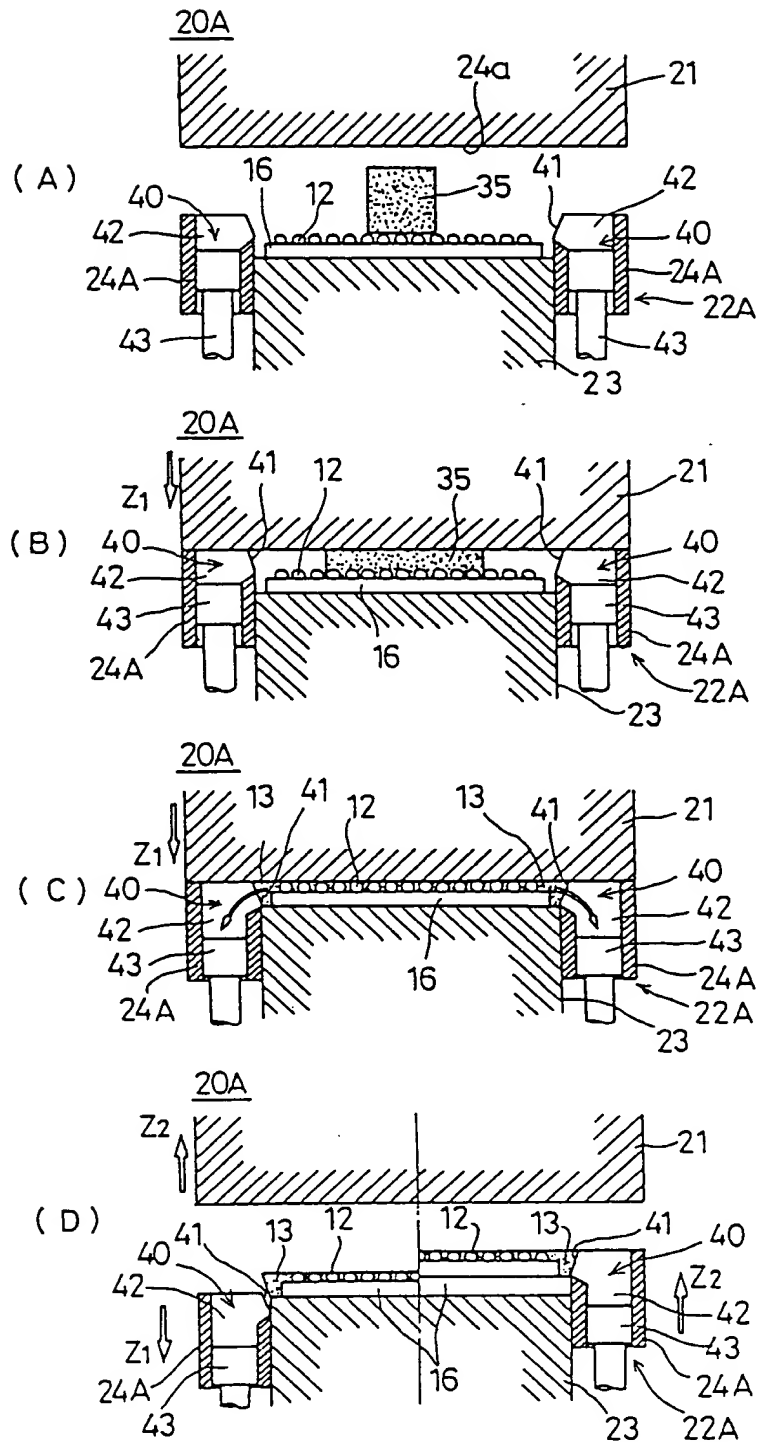
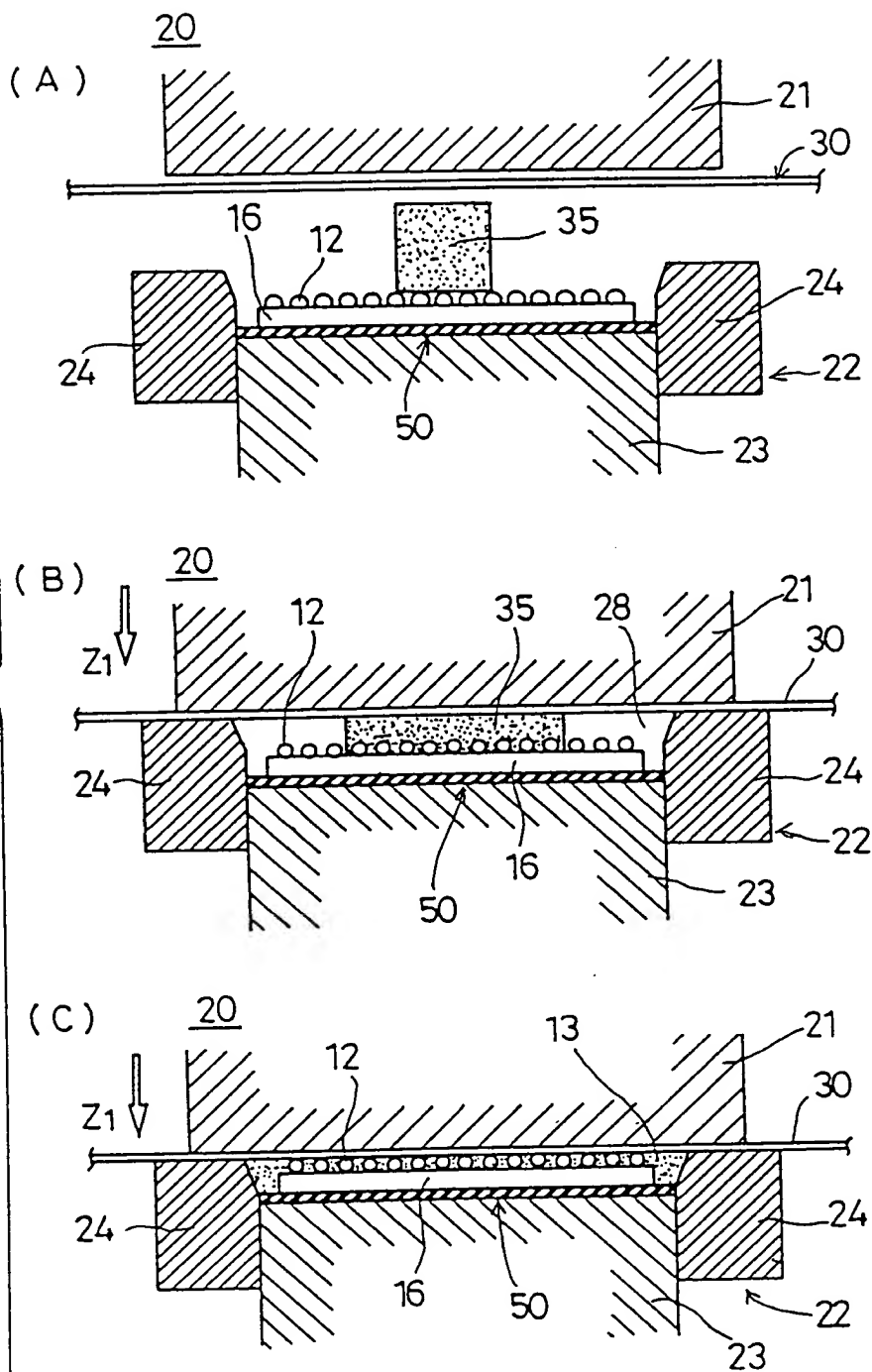


FIG. 13



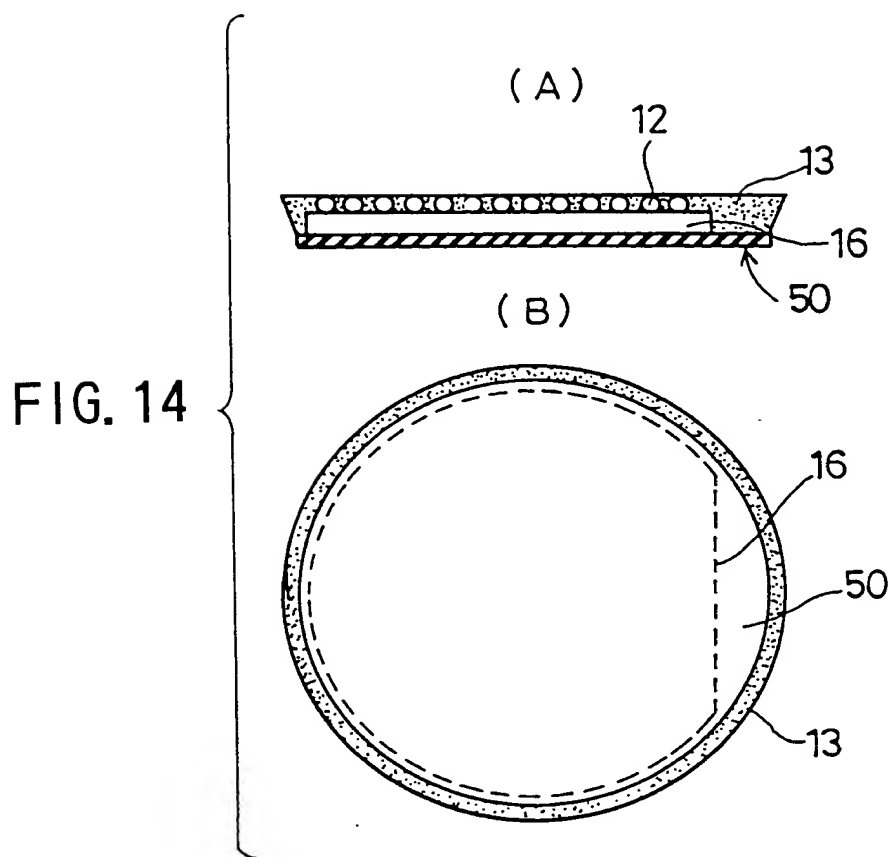


FIG. 15

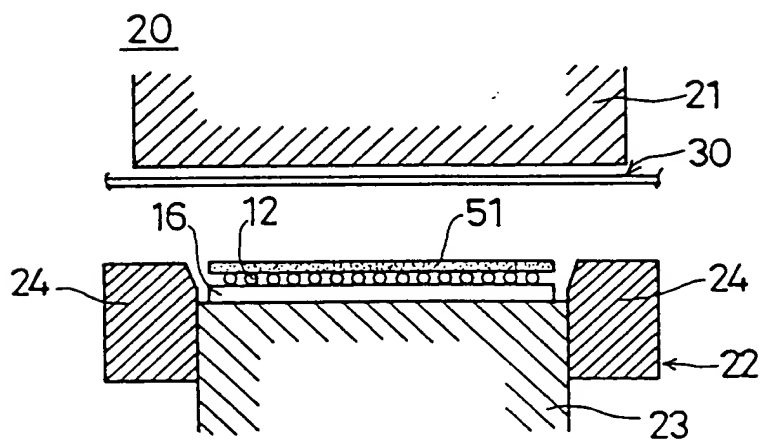


FIG. 16

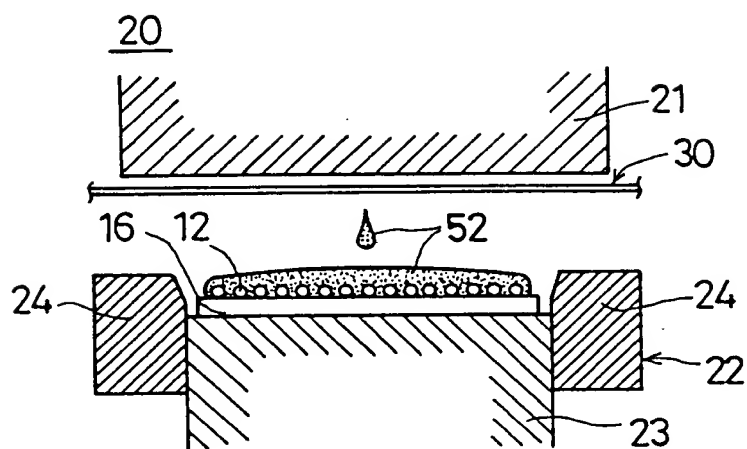


FIG. 17

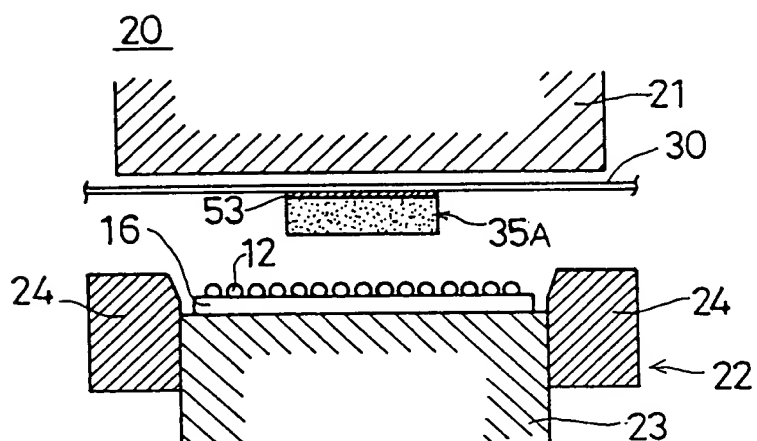


FIG. 18.

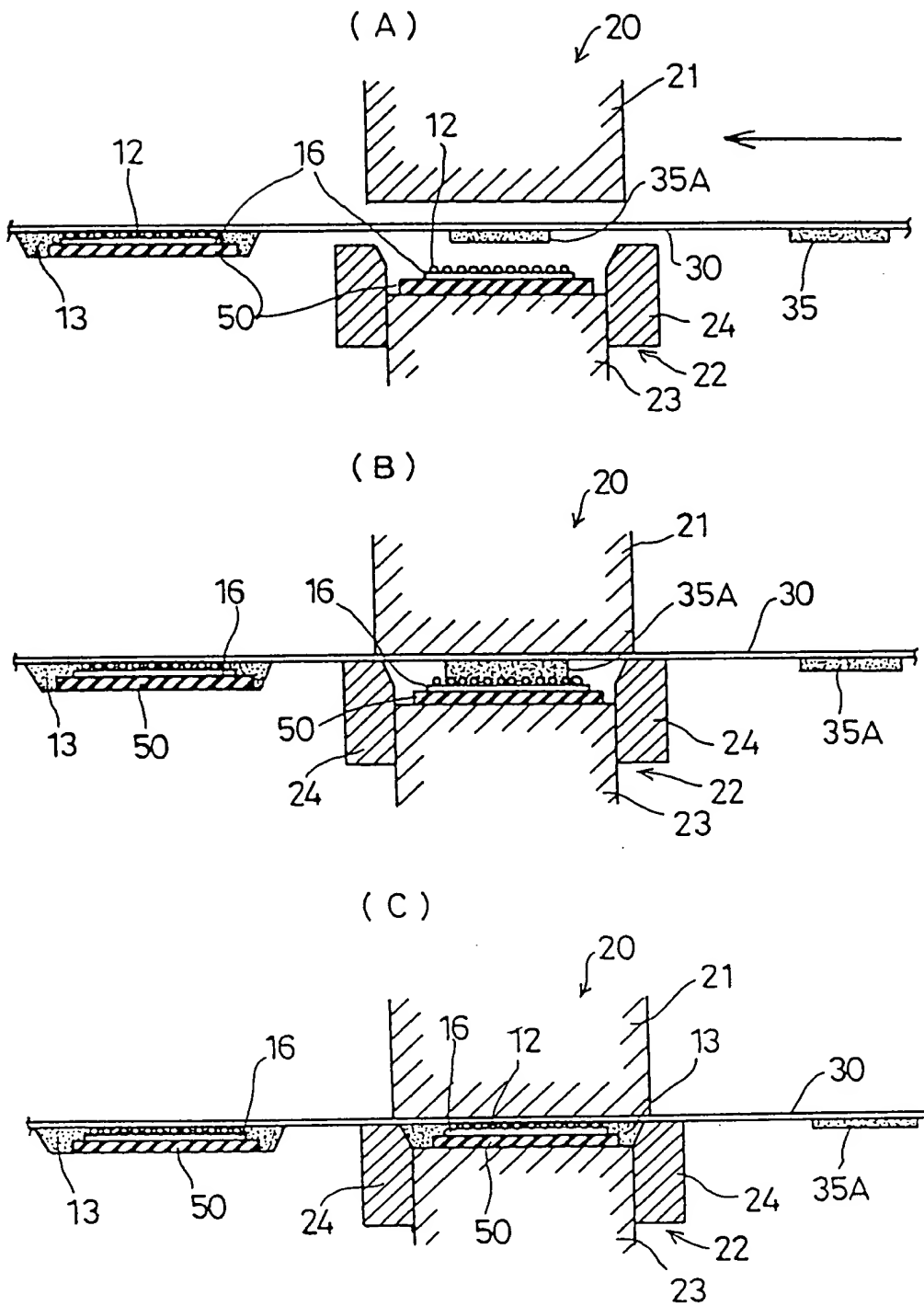


FIG. 19

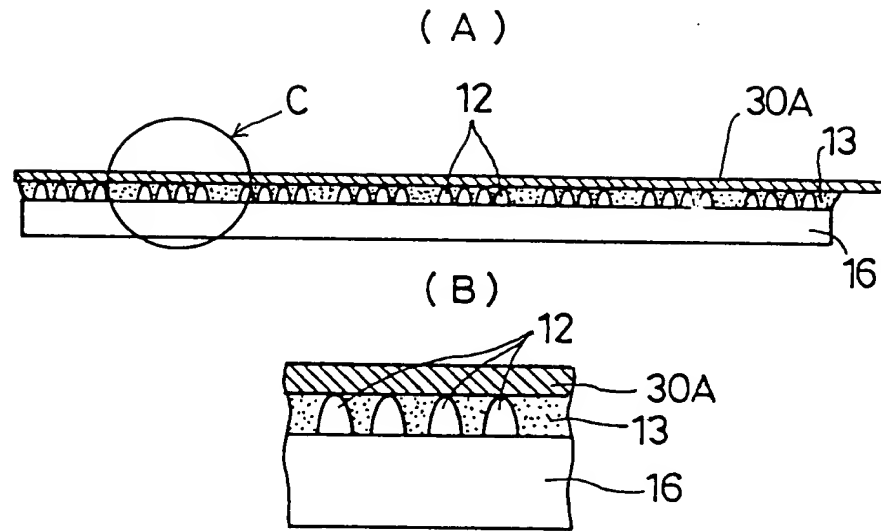


FIG. 20

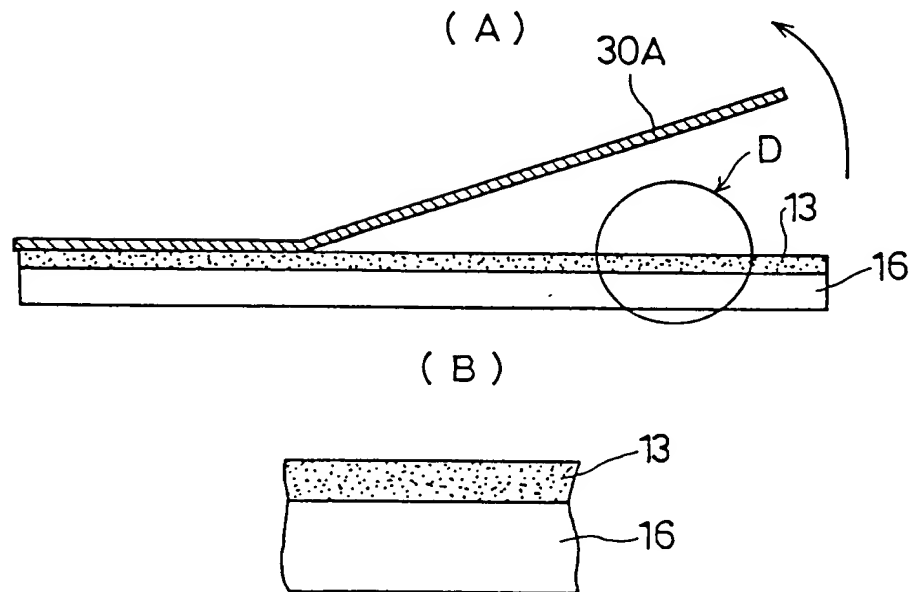


FIG. 21

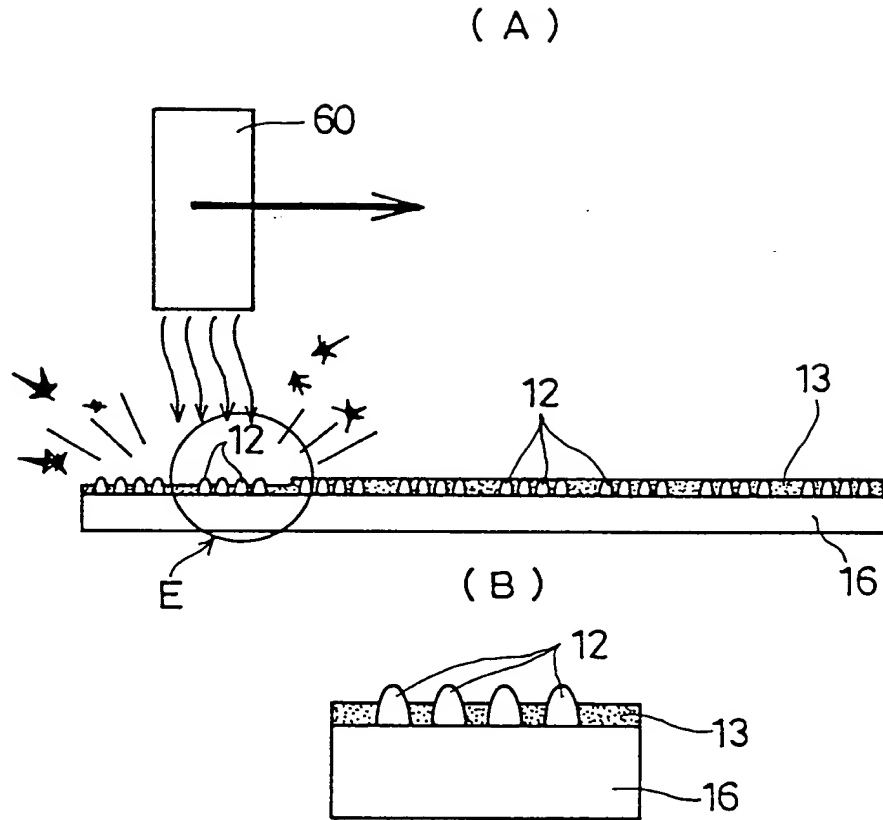


FIG. 22

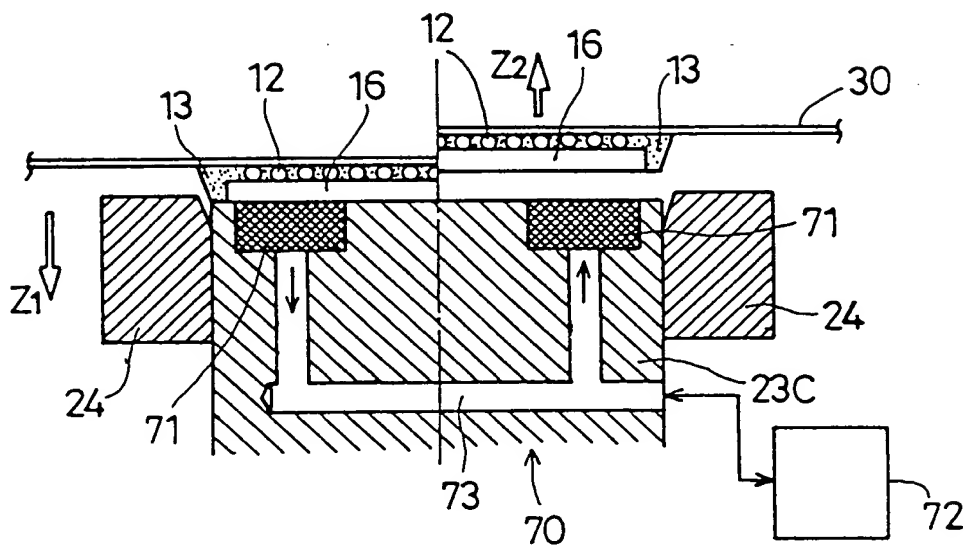
20C

FIG. 23

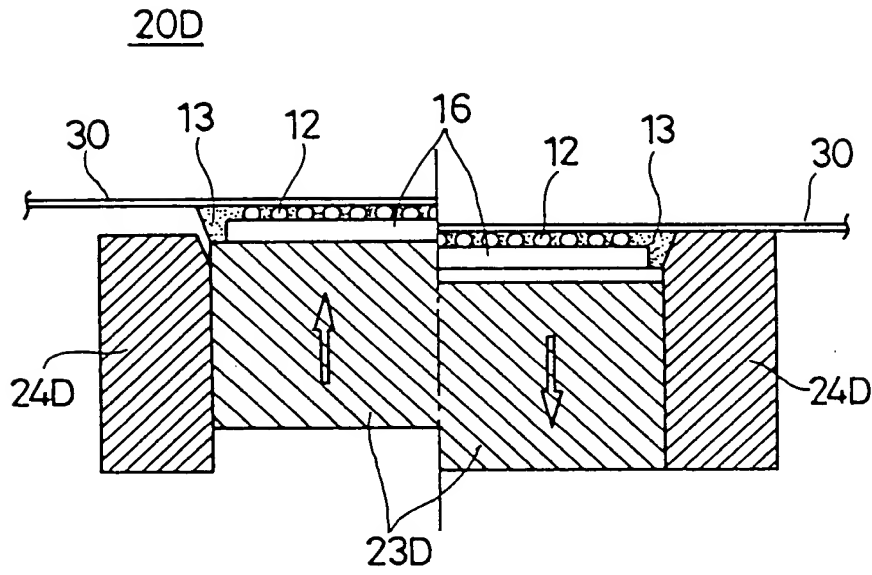


FIG. 24

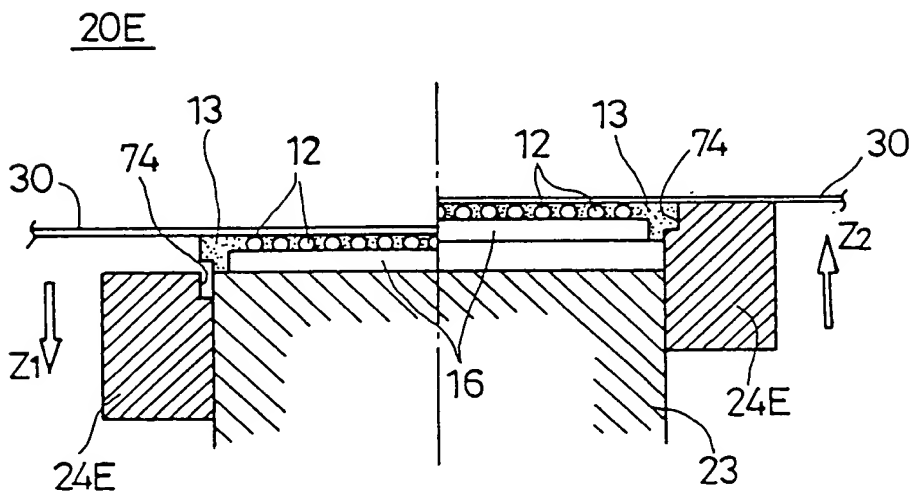


FIG. 25

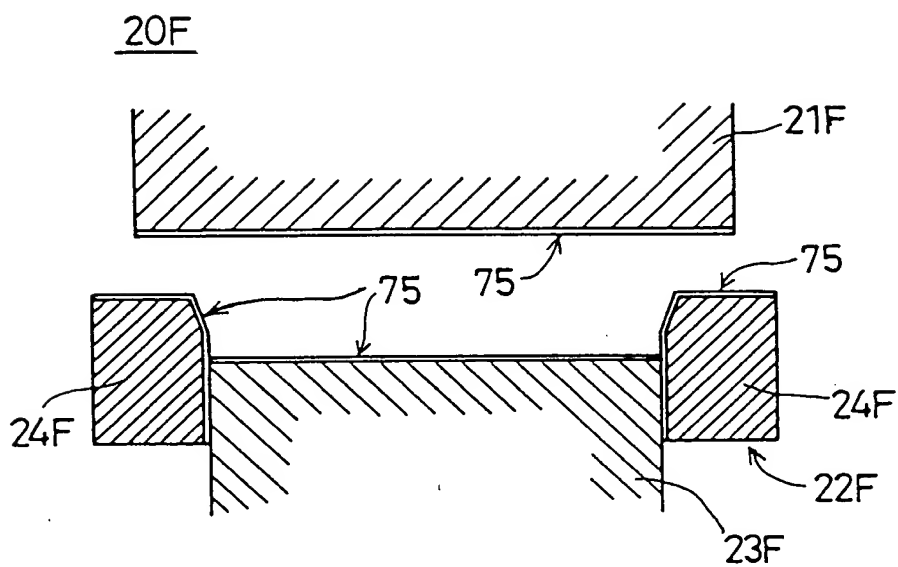


FIG. 26

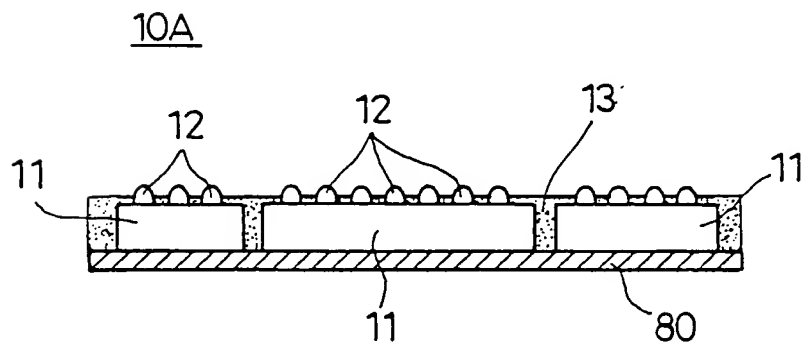


Figure 10B is a cross-sectional view of a multi-layered substrate 10B. It shows a central layer 11 with a textured surface 12. This central layer is flanked by two side layers 13. The entire assembly is mounted on a base 80. The base 80 has a top layer 81 and a bottom layer 82. The height of the top layer 81 is indicated as H1, the height of the bottom layer 82 as H2, and the total height of the base 80 as H3.

FIG. 28

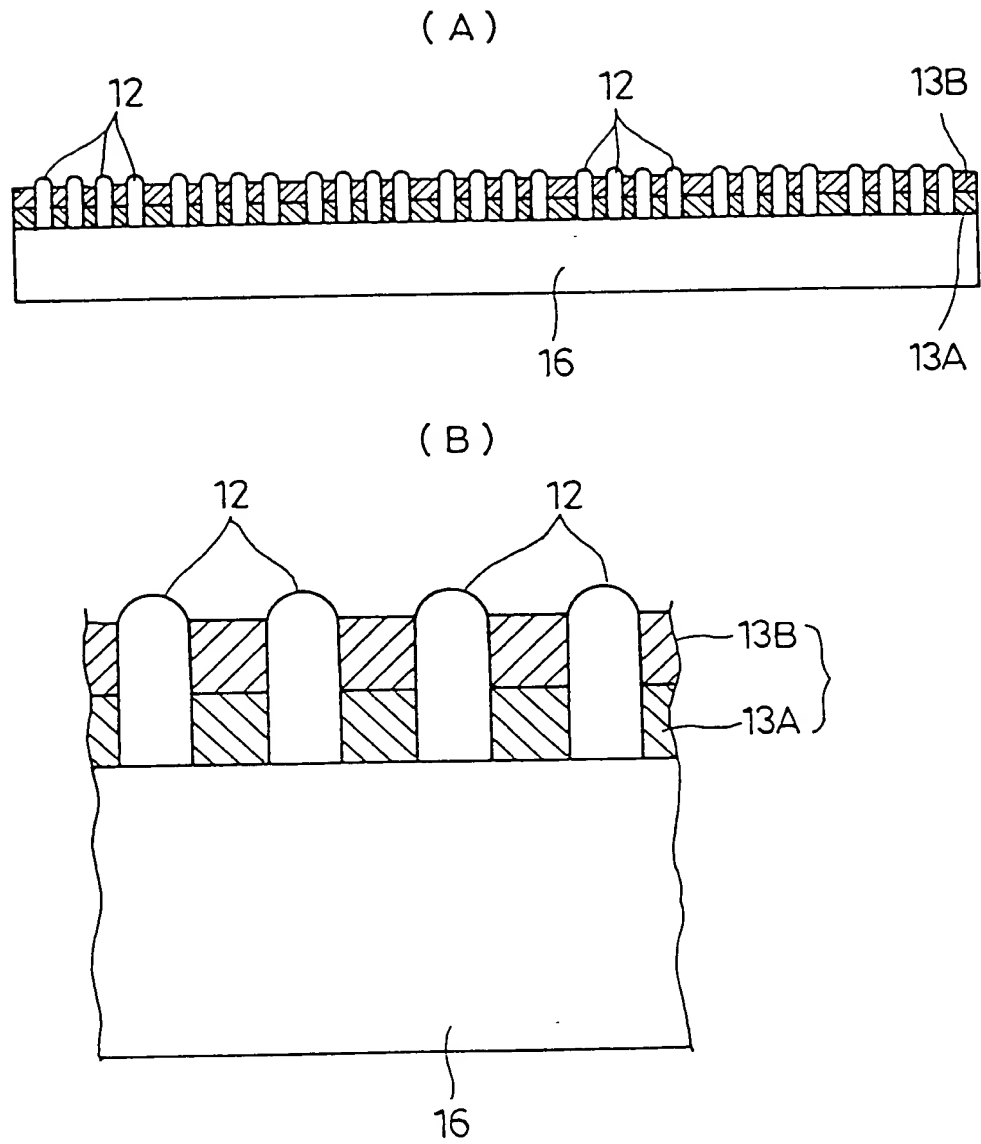


FIG. 29

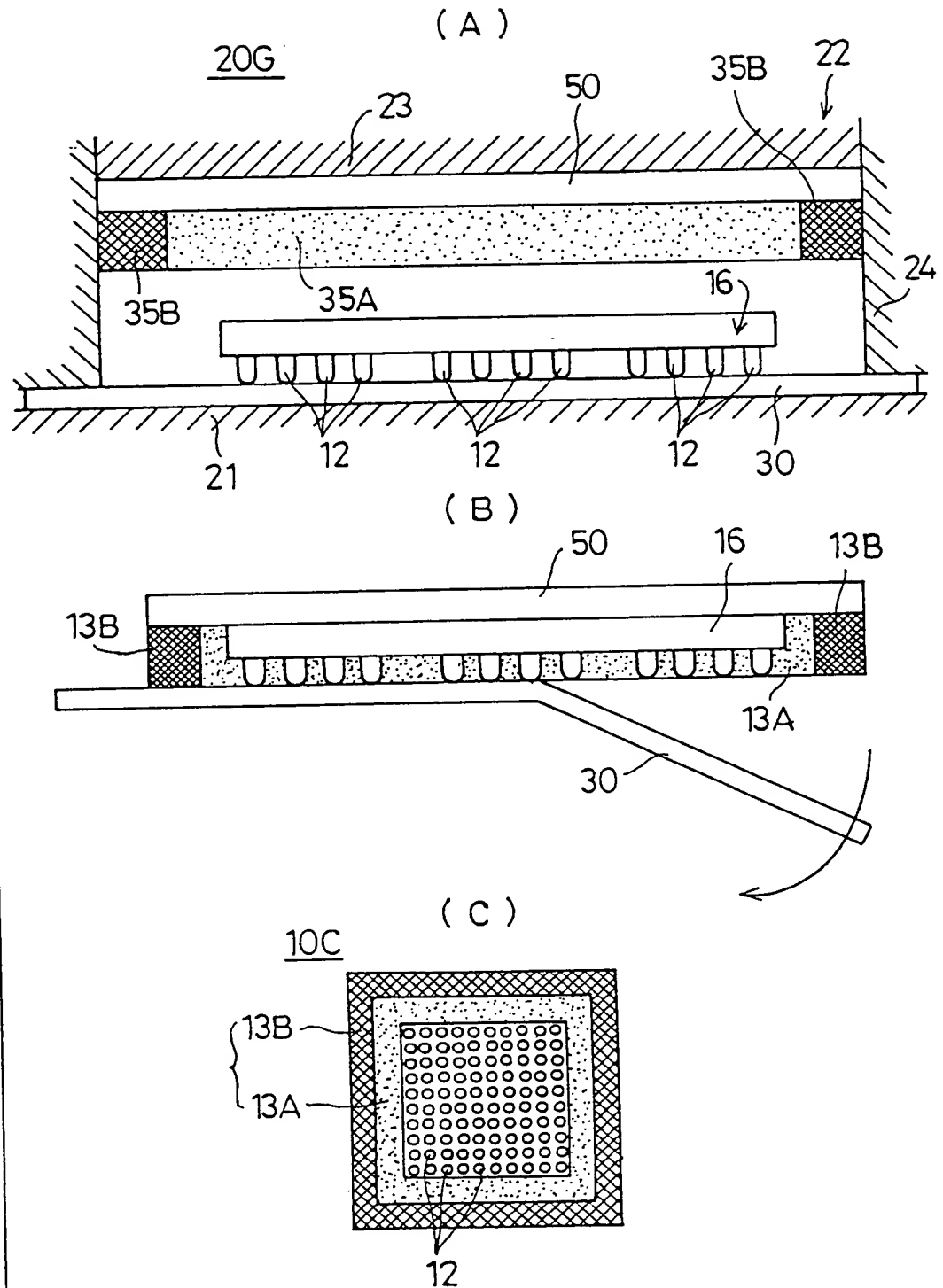


FIG. 30

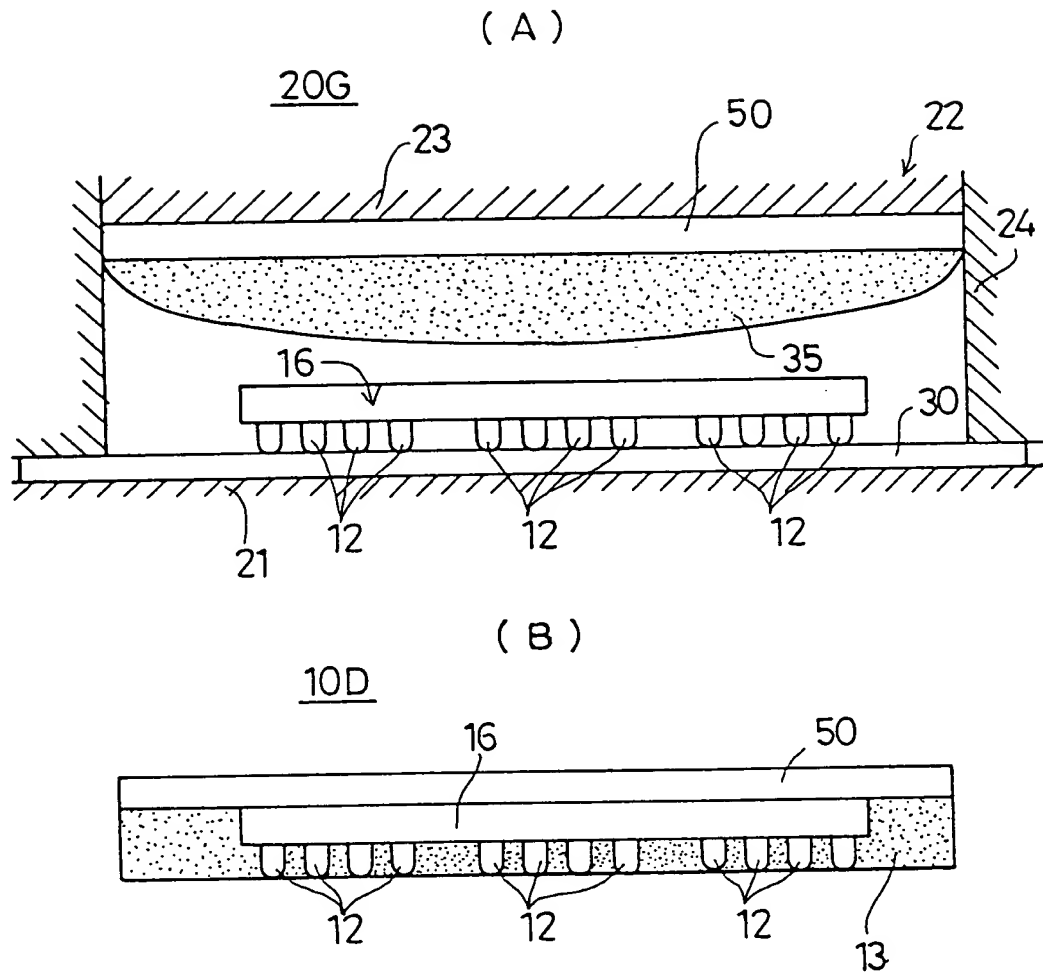


FIG. 31

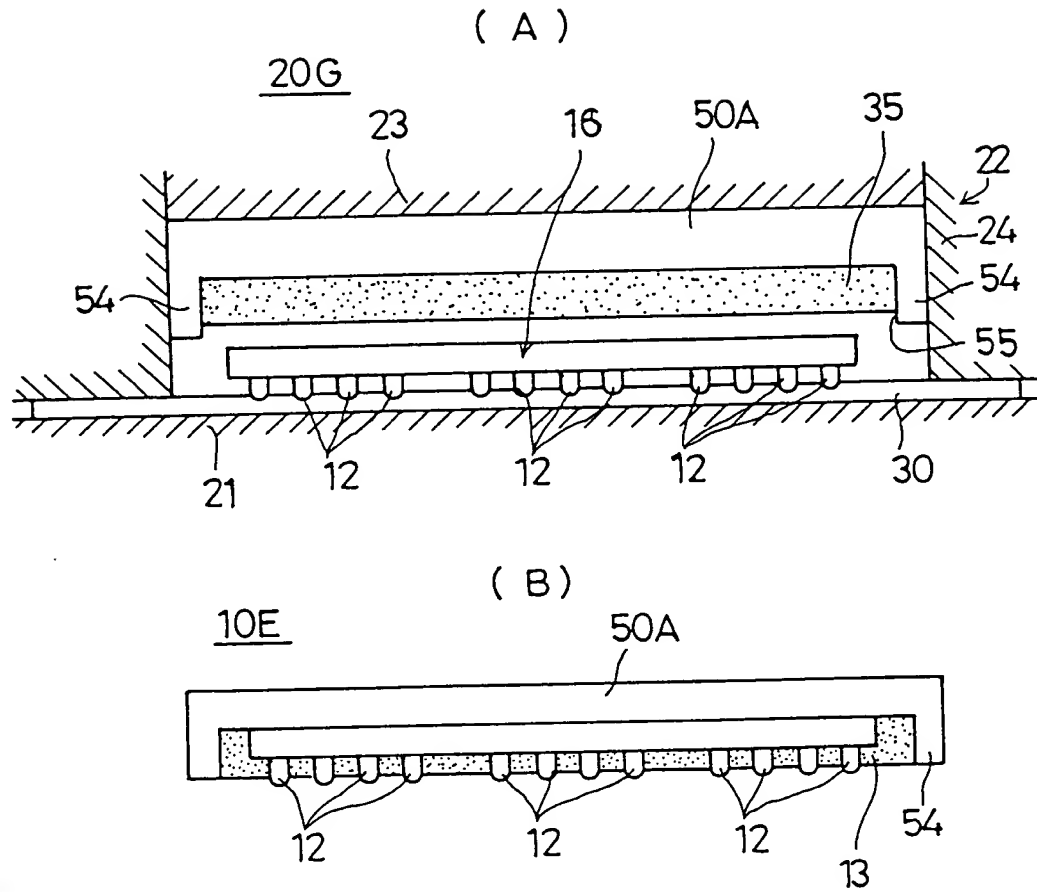


FIG. 32

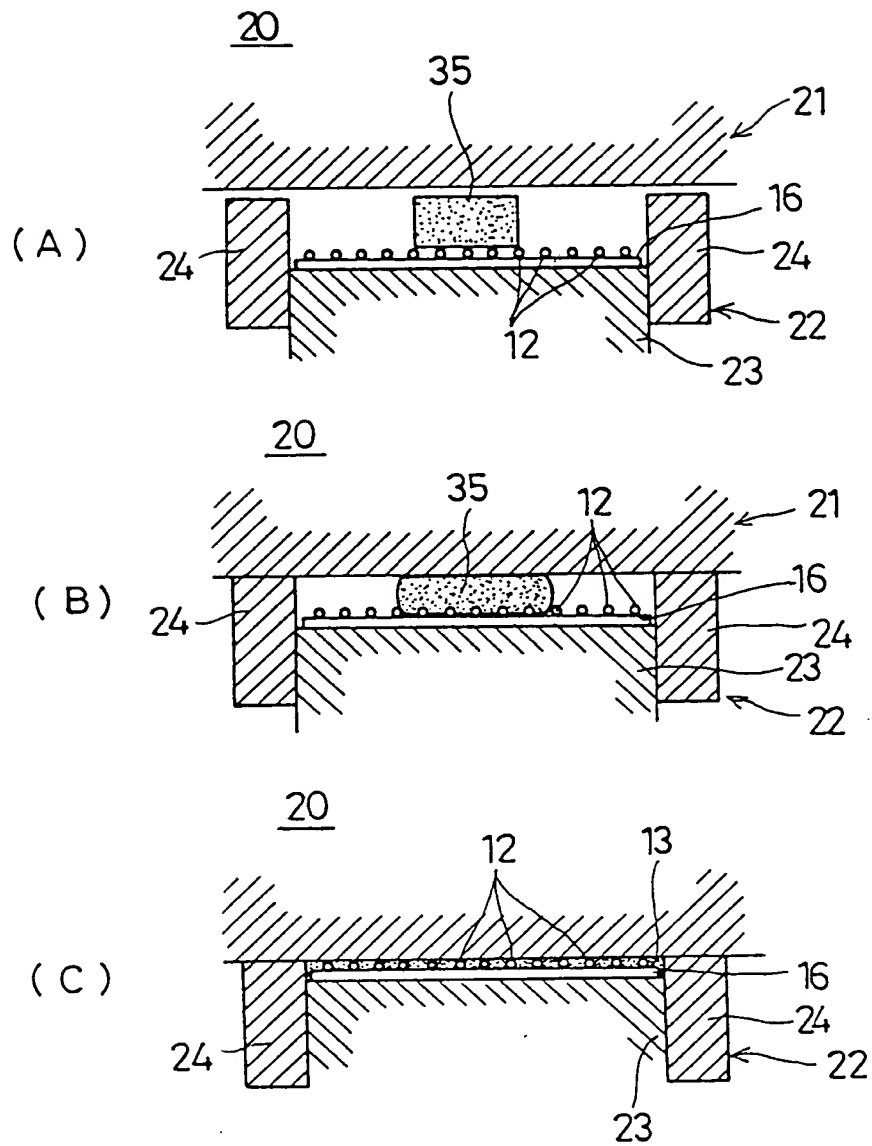


FIG. 33

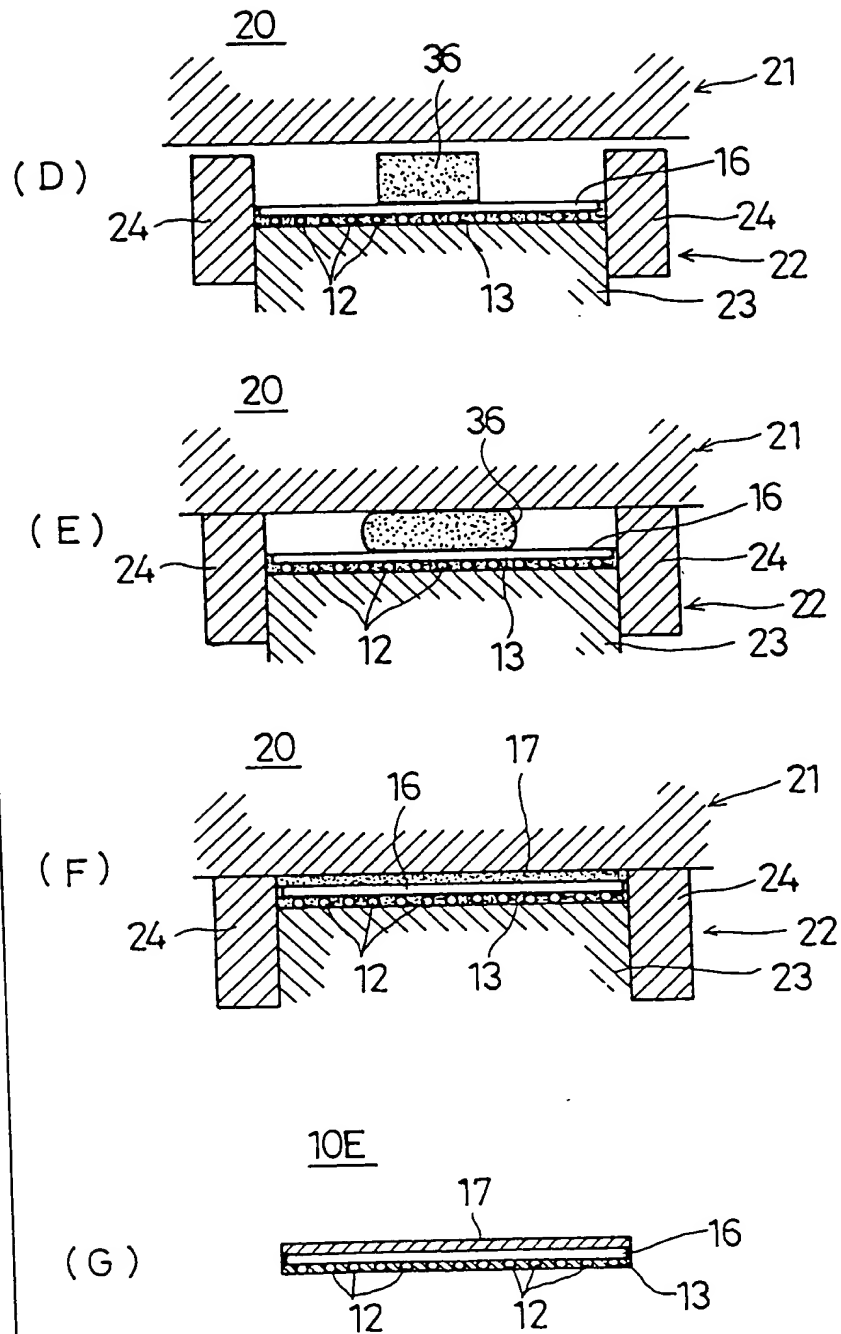


FIG. 34

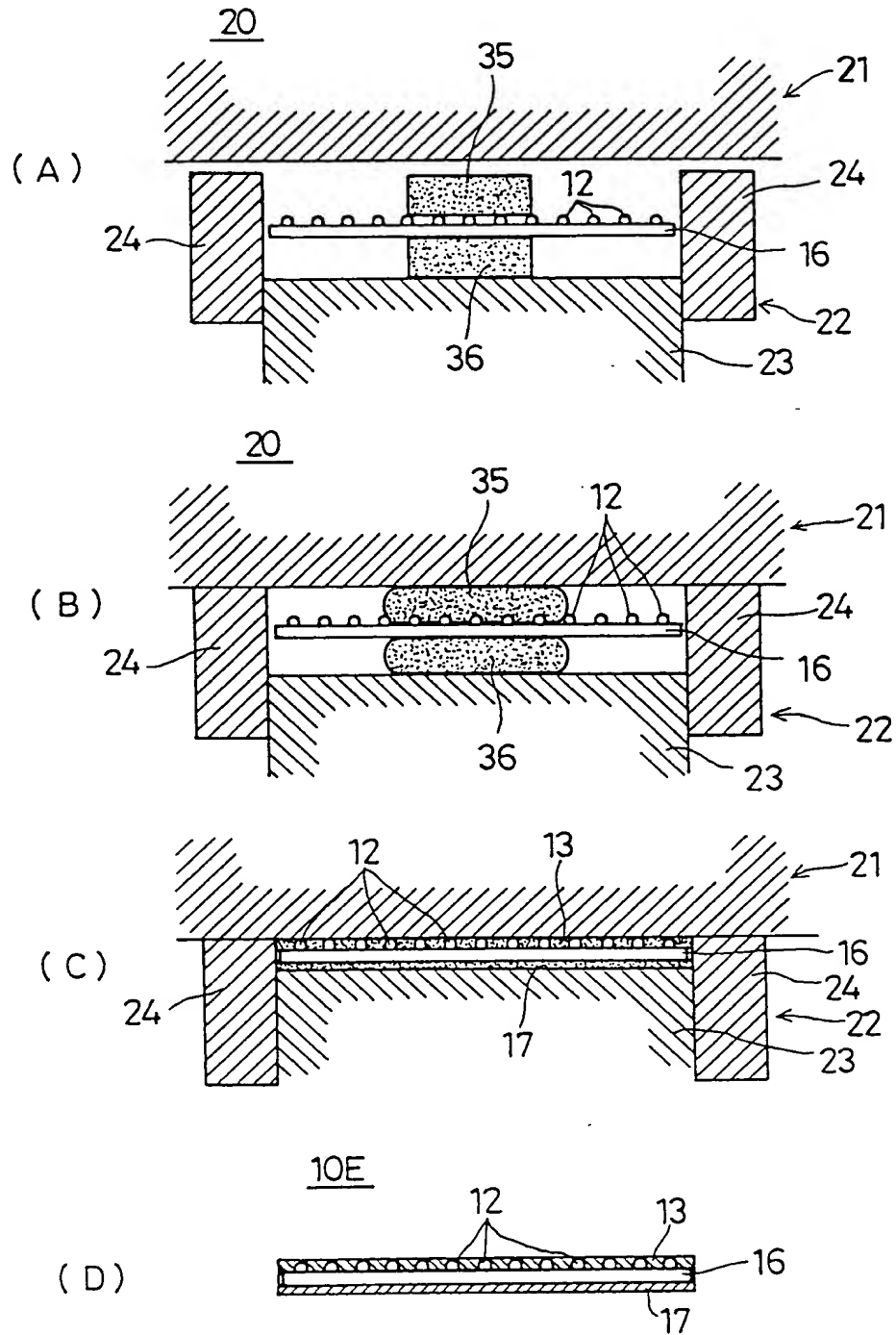


FIG. 35

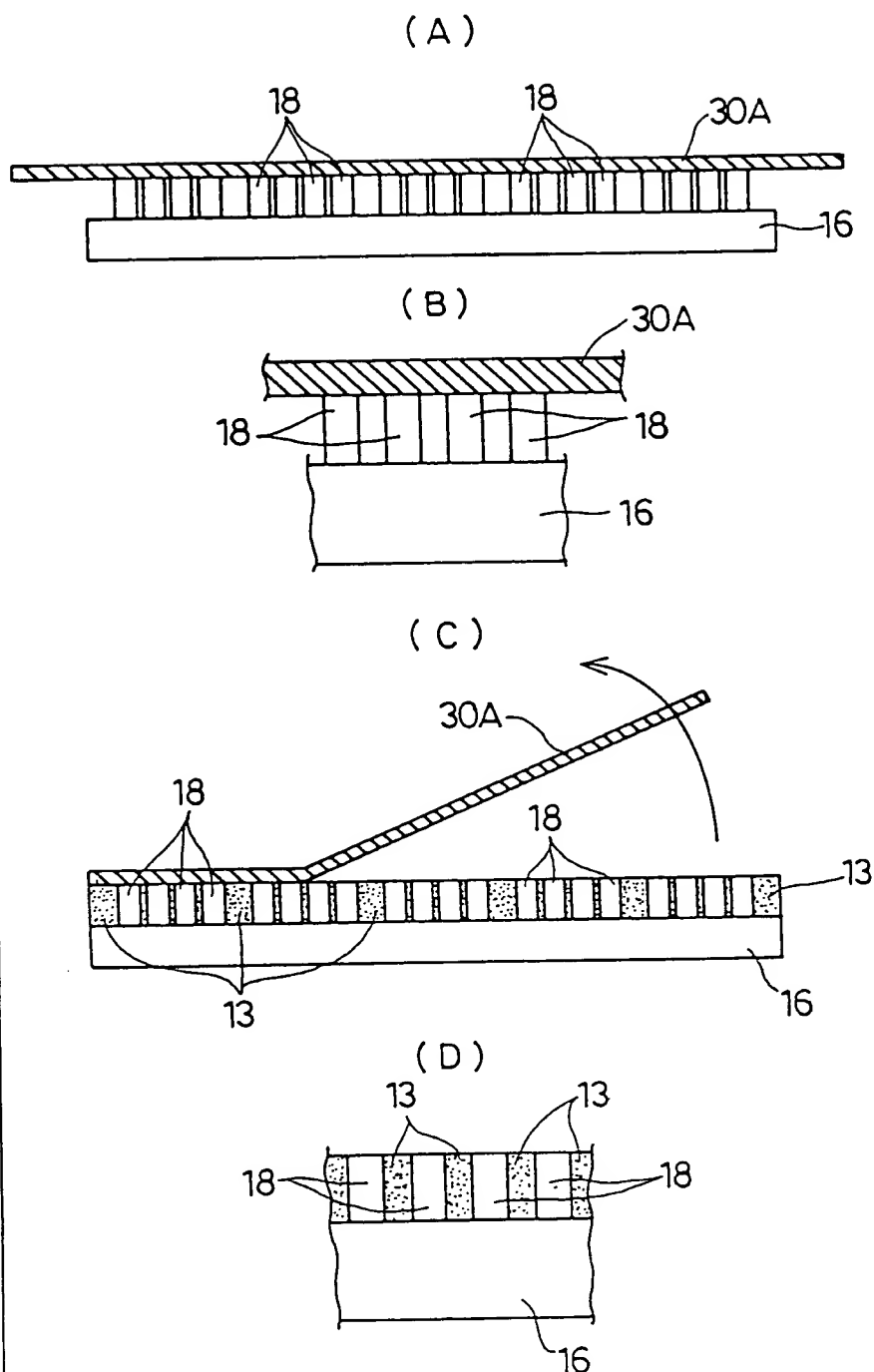


FIG. 36

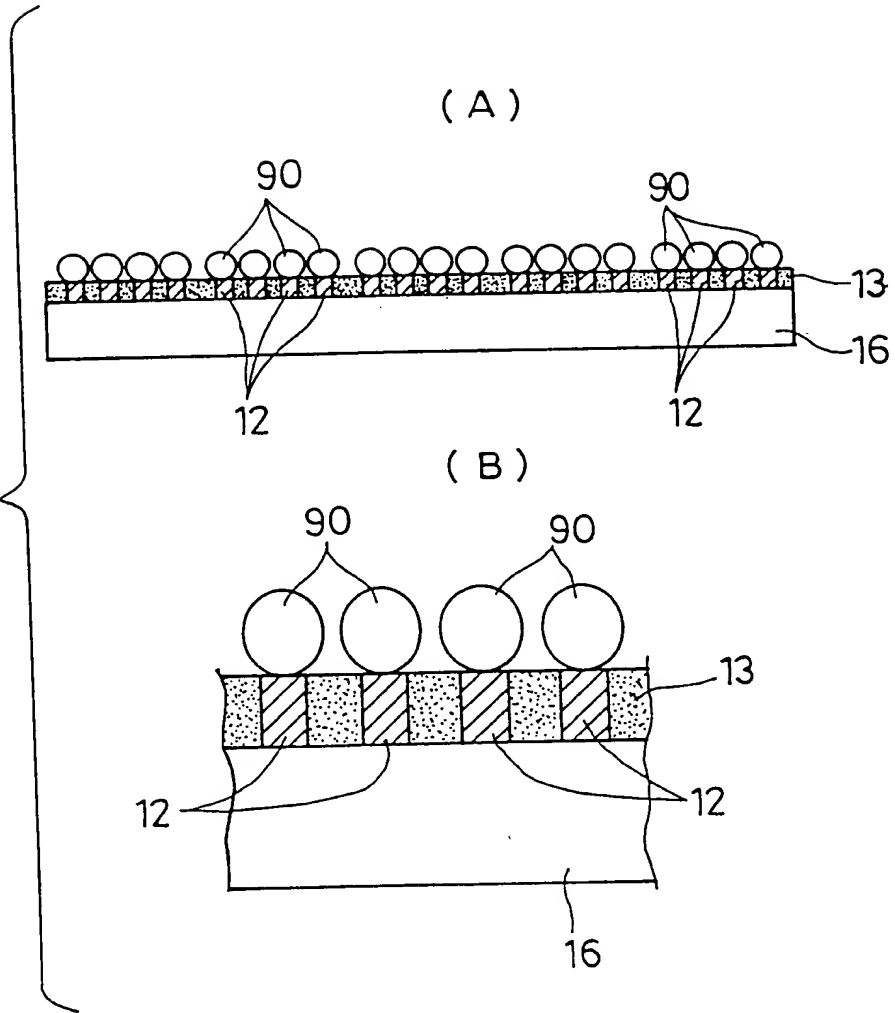


FIG. 37

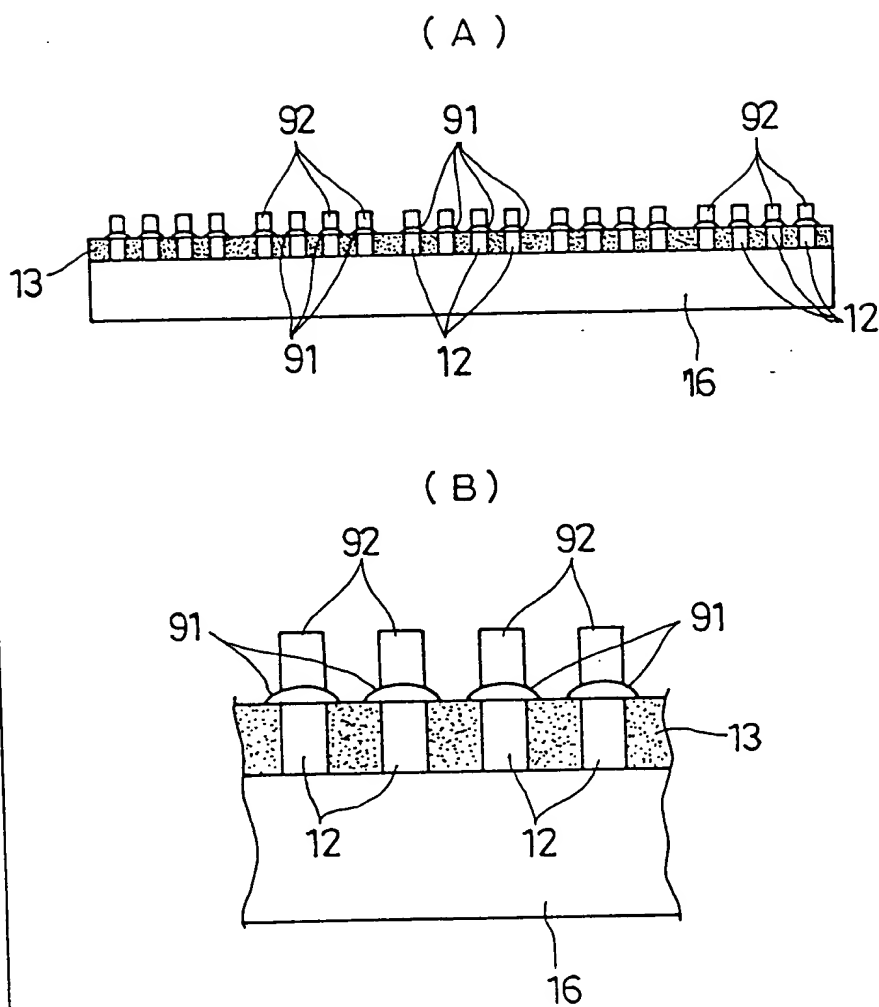


FIG. 38

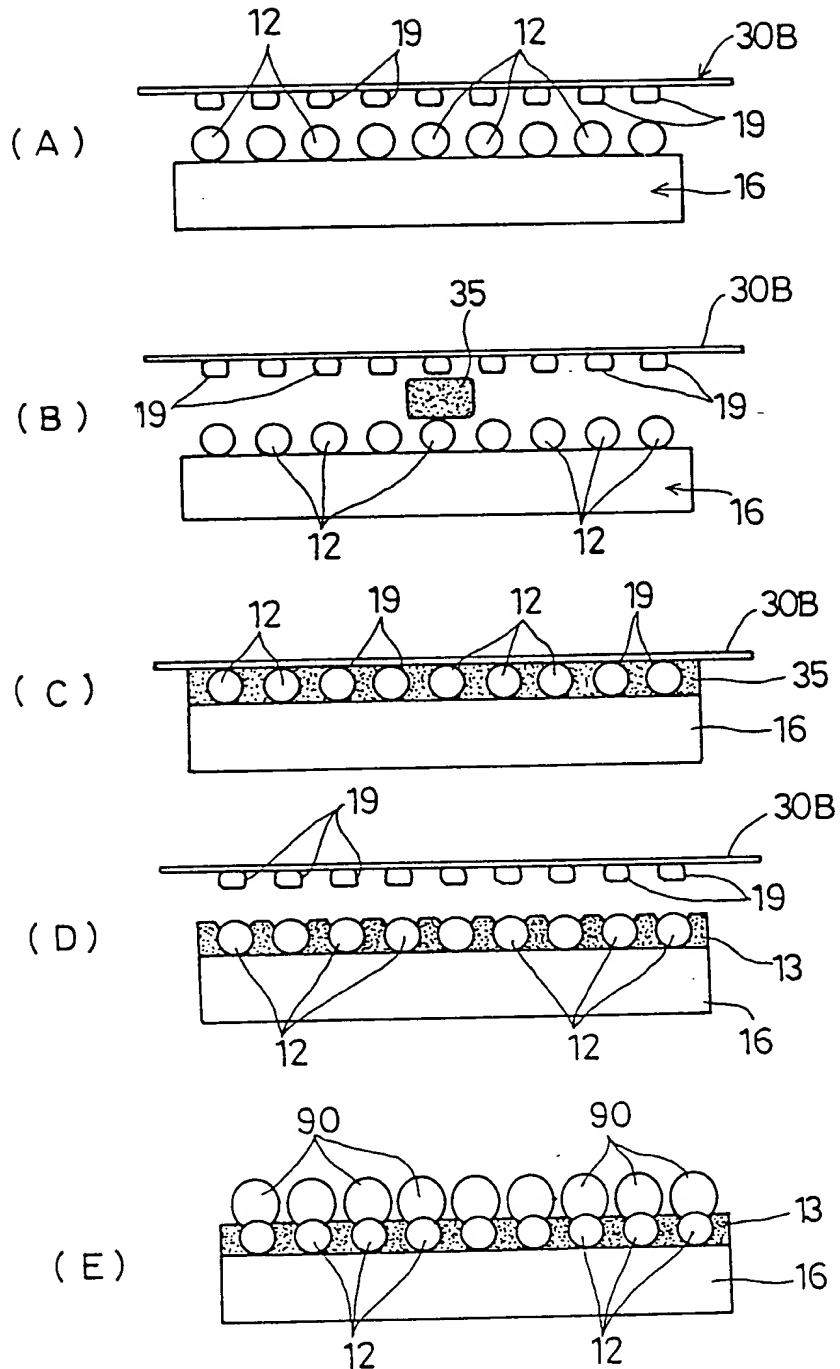


FIG. 39

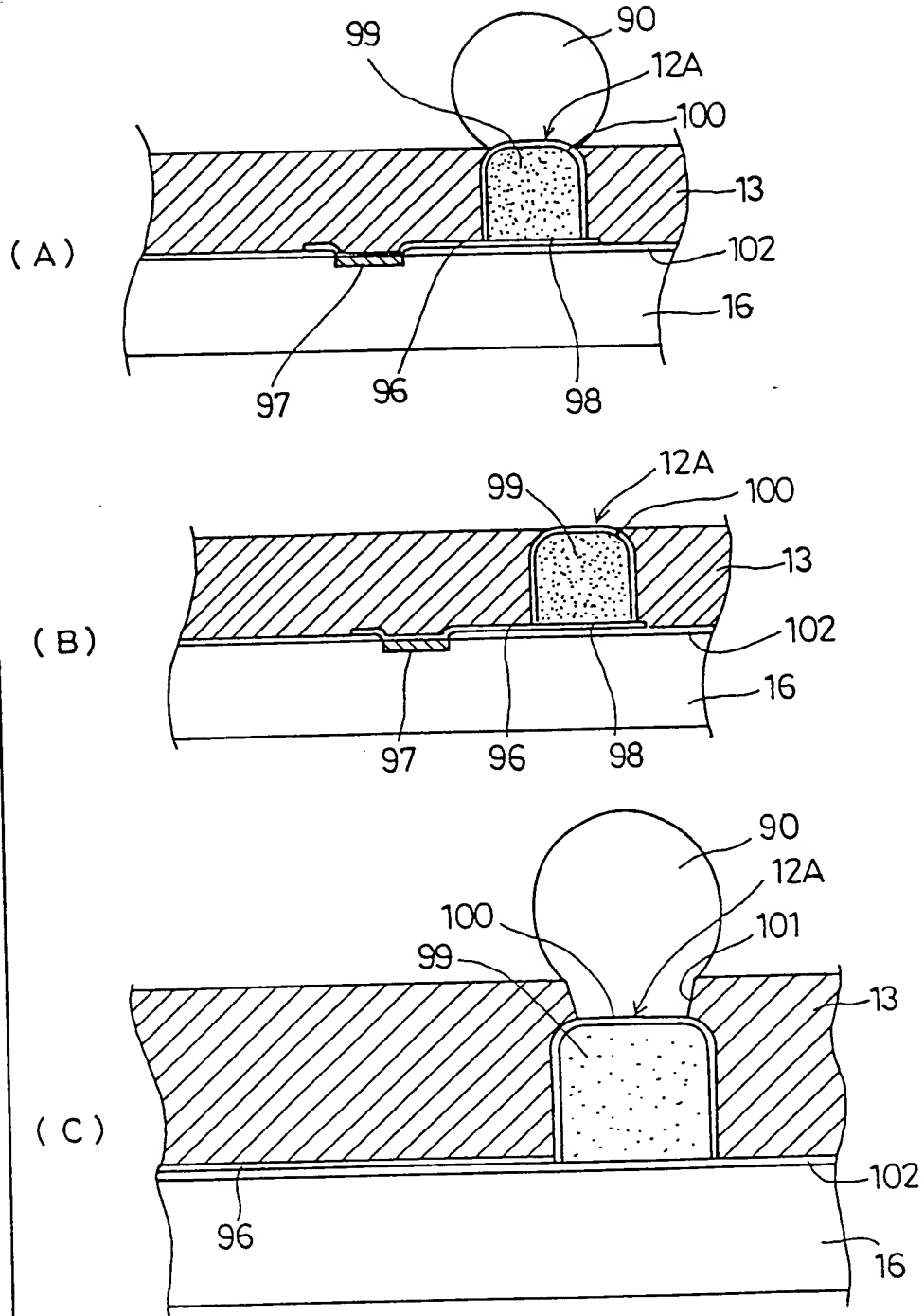


FIG. 40

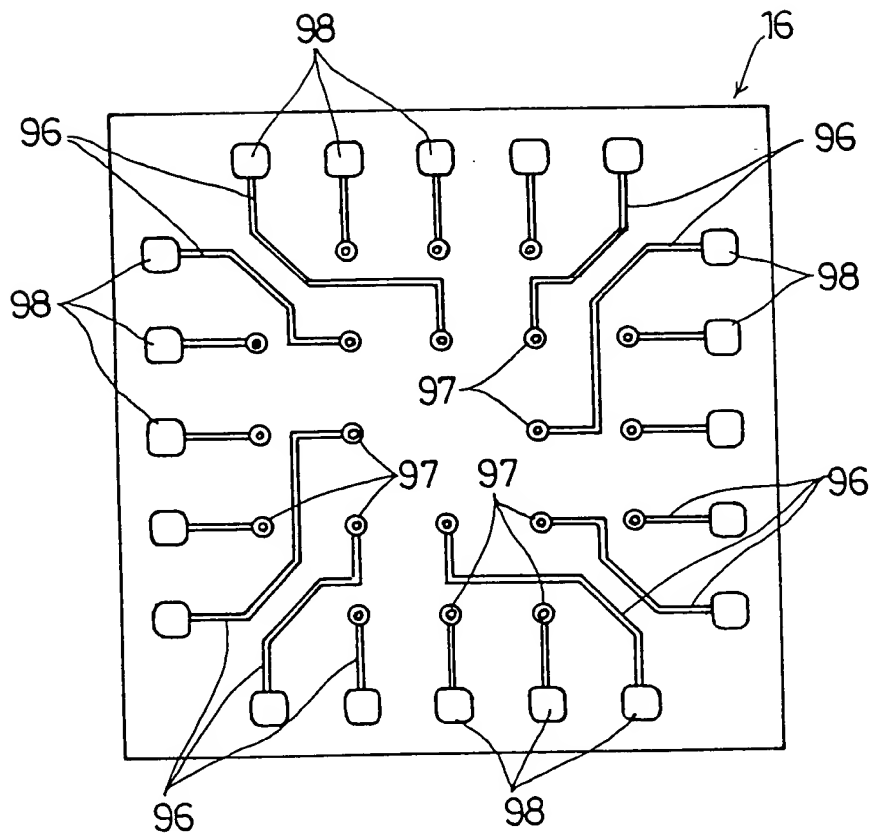


FIG. 41

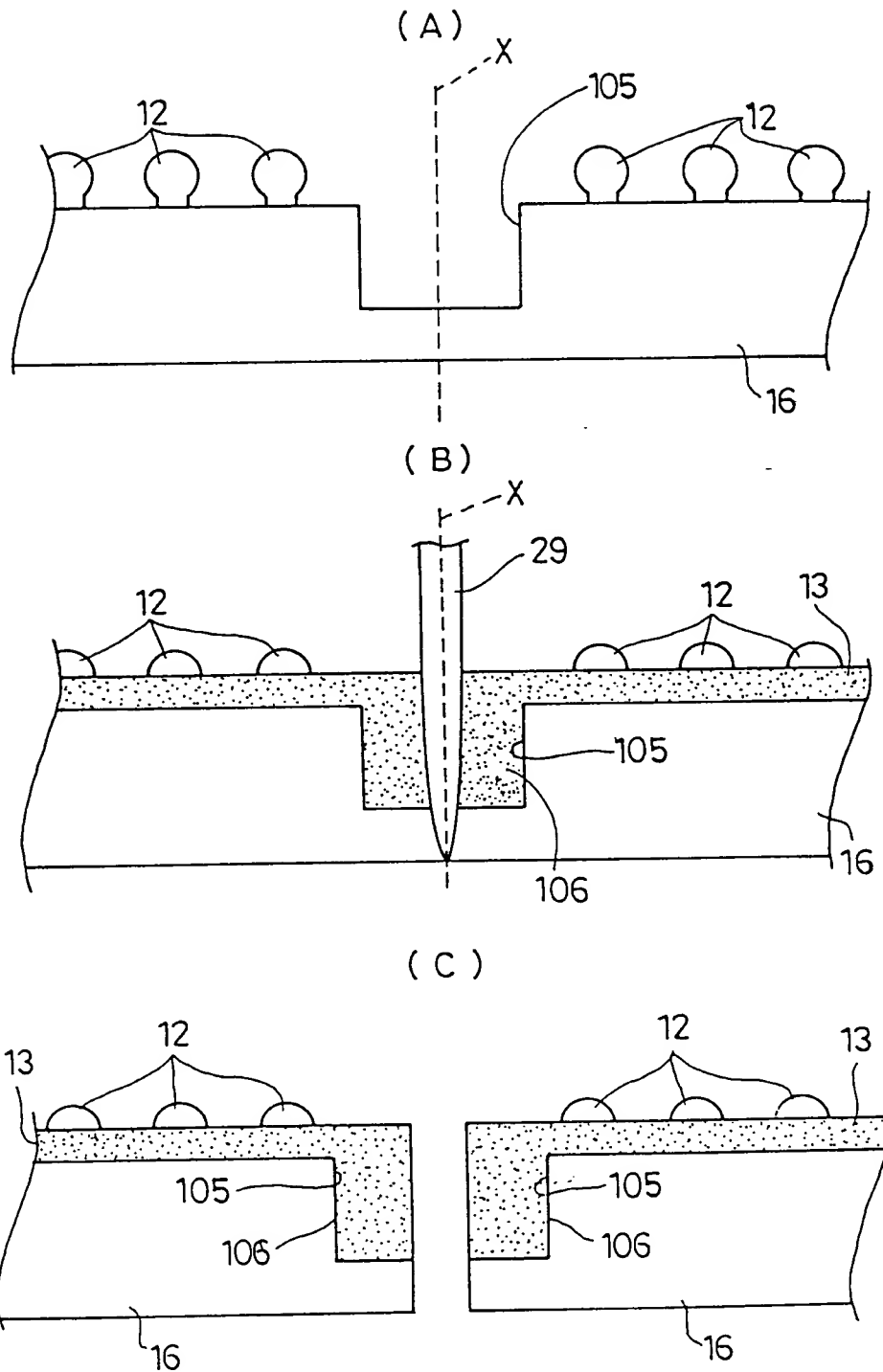


FIG. 42

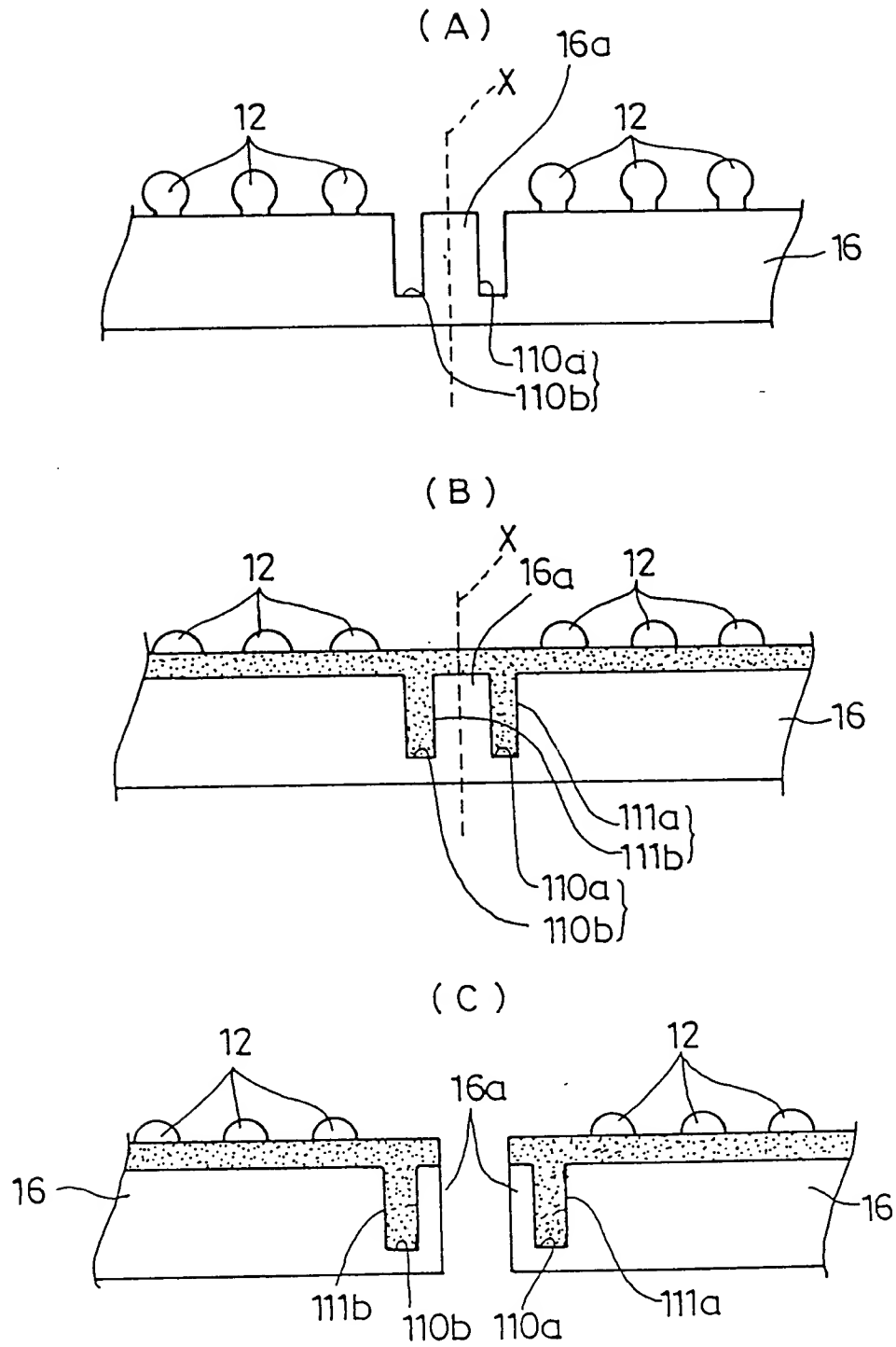


FIG. 43

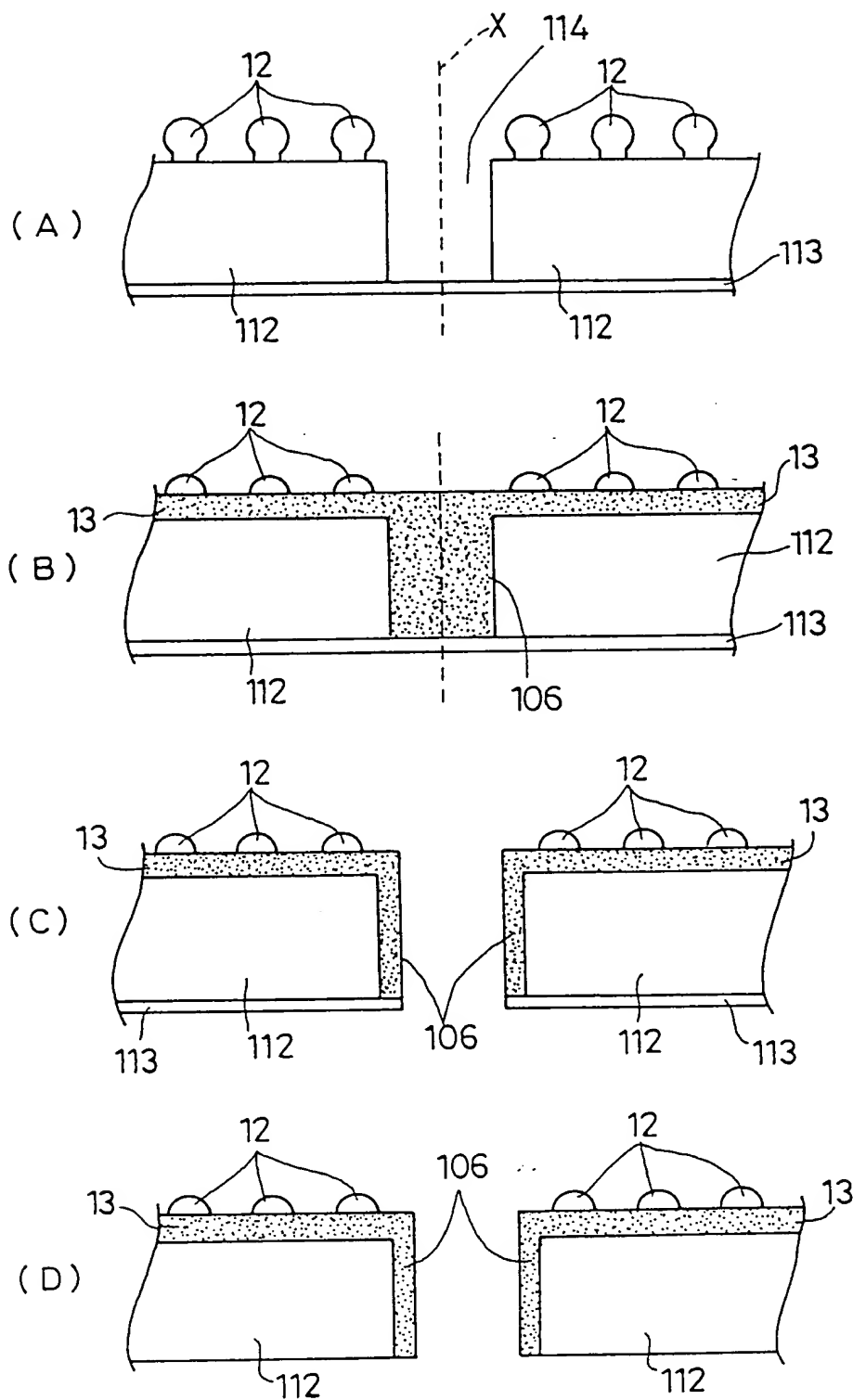


FIG. 44

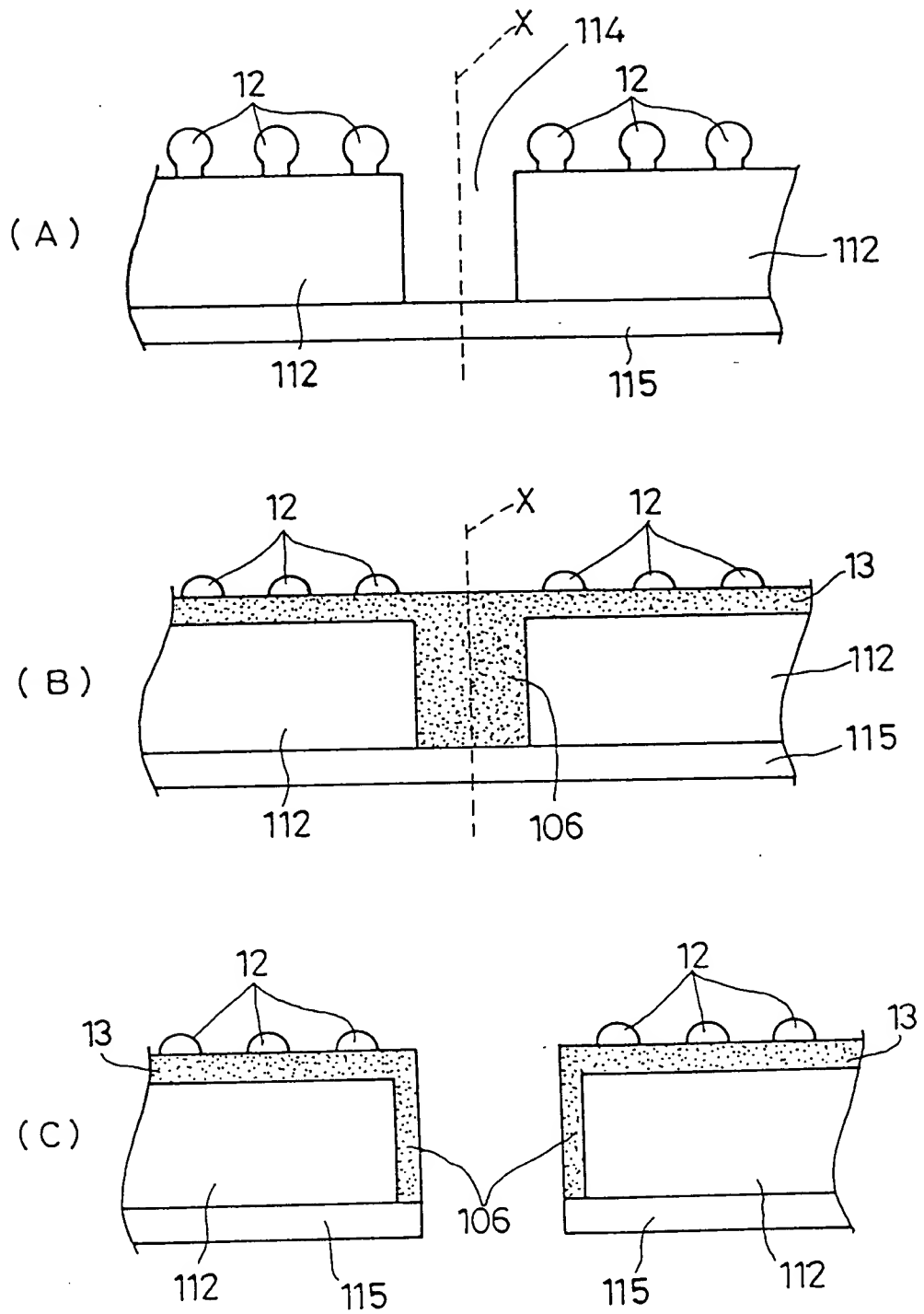


FIG. 45

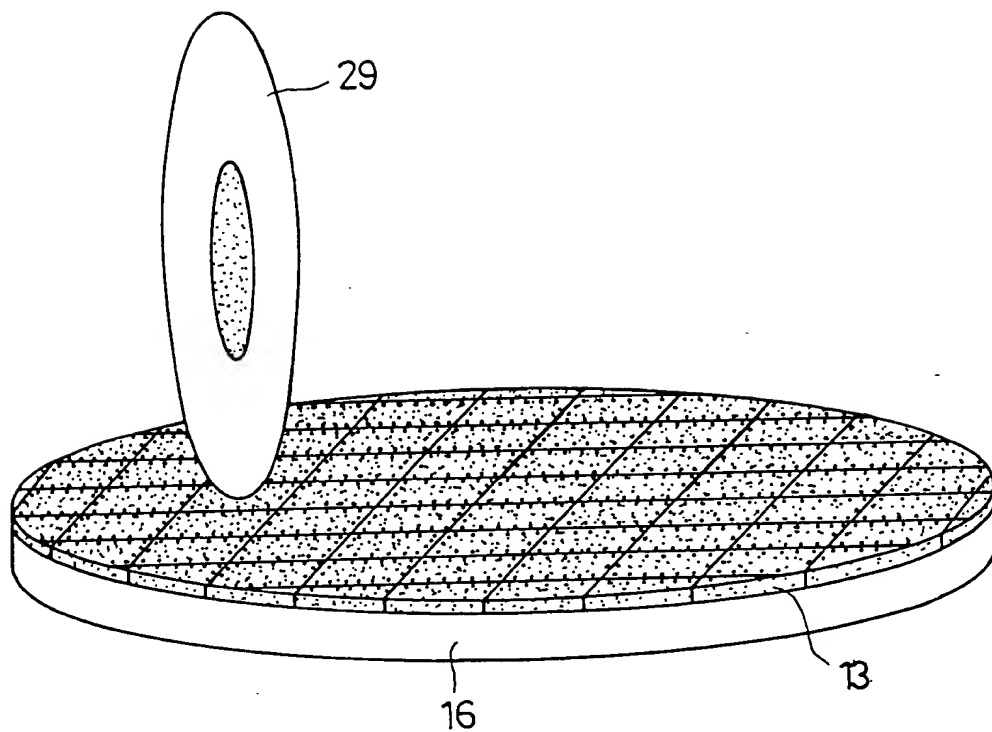


FIG. 46

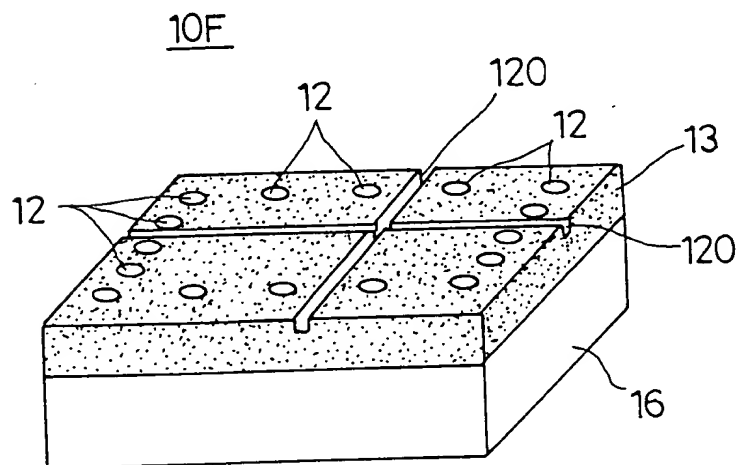


FIG. 47

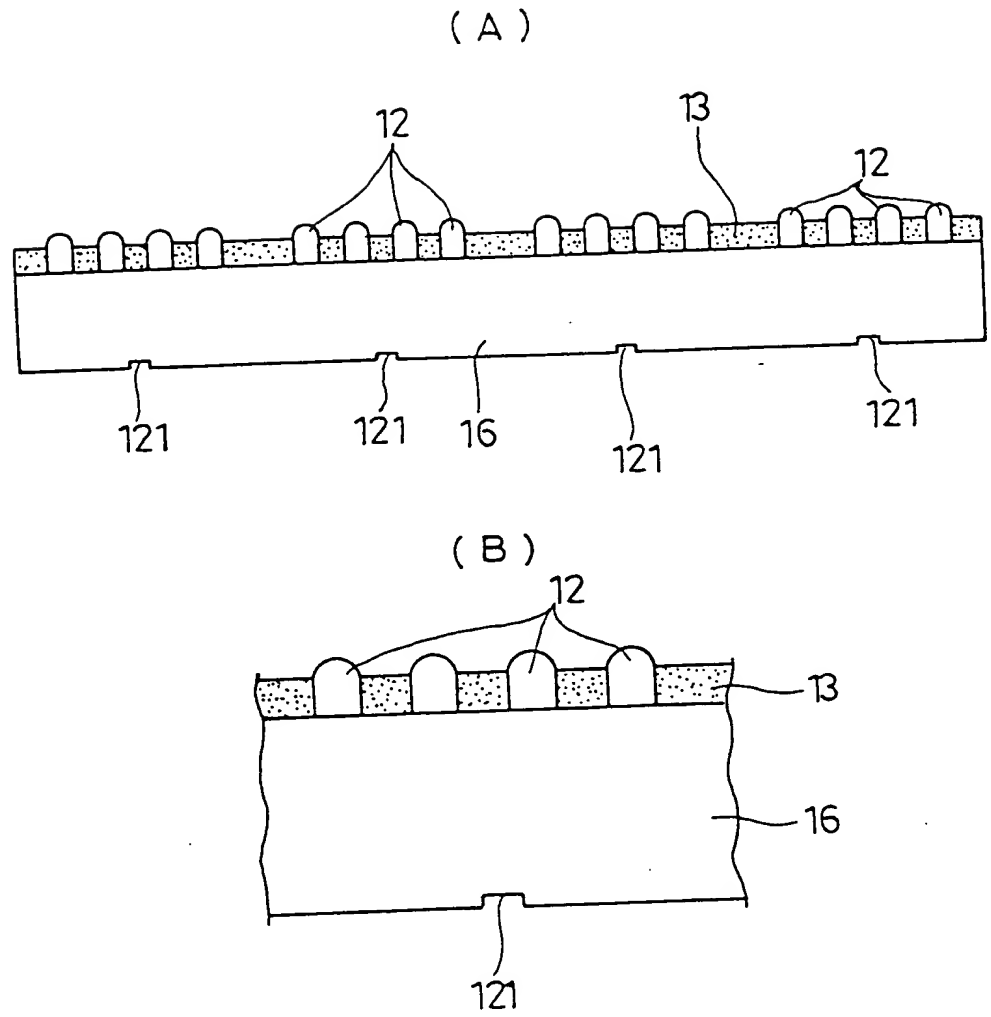


FIG. 48

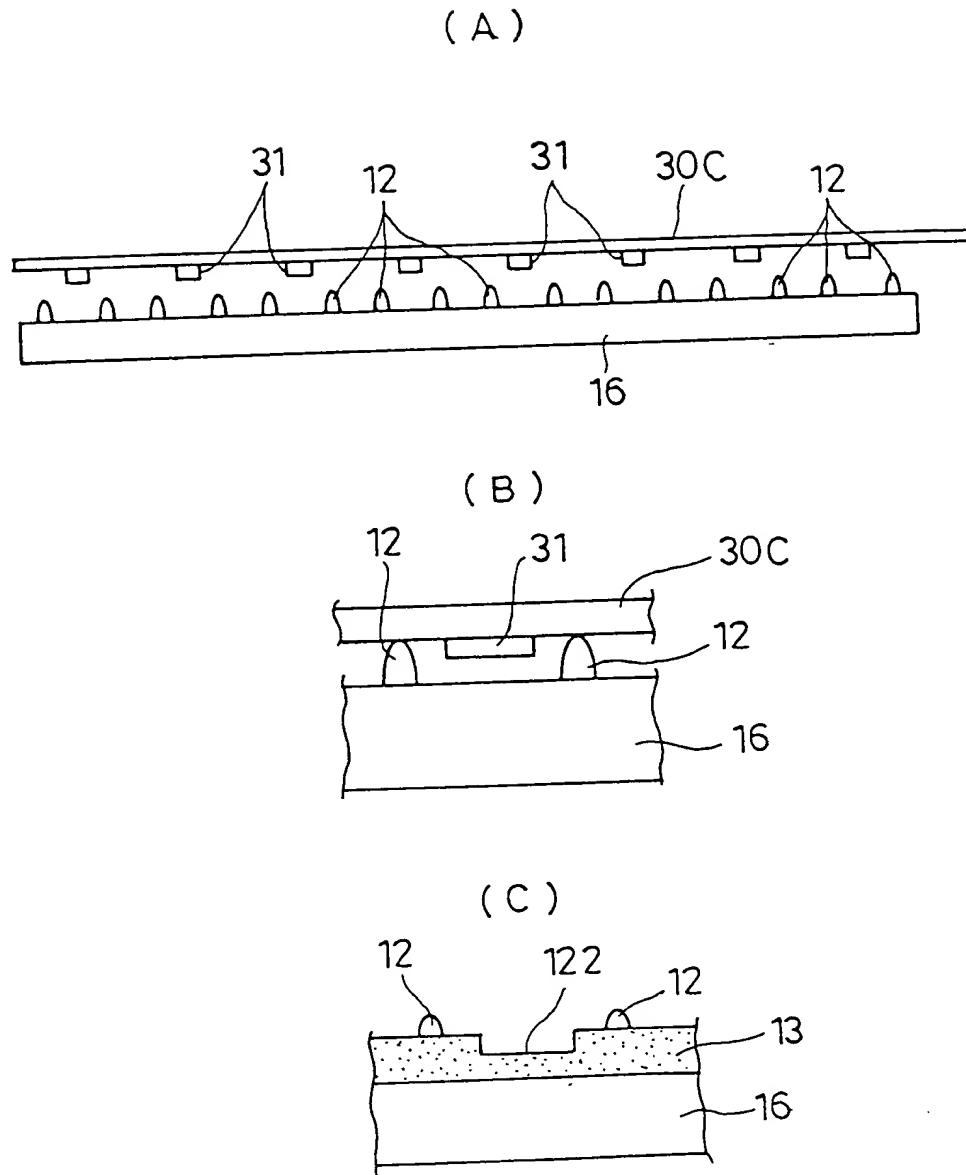


FIG. 49

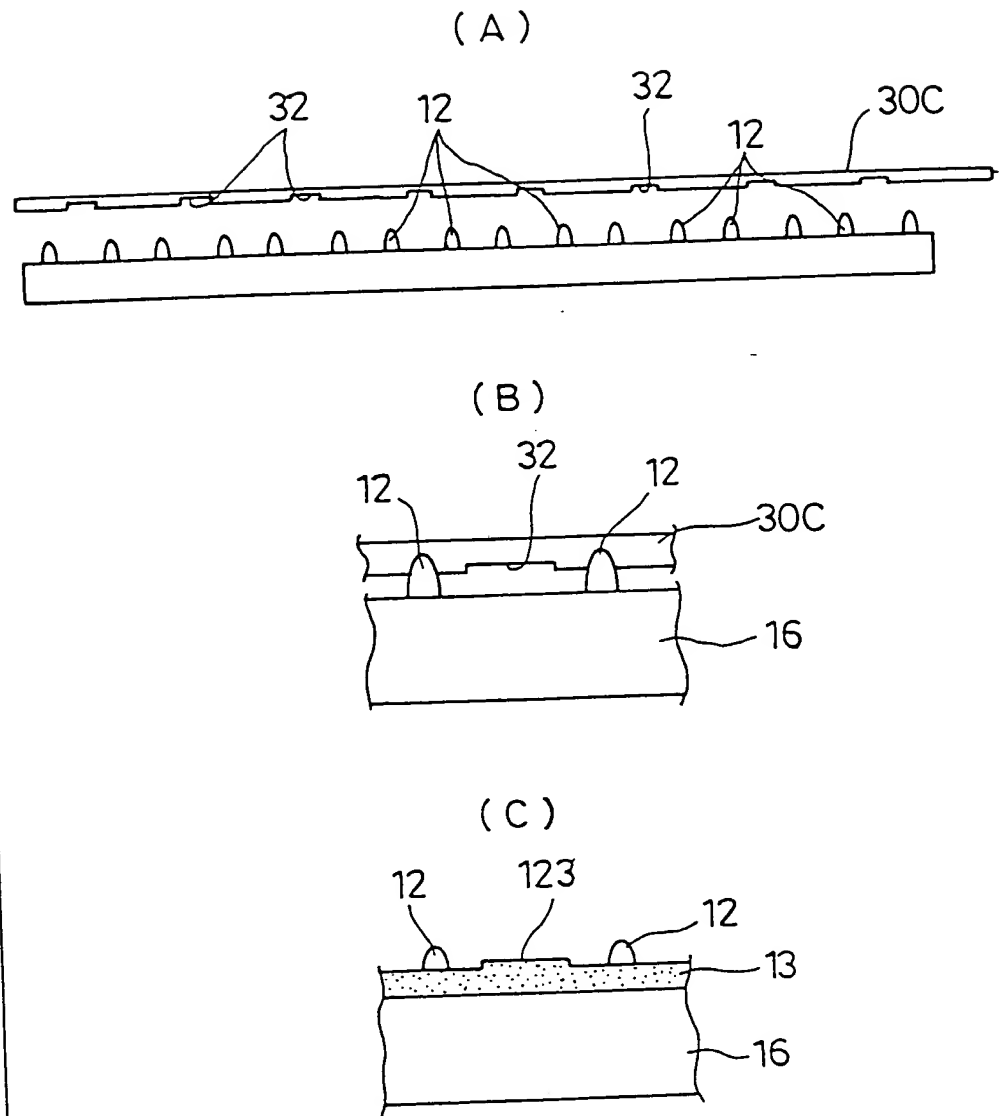
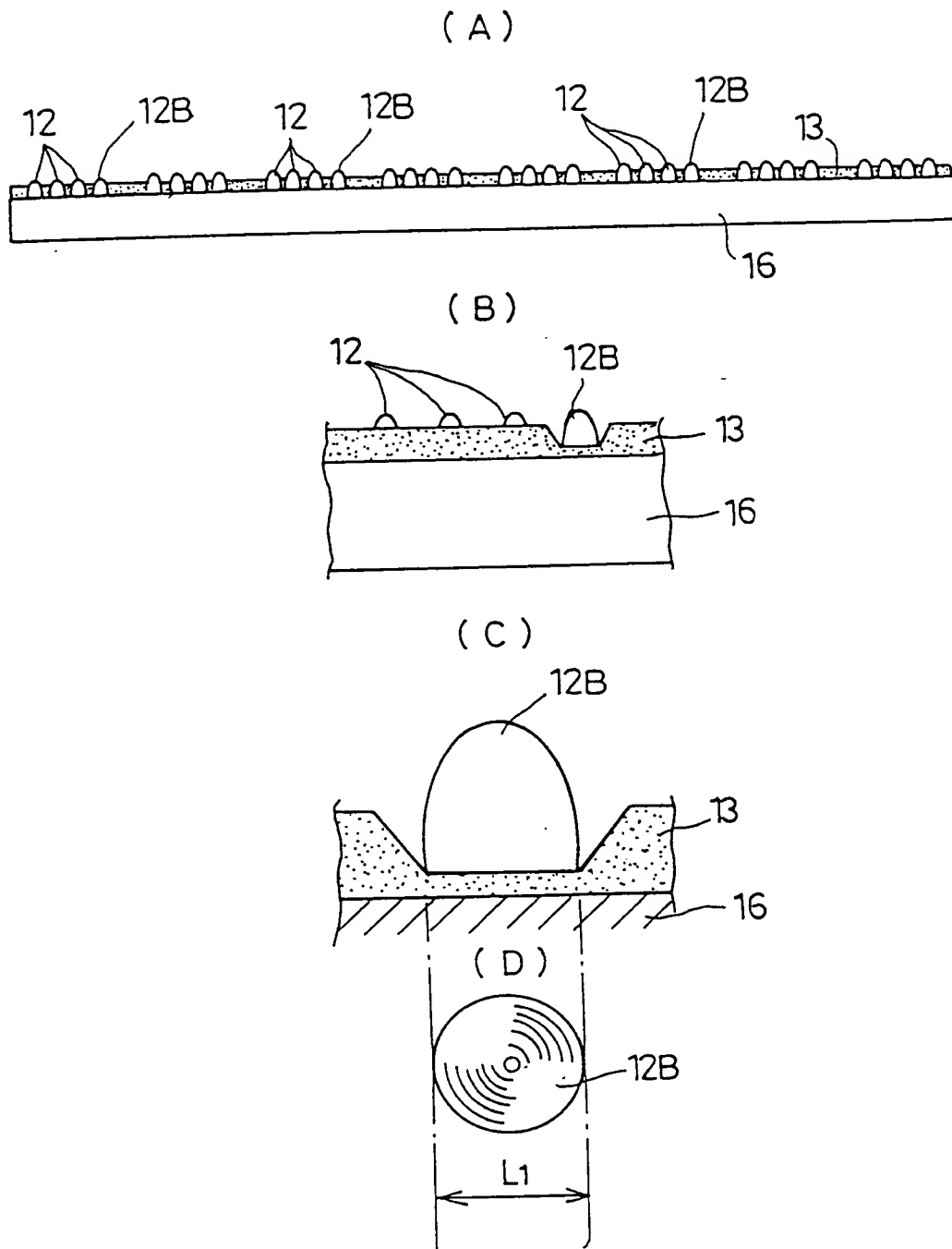


FIG. 50



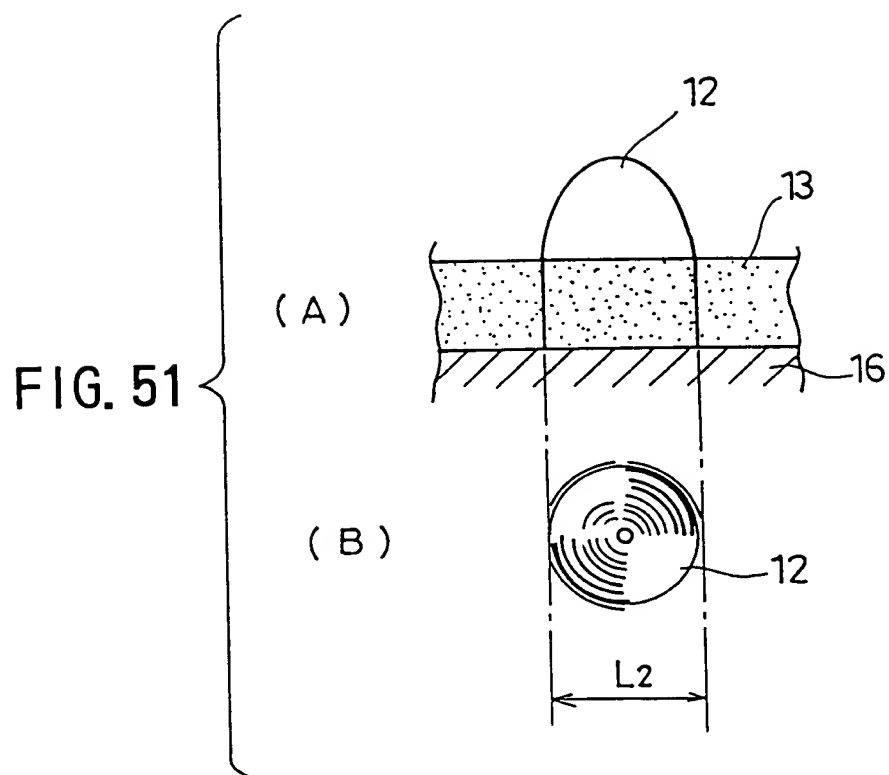


FIG. 52

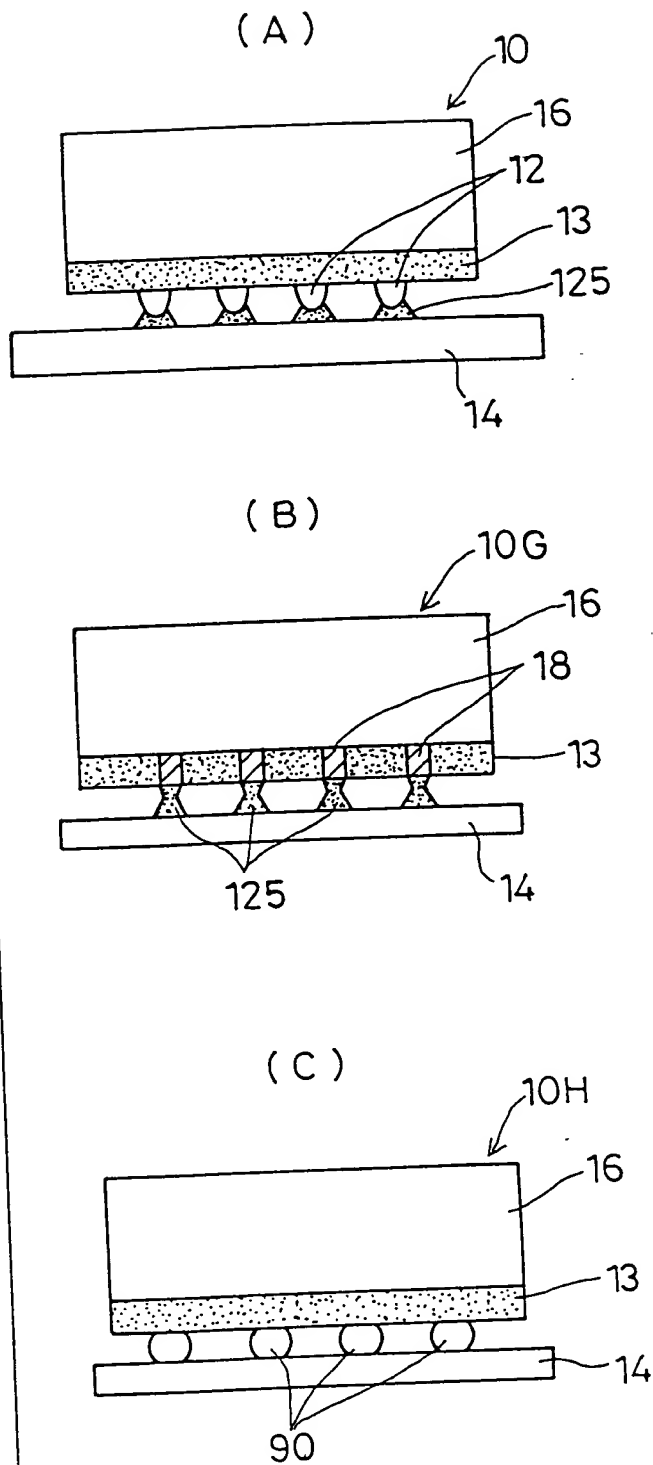


FIG. 53

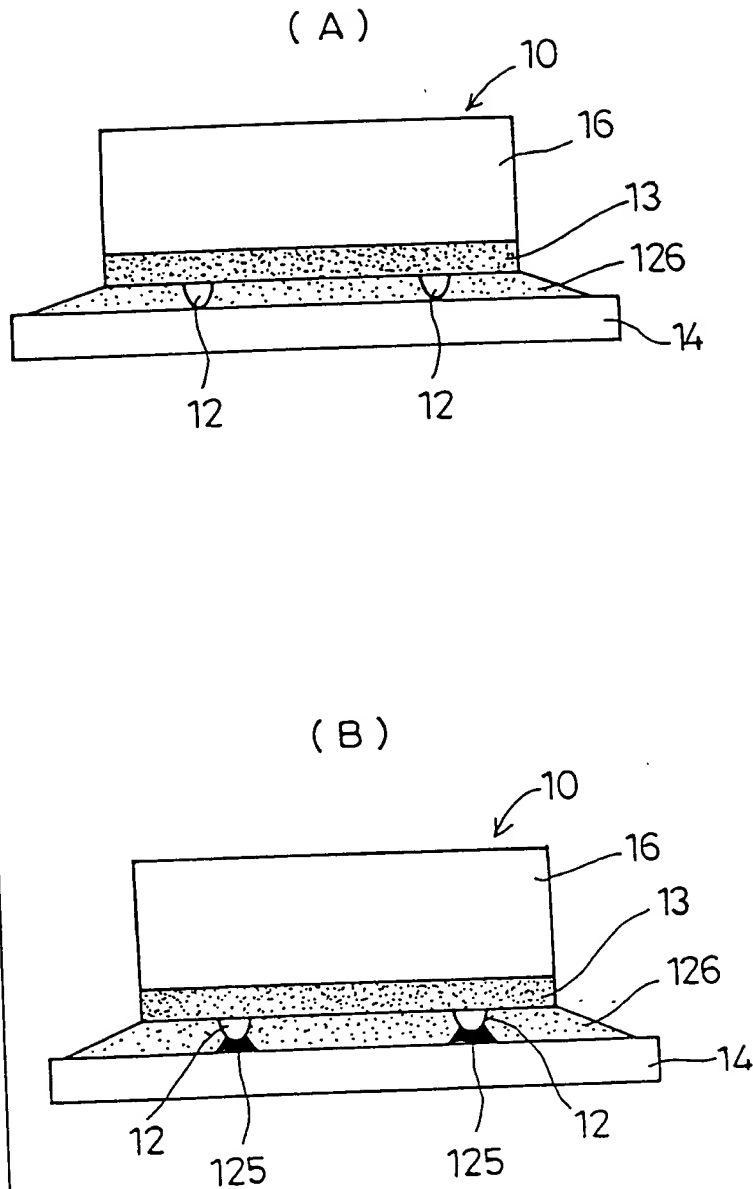


FIG. 54

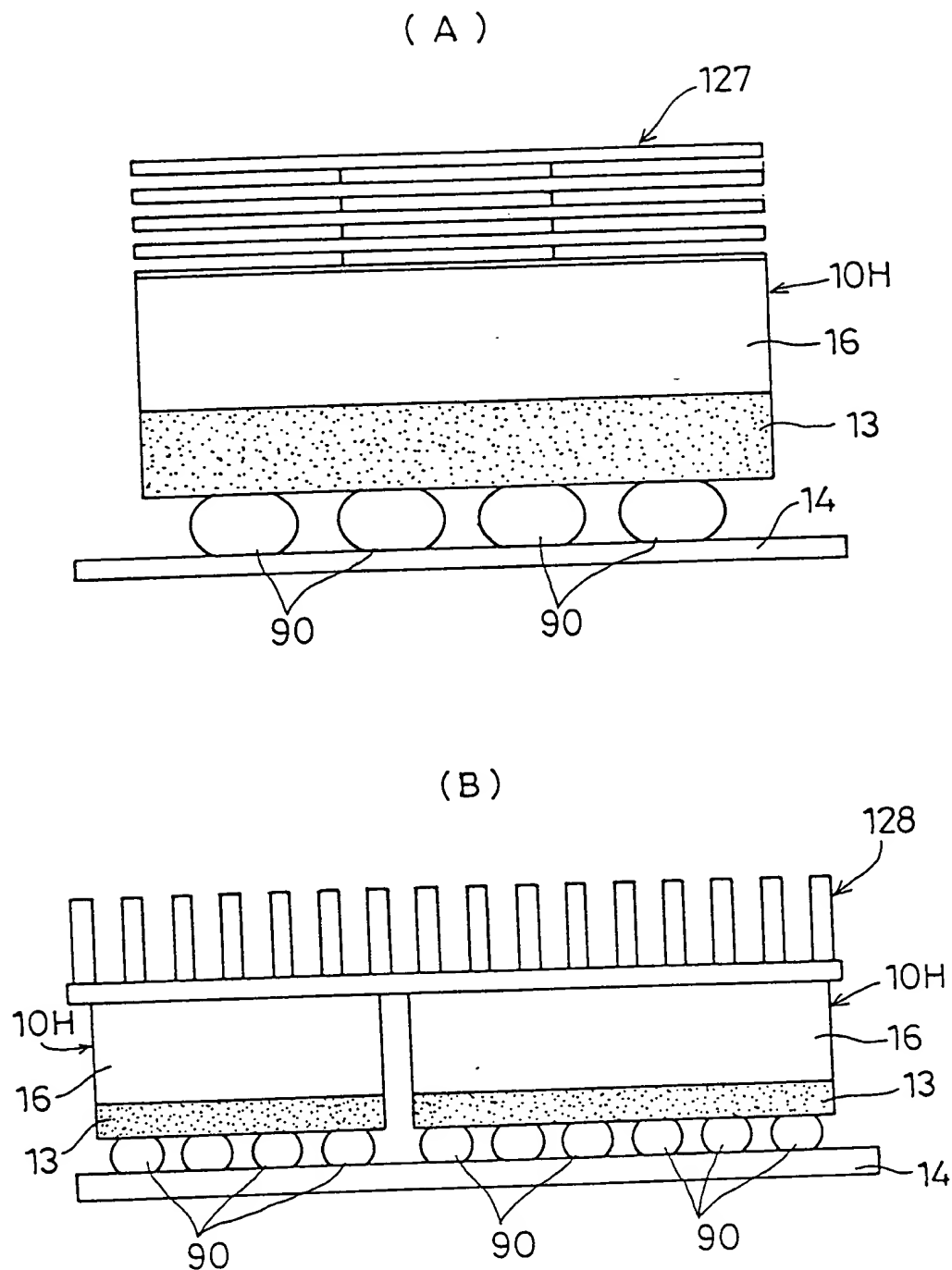


FIG. 55

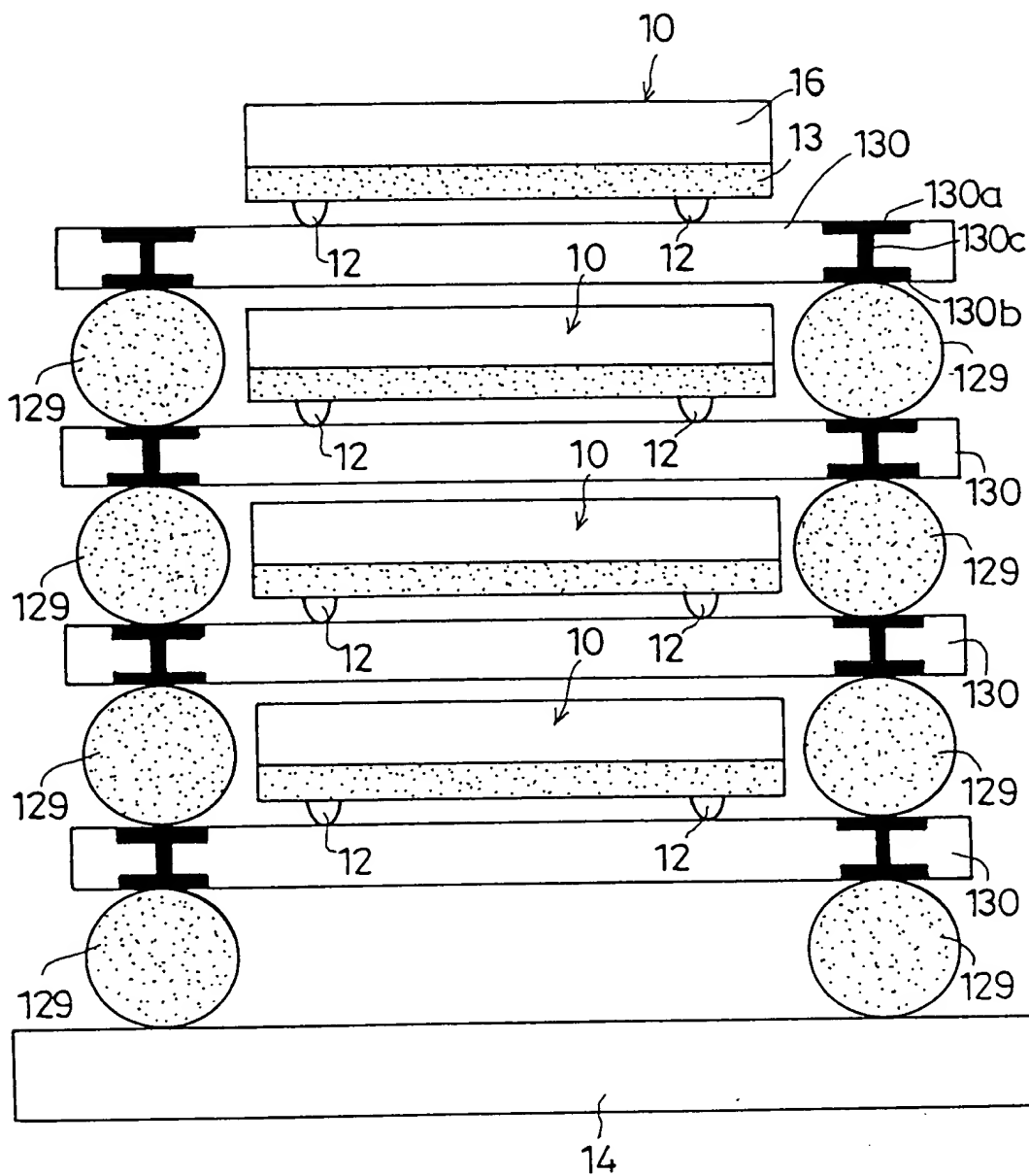


FIG. 56

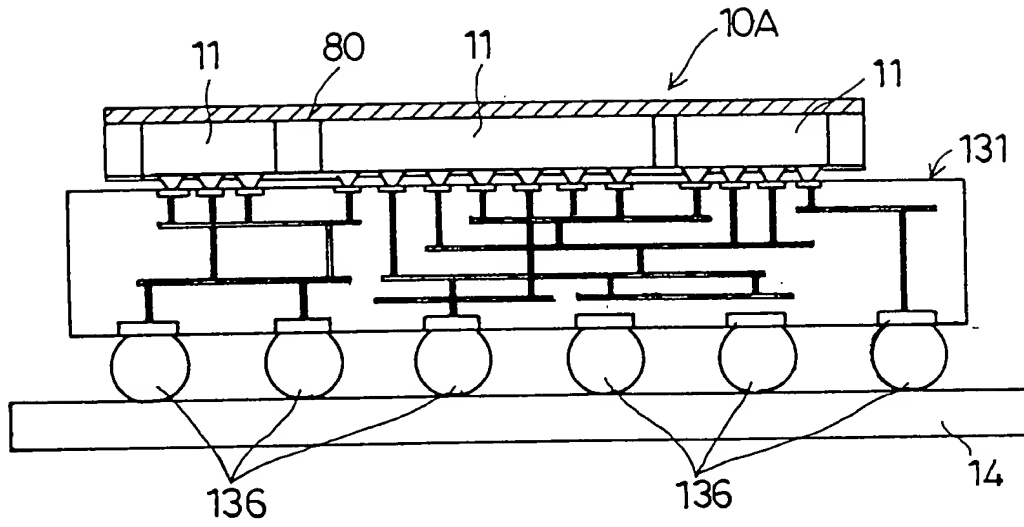


FIG. 57

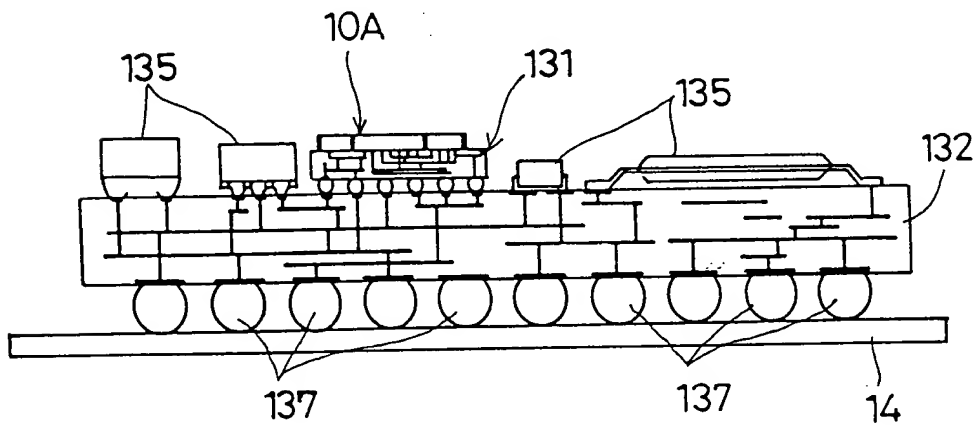


FIG. 58

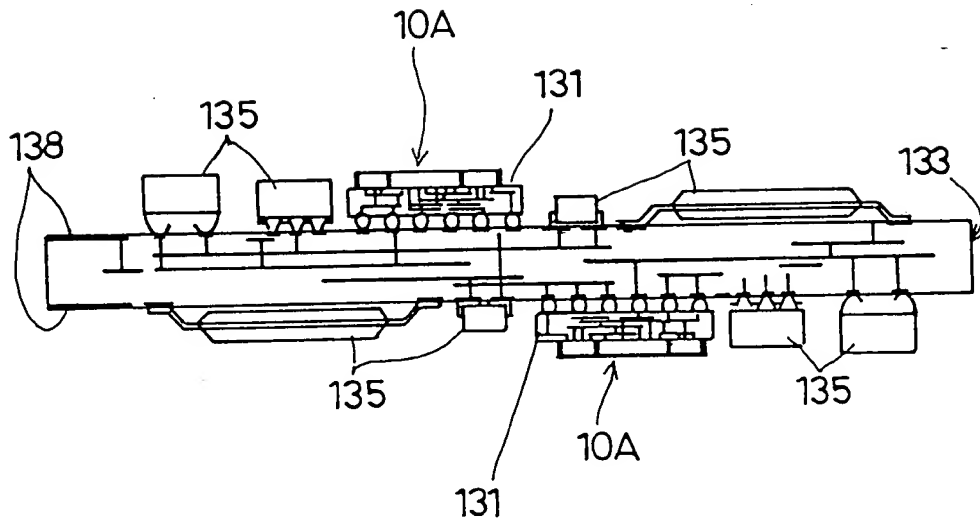
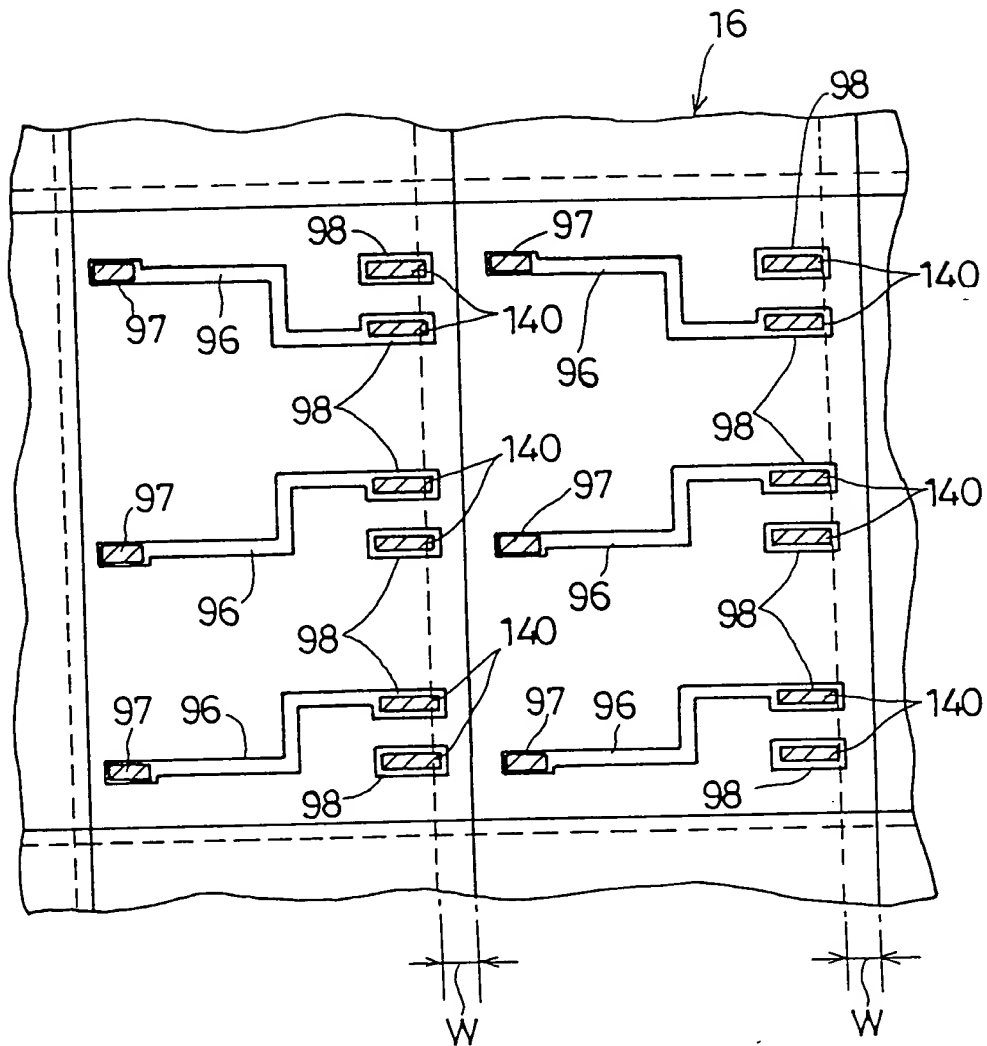


FIG. 59



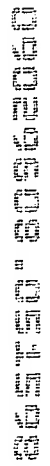
[illegible]

FIG. 61

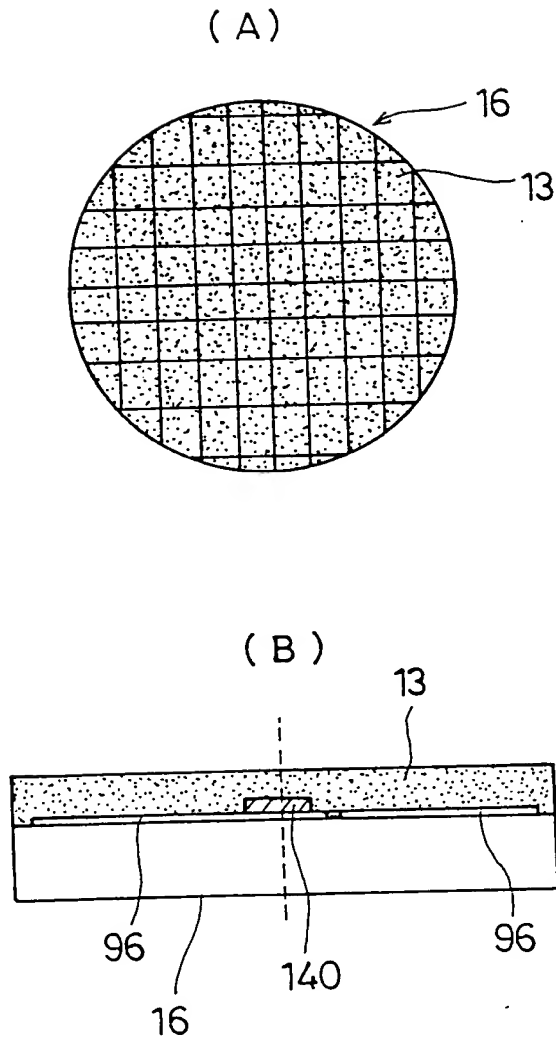


FIG. 62

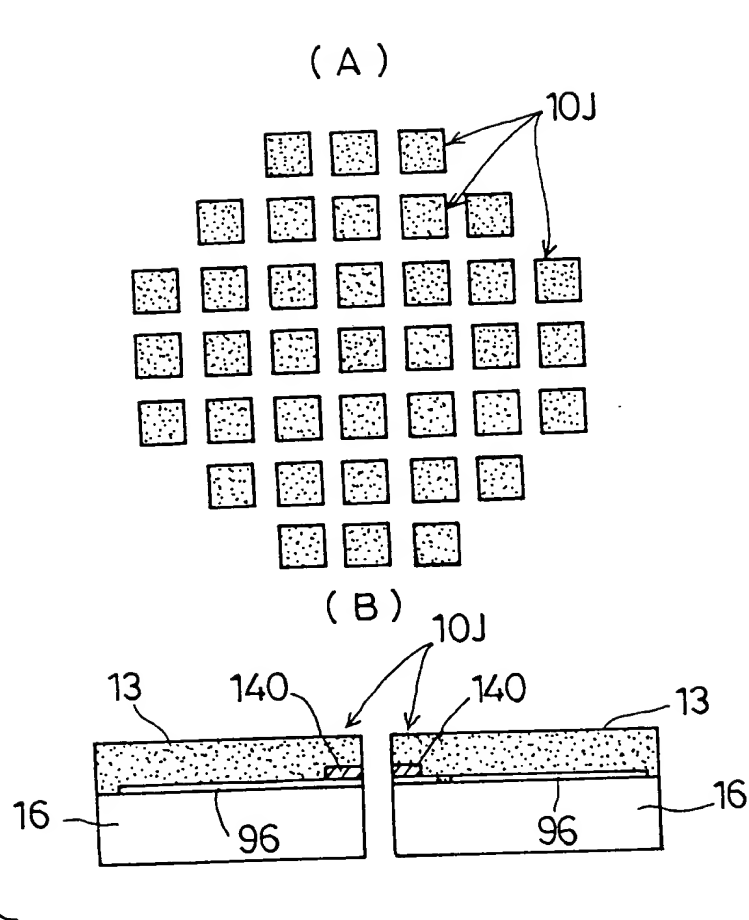


FIG. 63

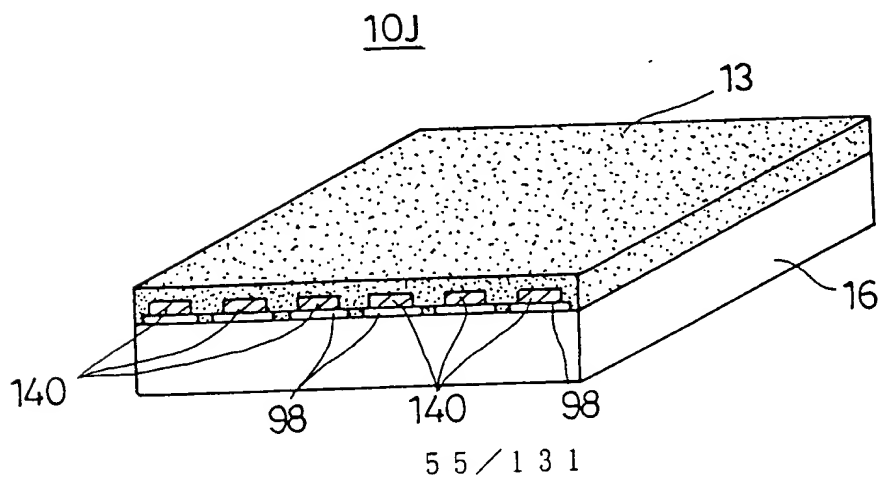


FIG. 64

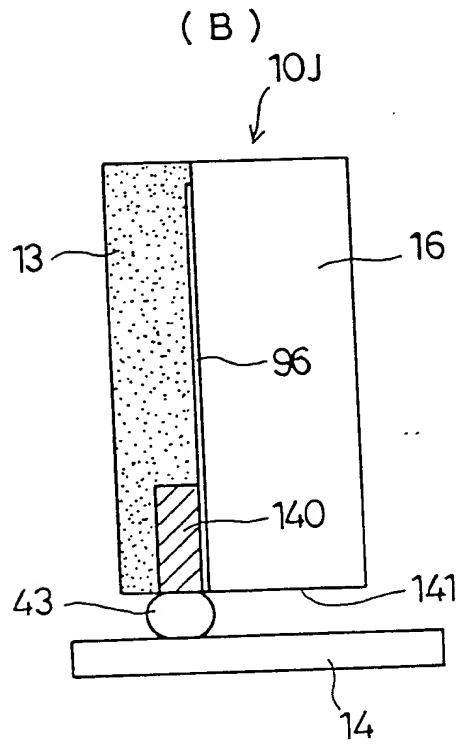
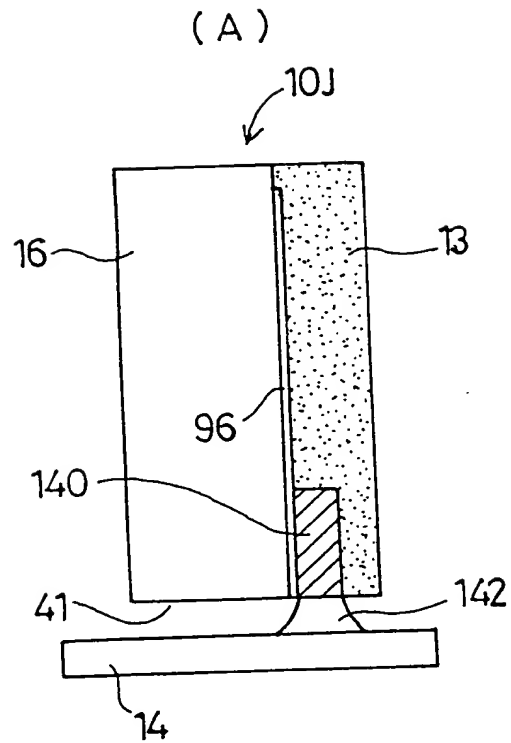


FIG. 65

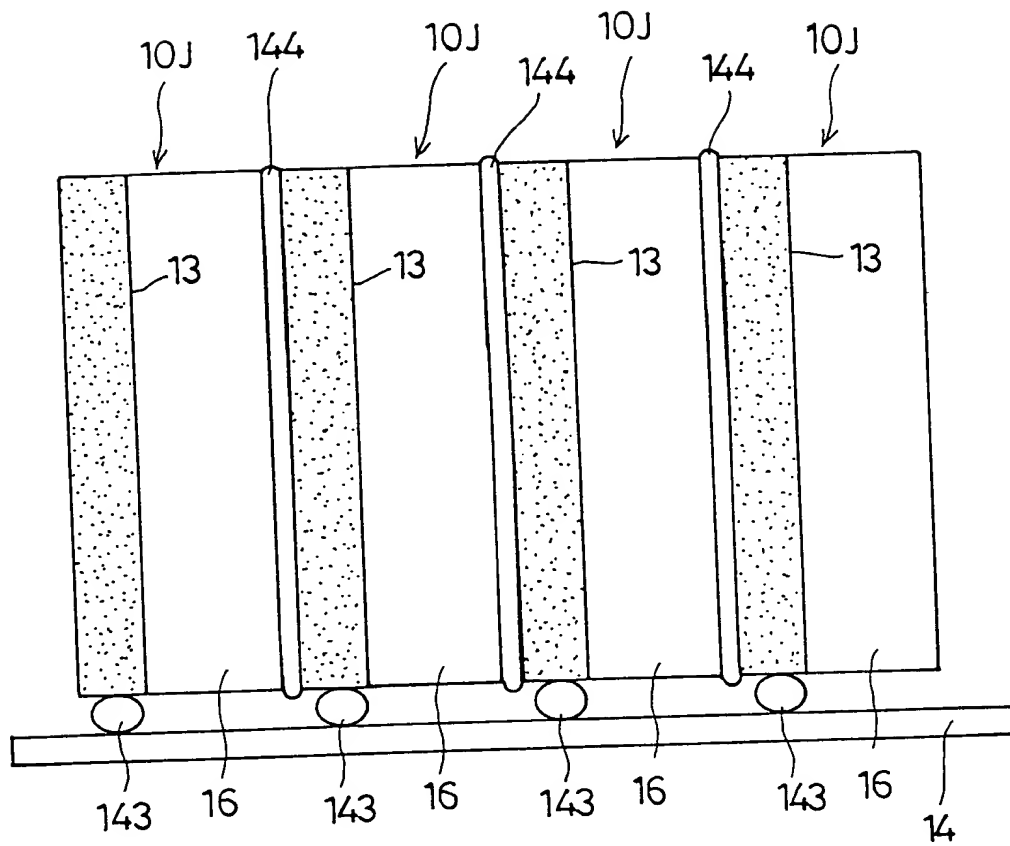


FIG. 66

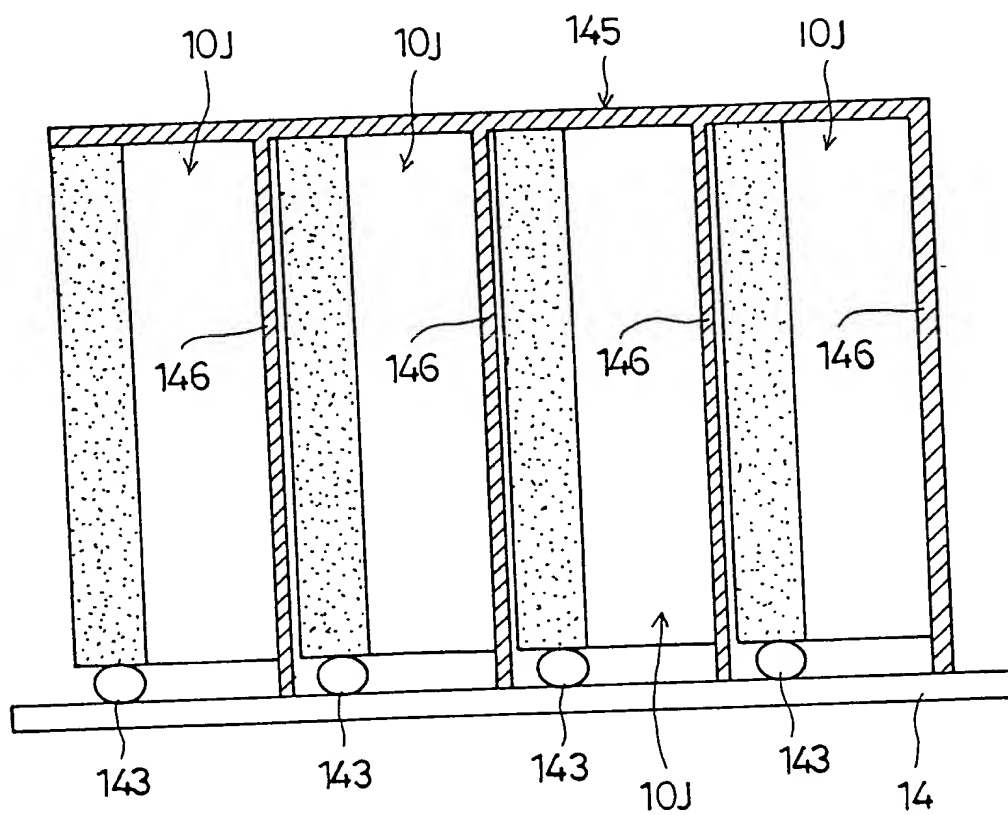


FIG. 67

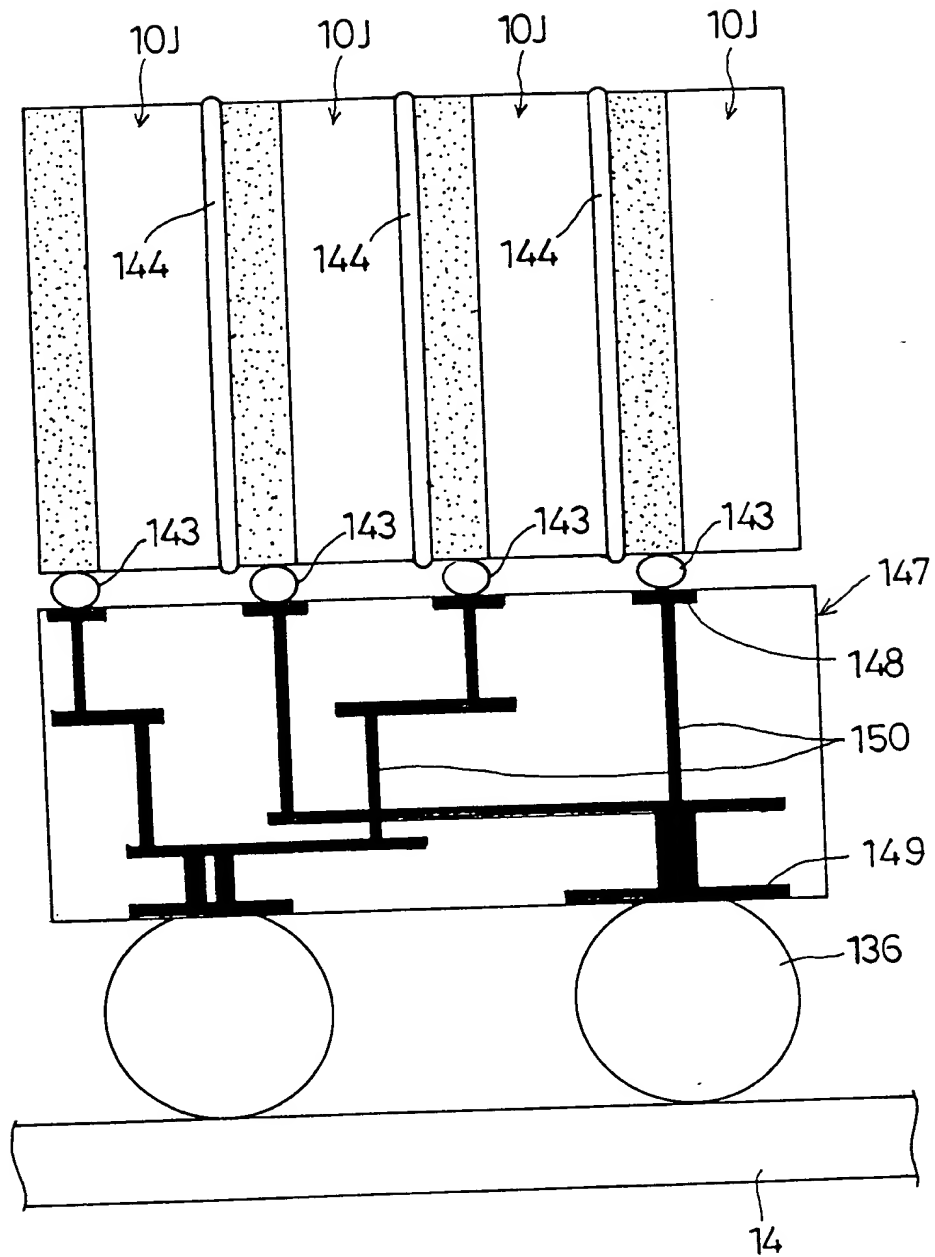


FIG. 68

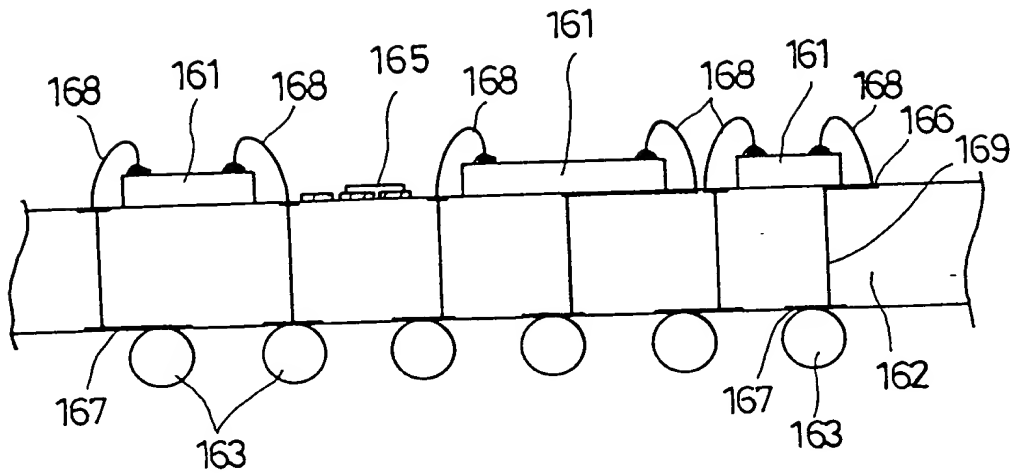


FIG. 69

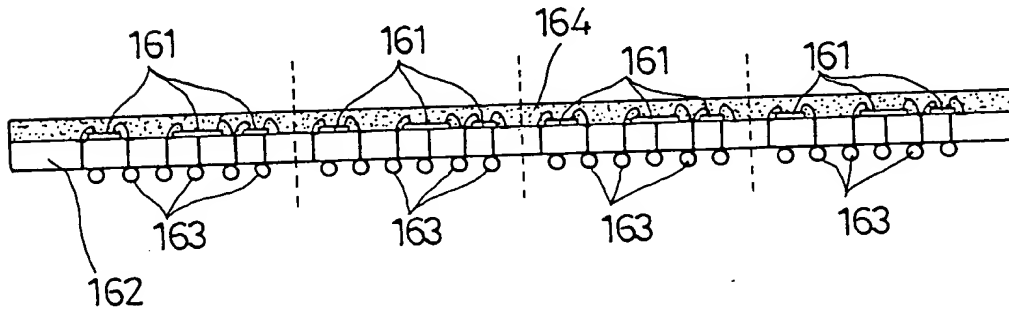


FIG. 70

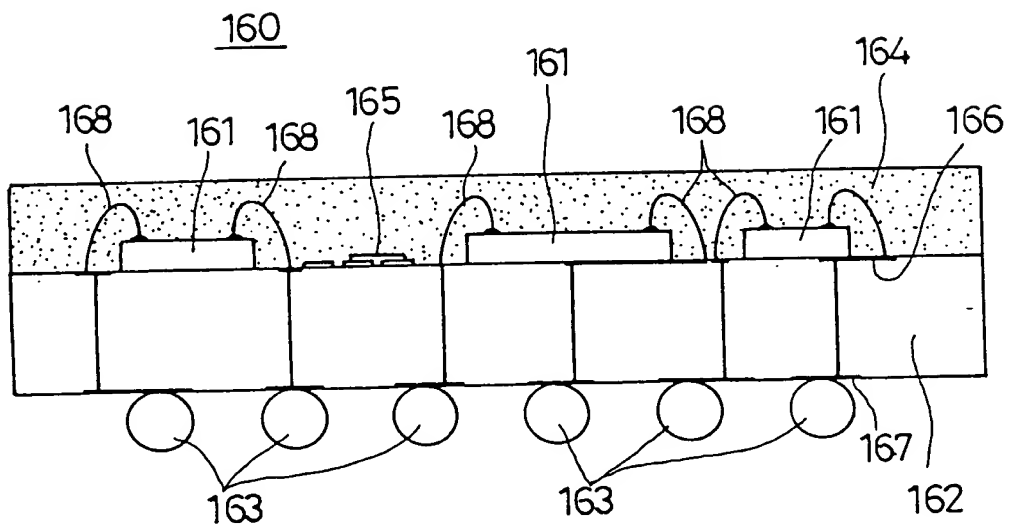


FIG. 71

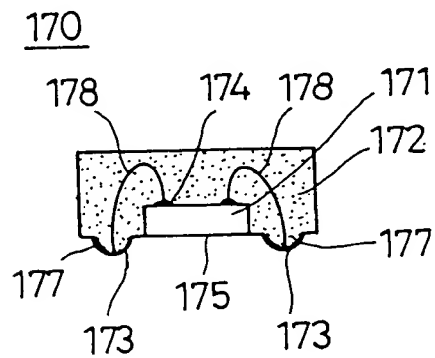


FIG. 72

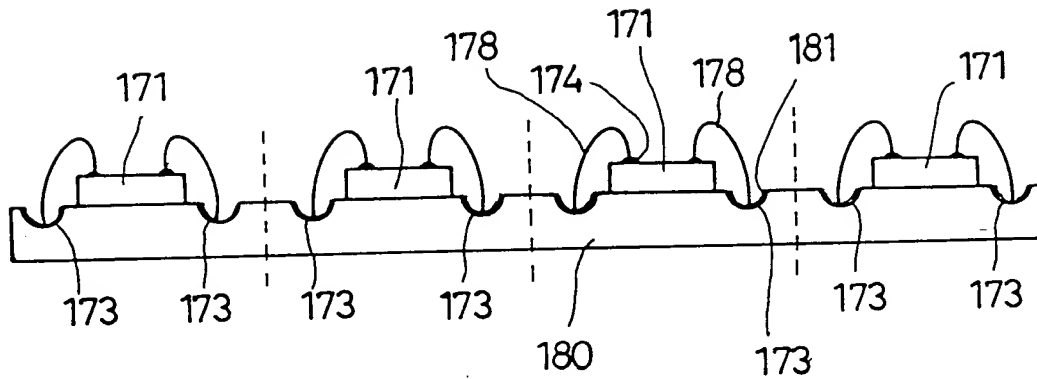


FIG. 73

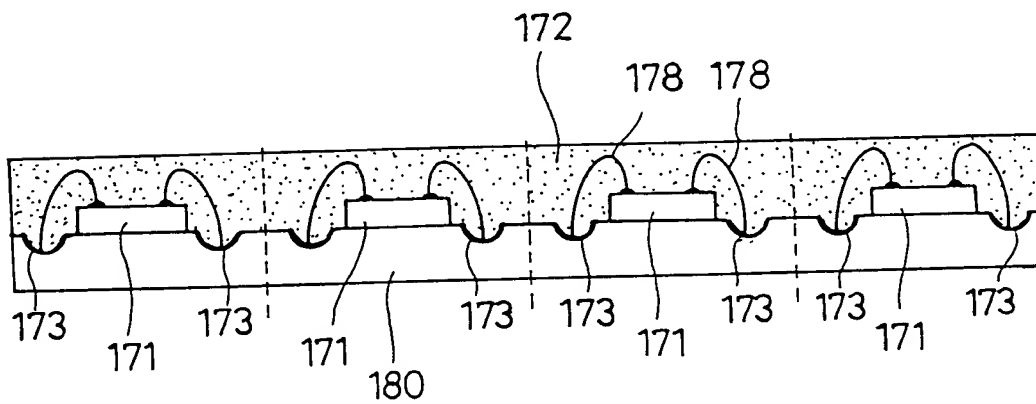


FIG. 74

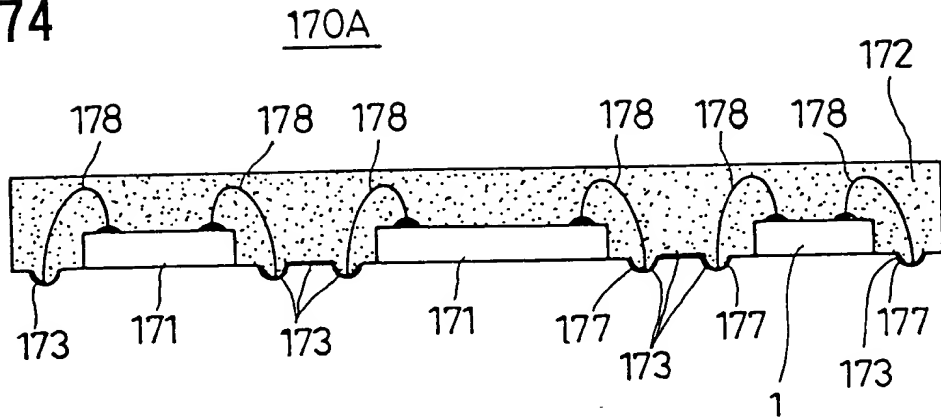
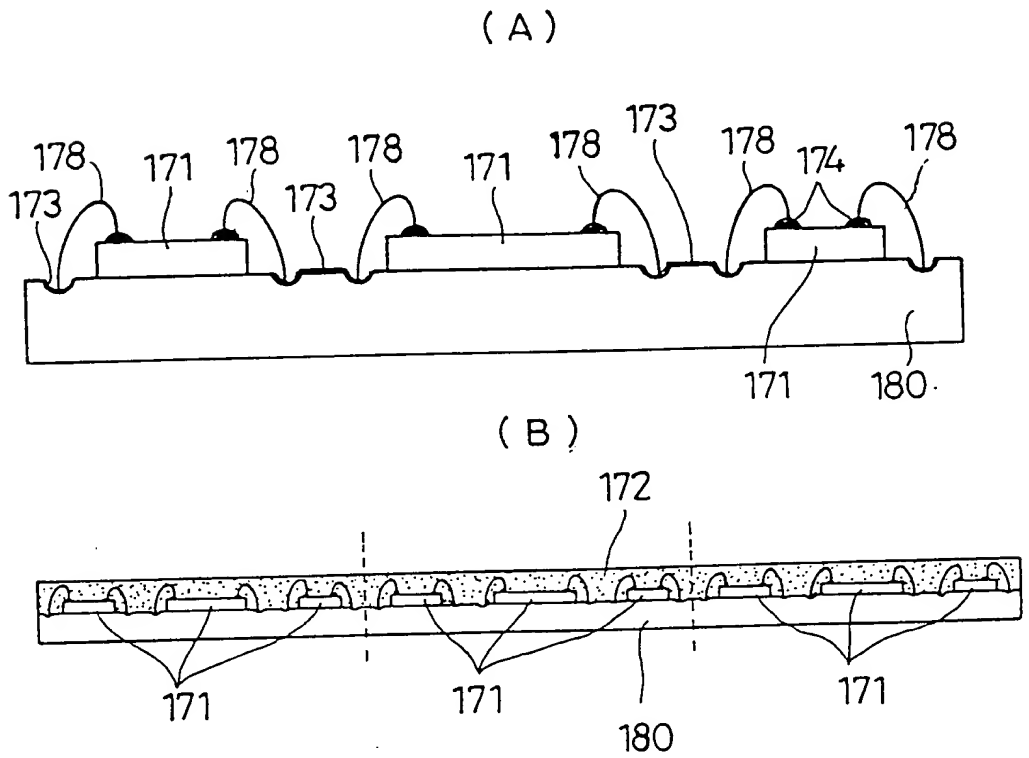
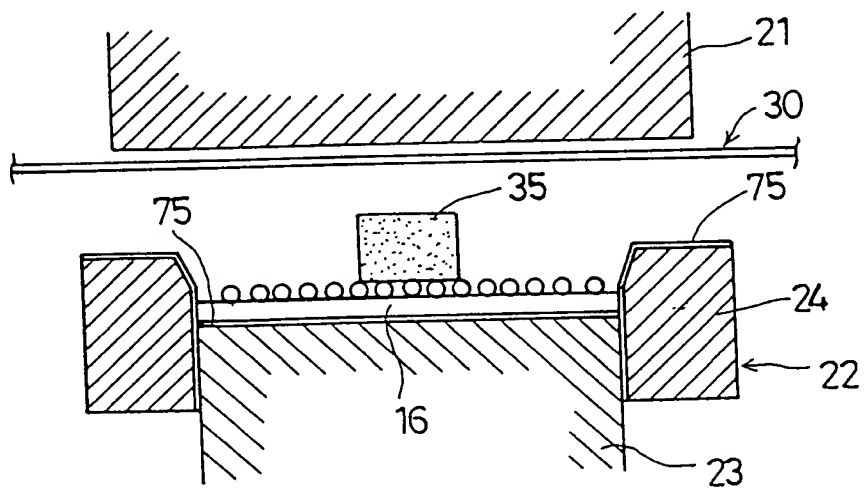


FIG. 75





6 4 / 1 3 1



6 5 / 1 3 1

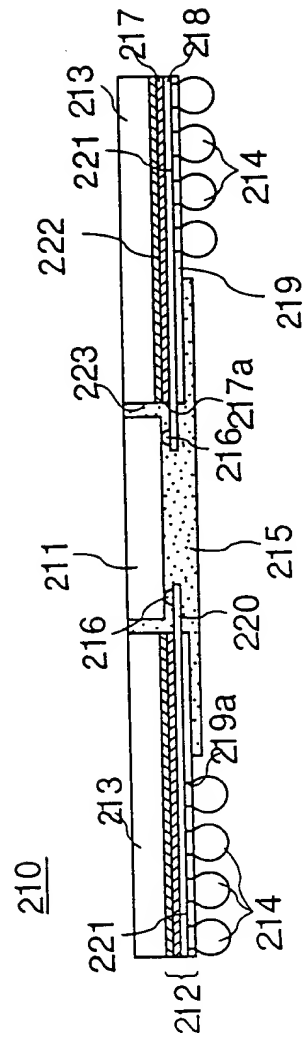
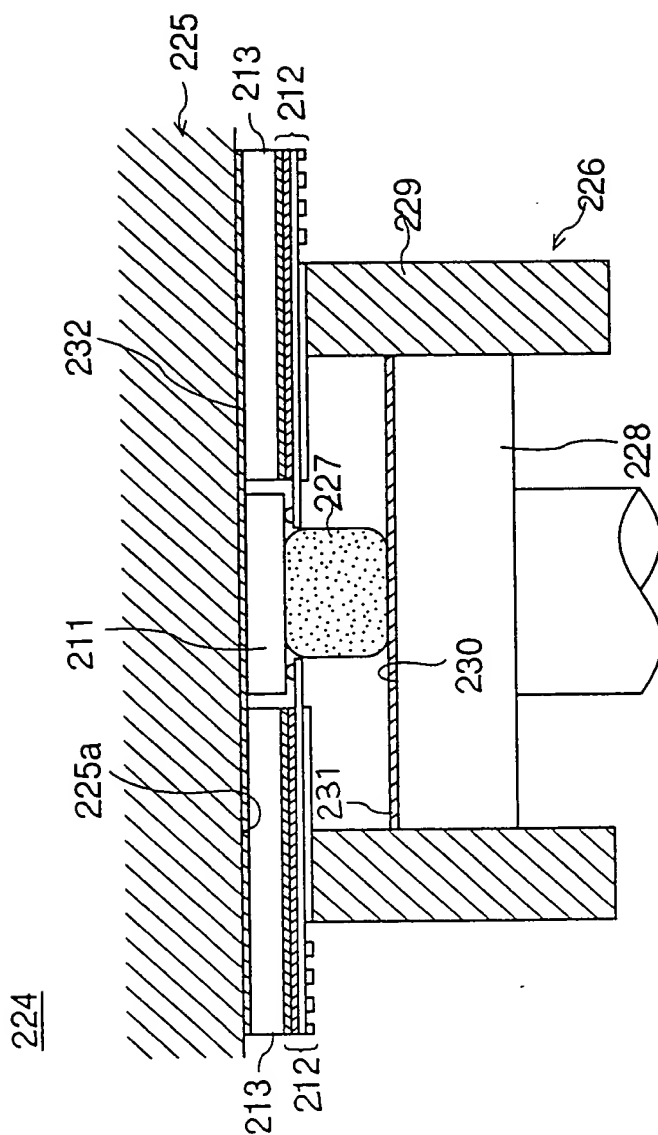




FIG. 80



6 8 / 1 3 1

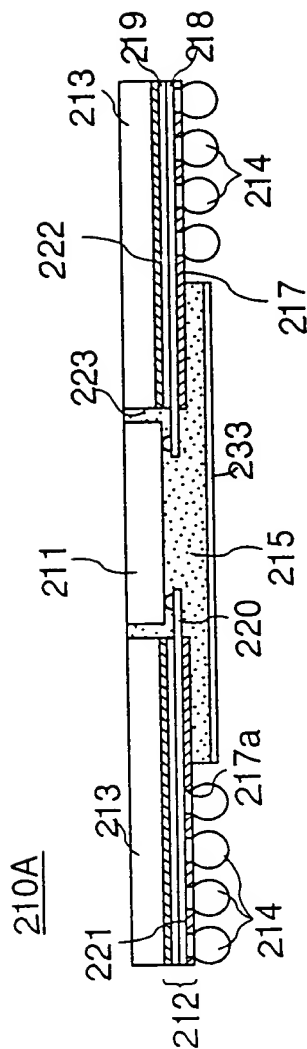


FIG. 82

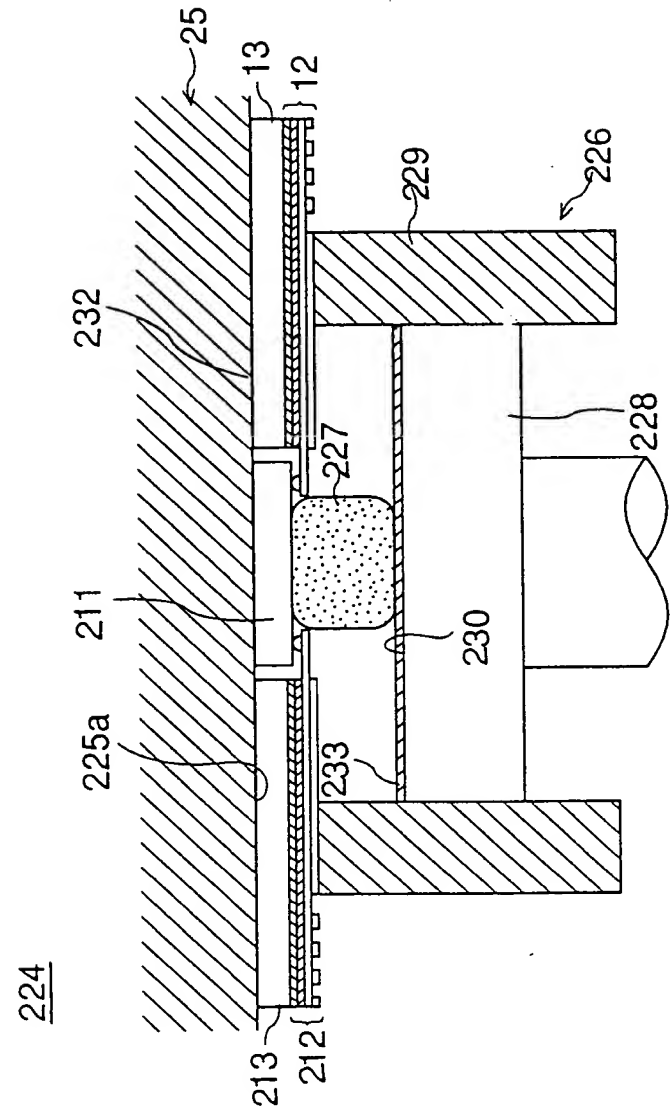


FIG. 83

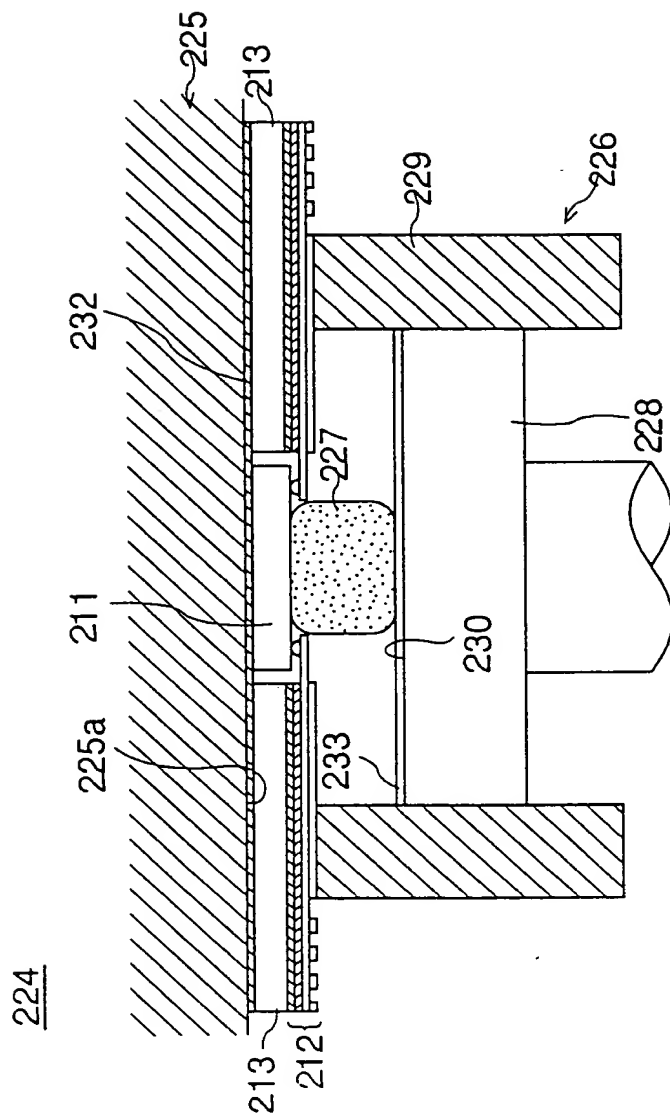


FIG. 84

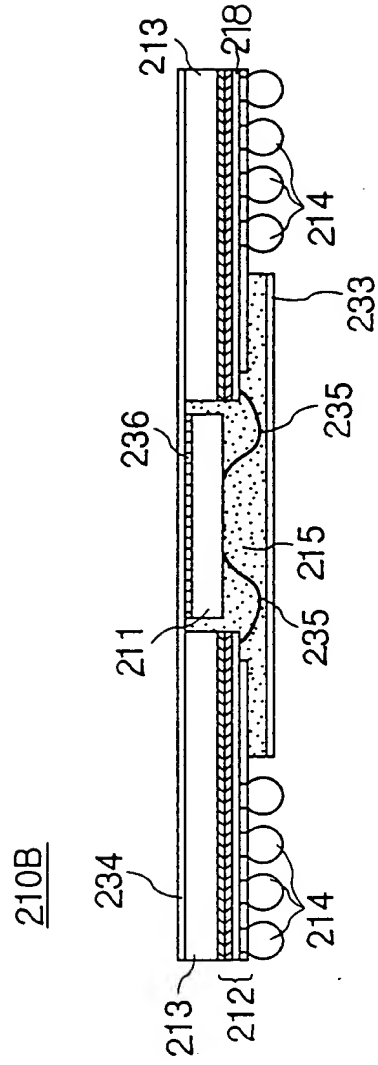


FIG. 85

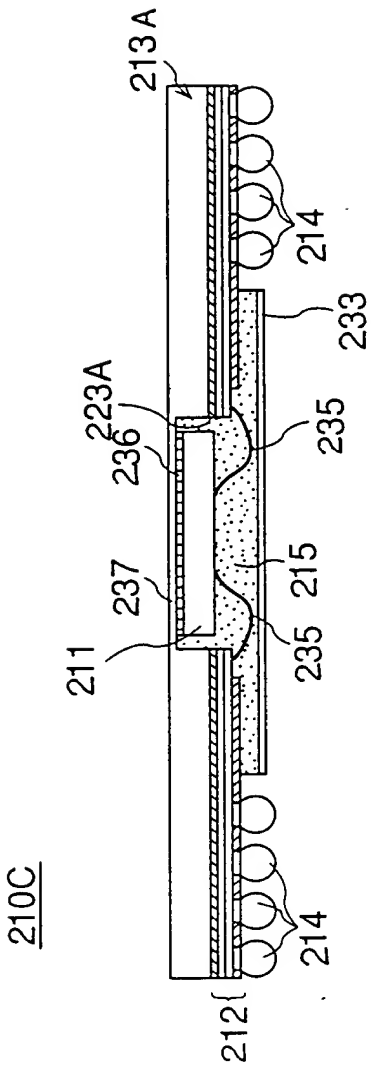


FIG. 86

210D

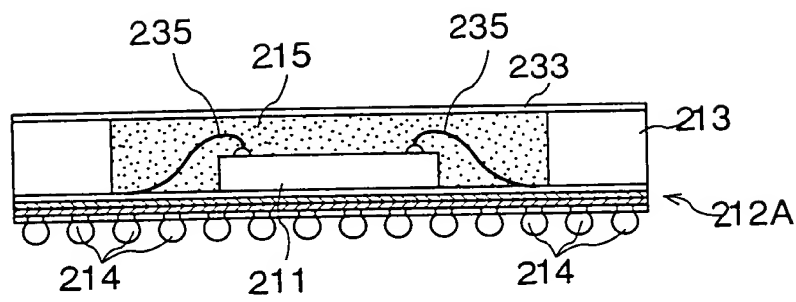


FIG. 87

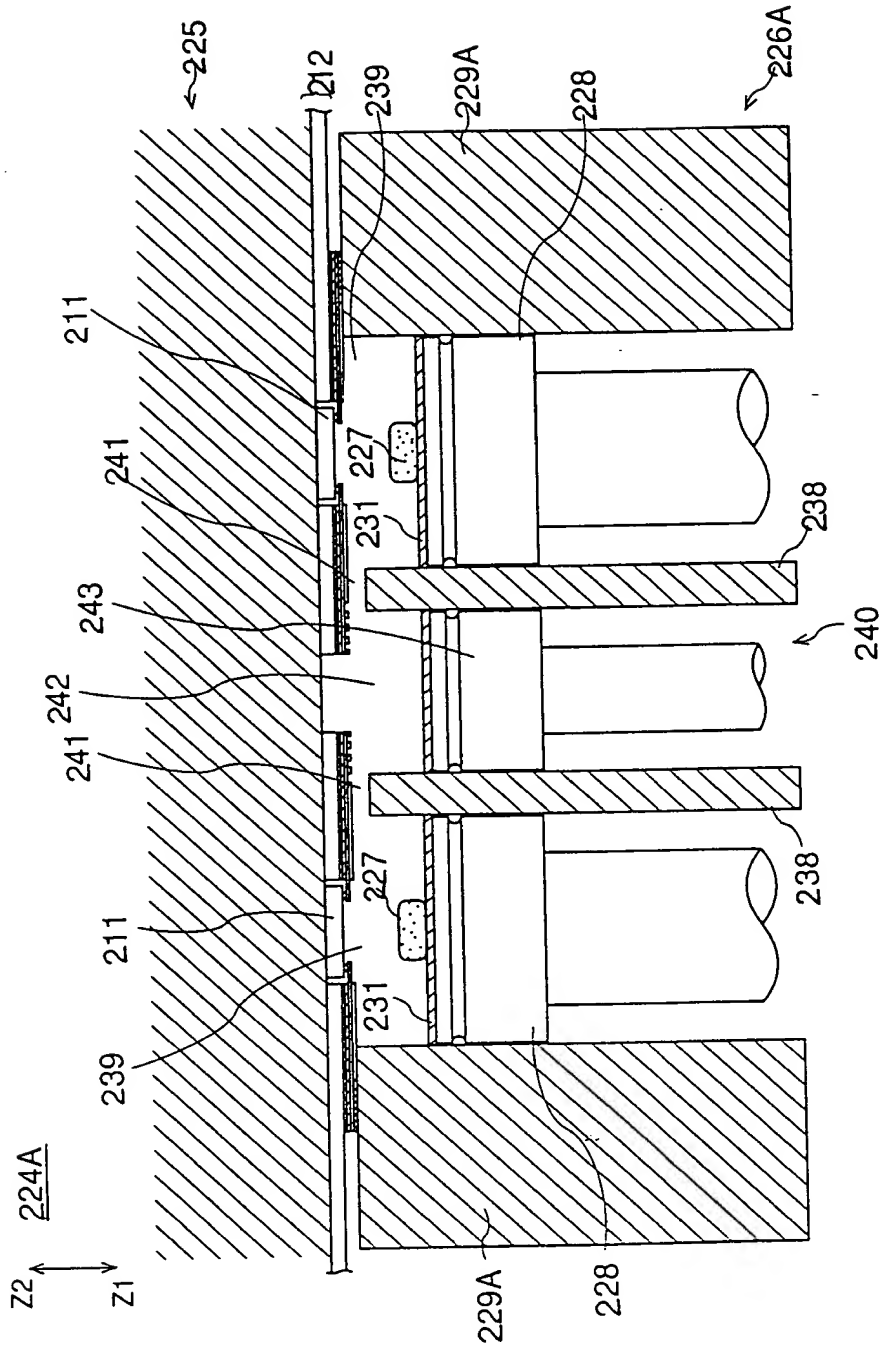


FIG. 88

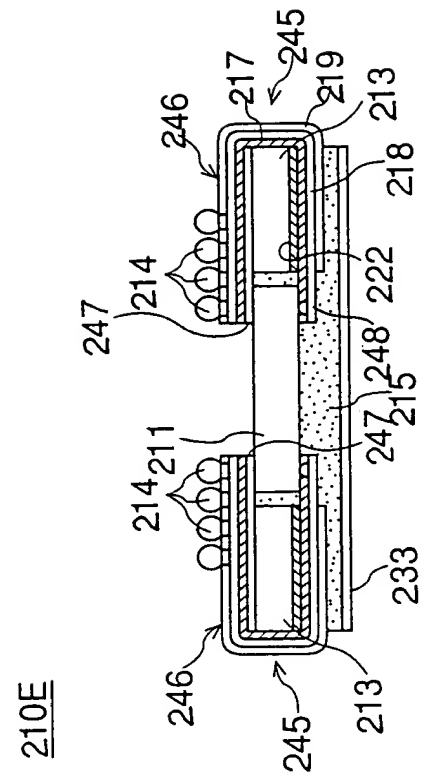


FIG. 89

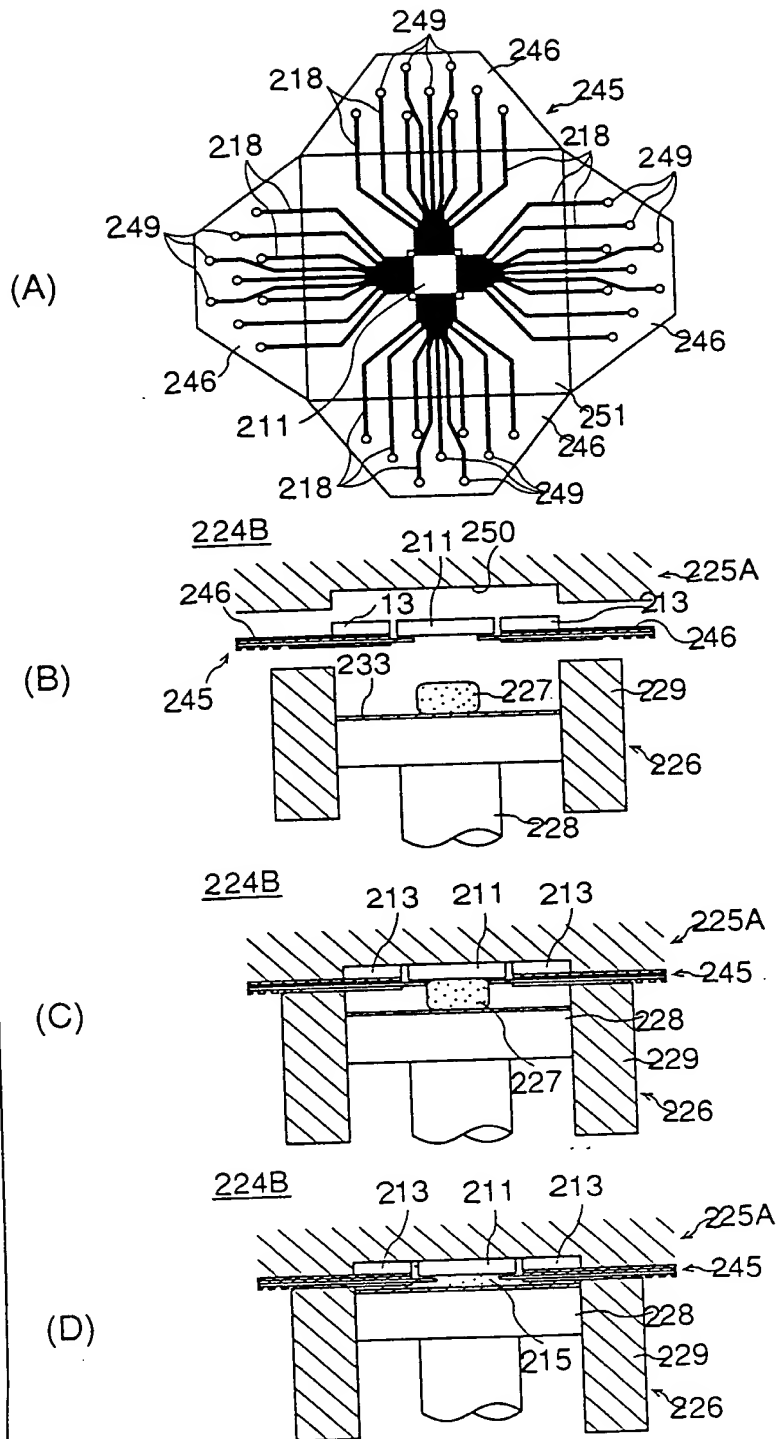


FIG. 90

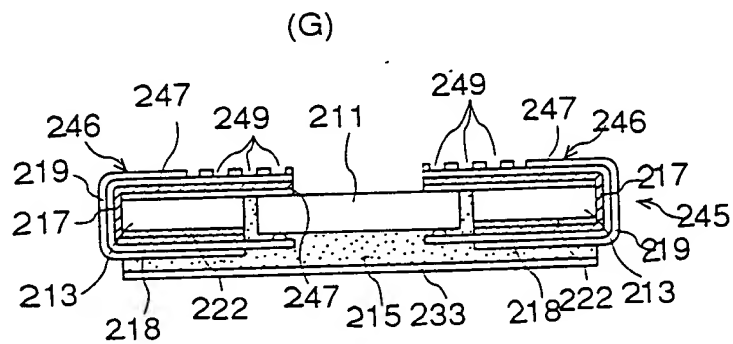
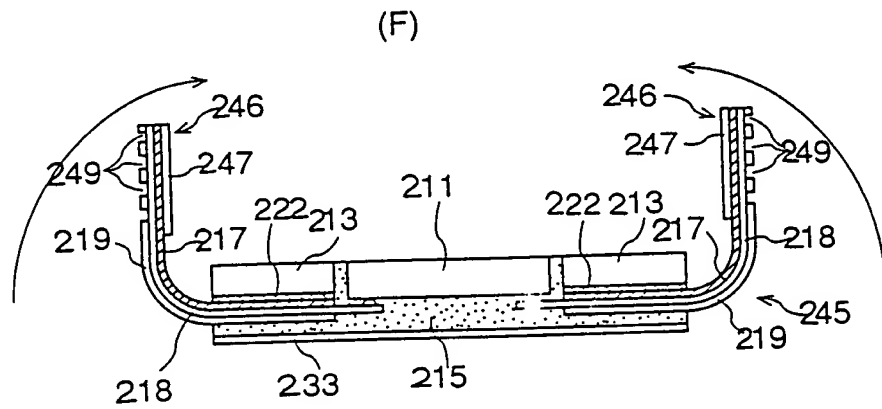
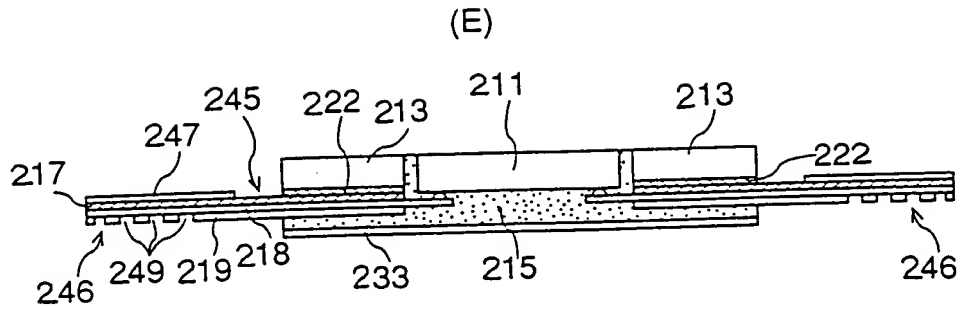


FIG. 91

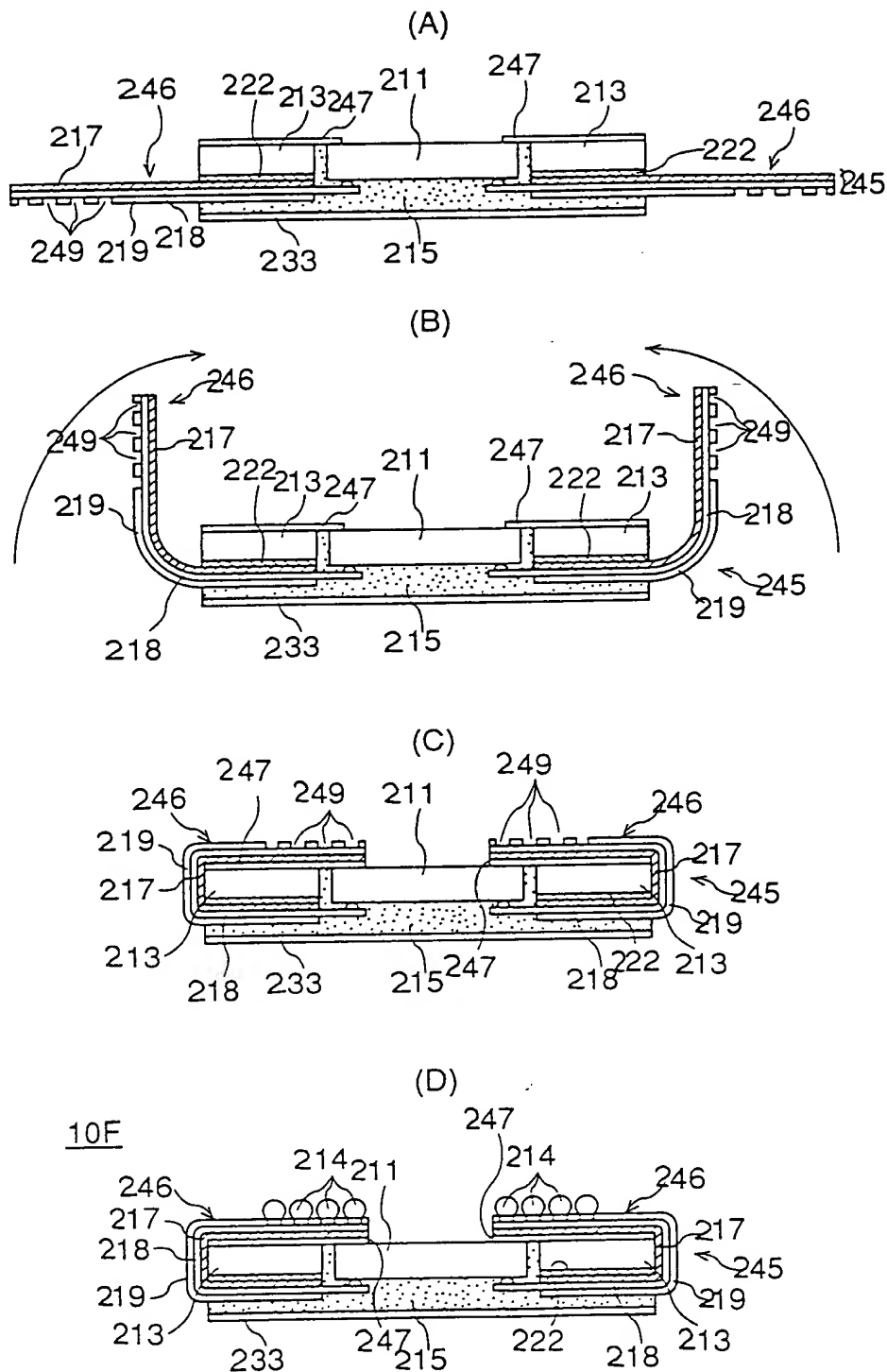


FIG. 92

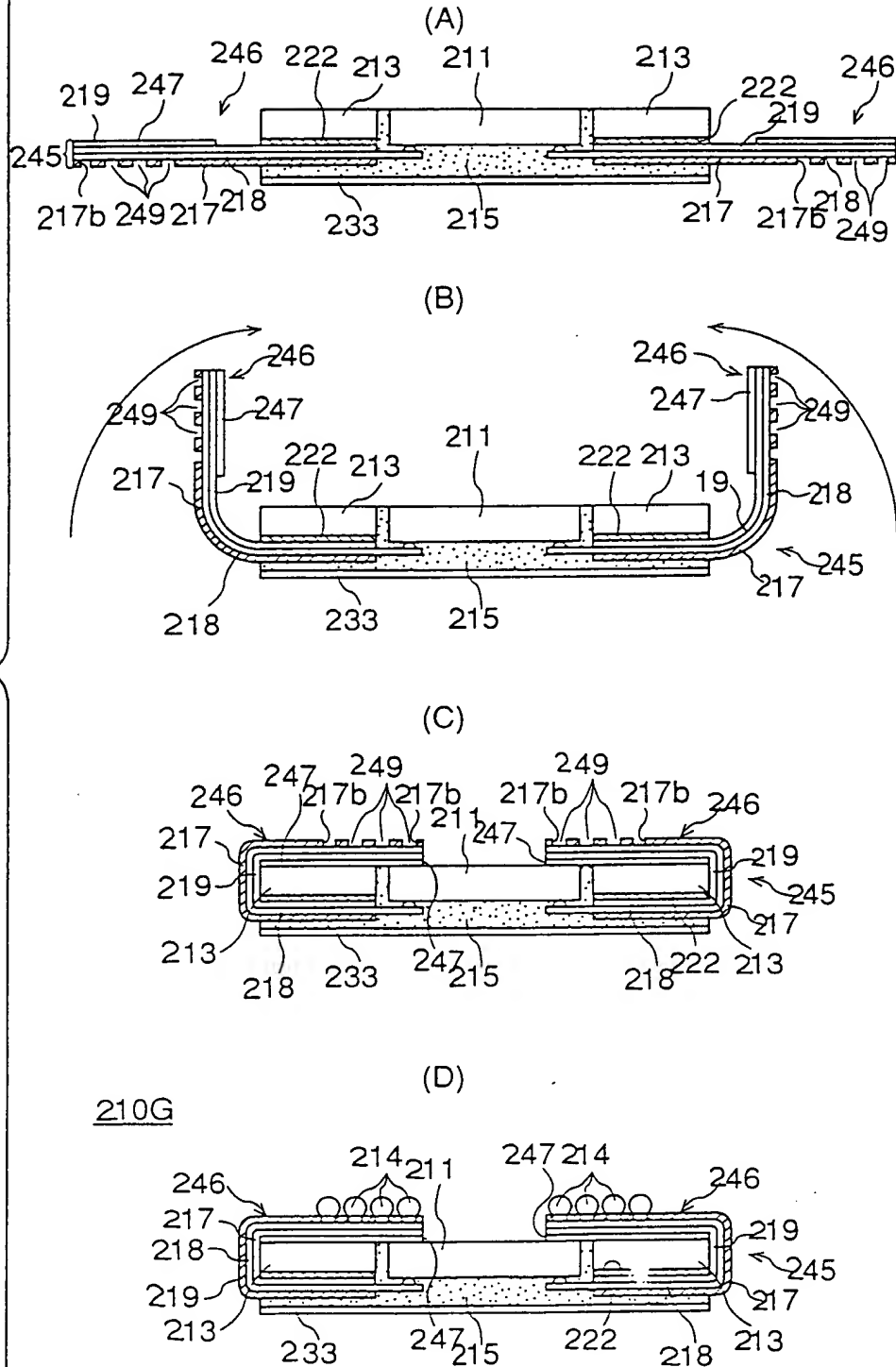


FIG. 93

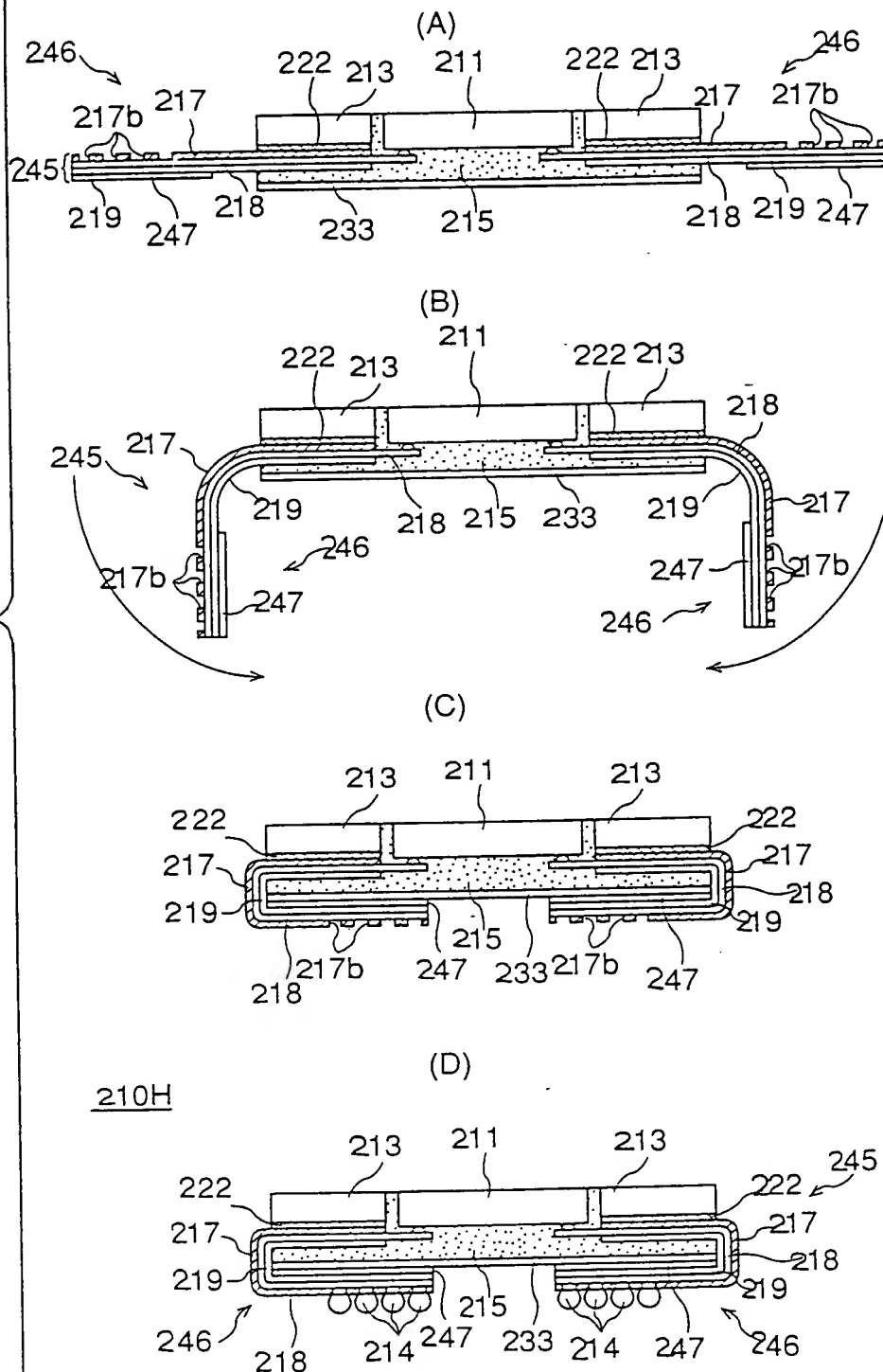


FIG. 94

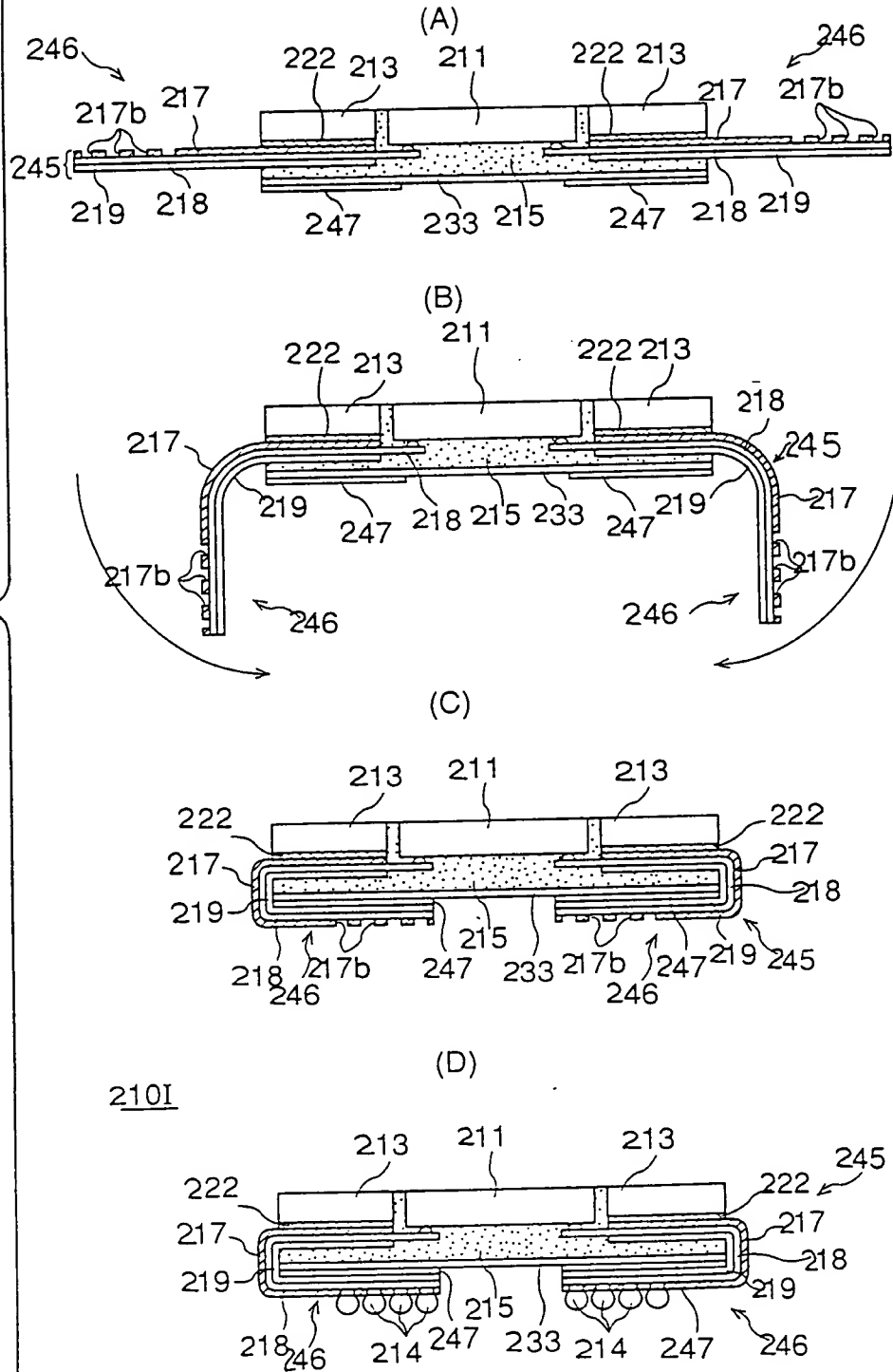


FIG. 95

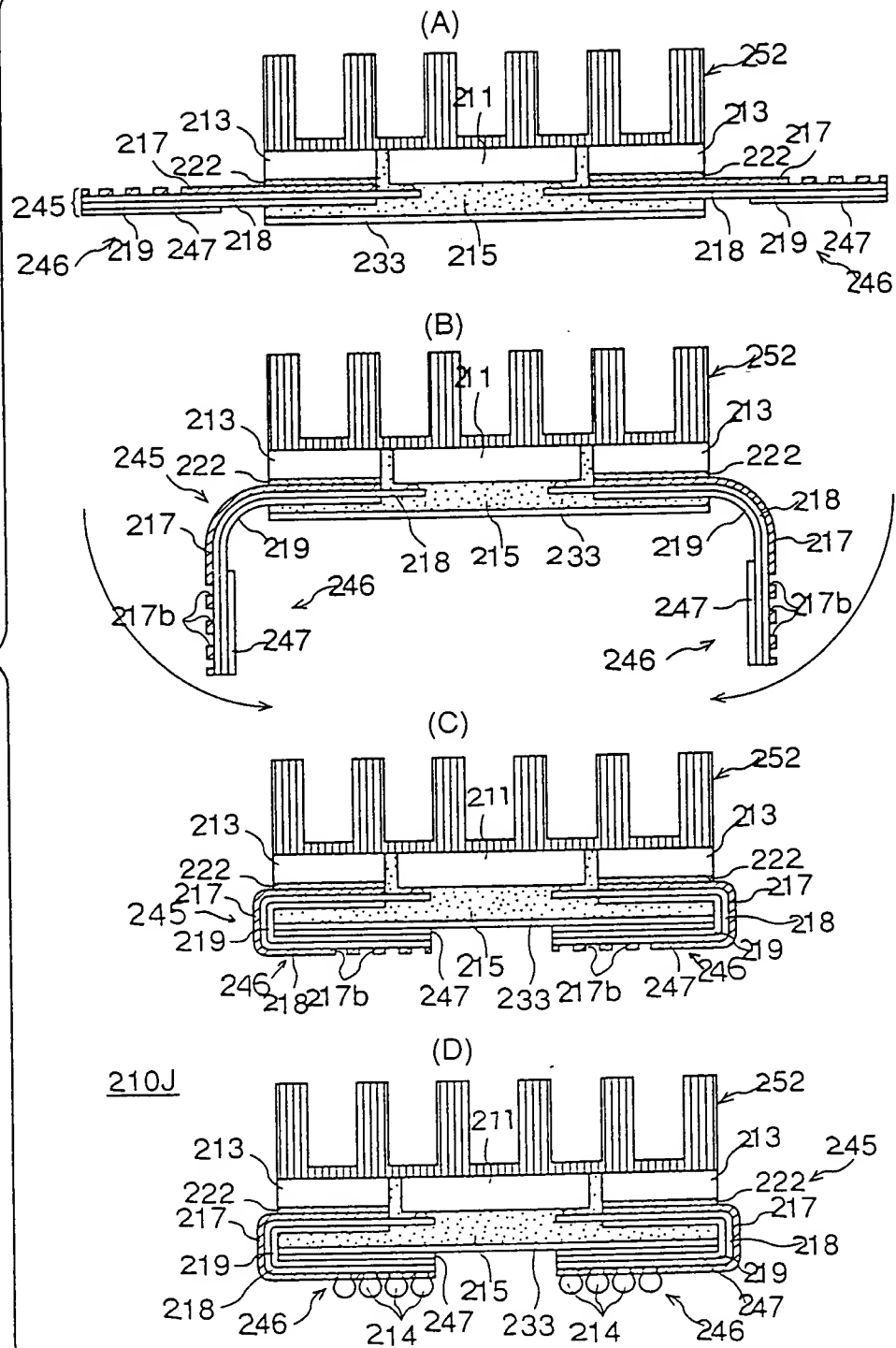


FIG. 96

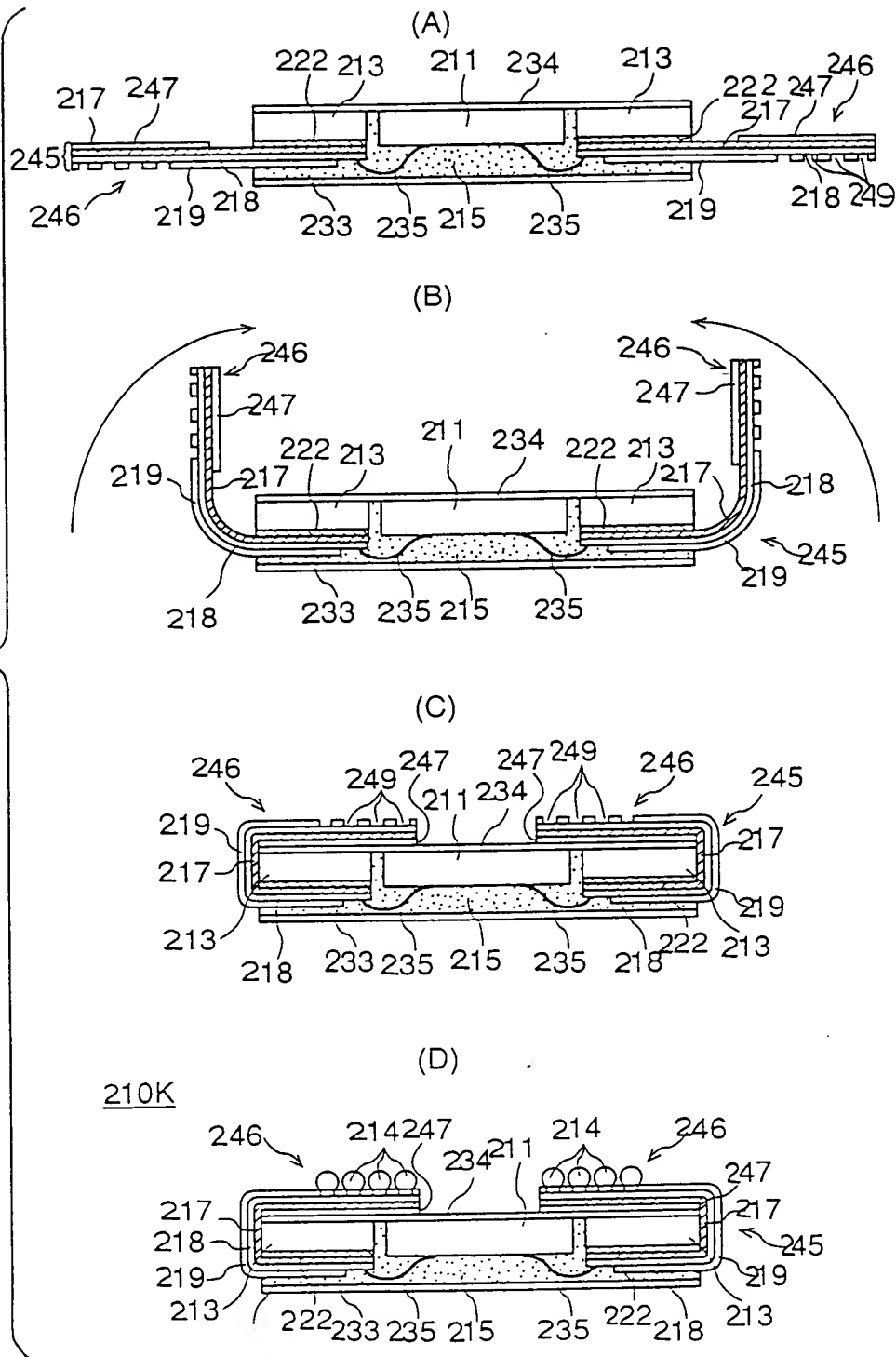


FIG. 97

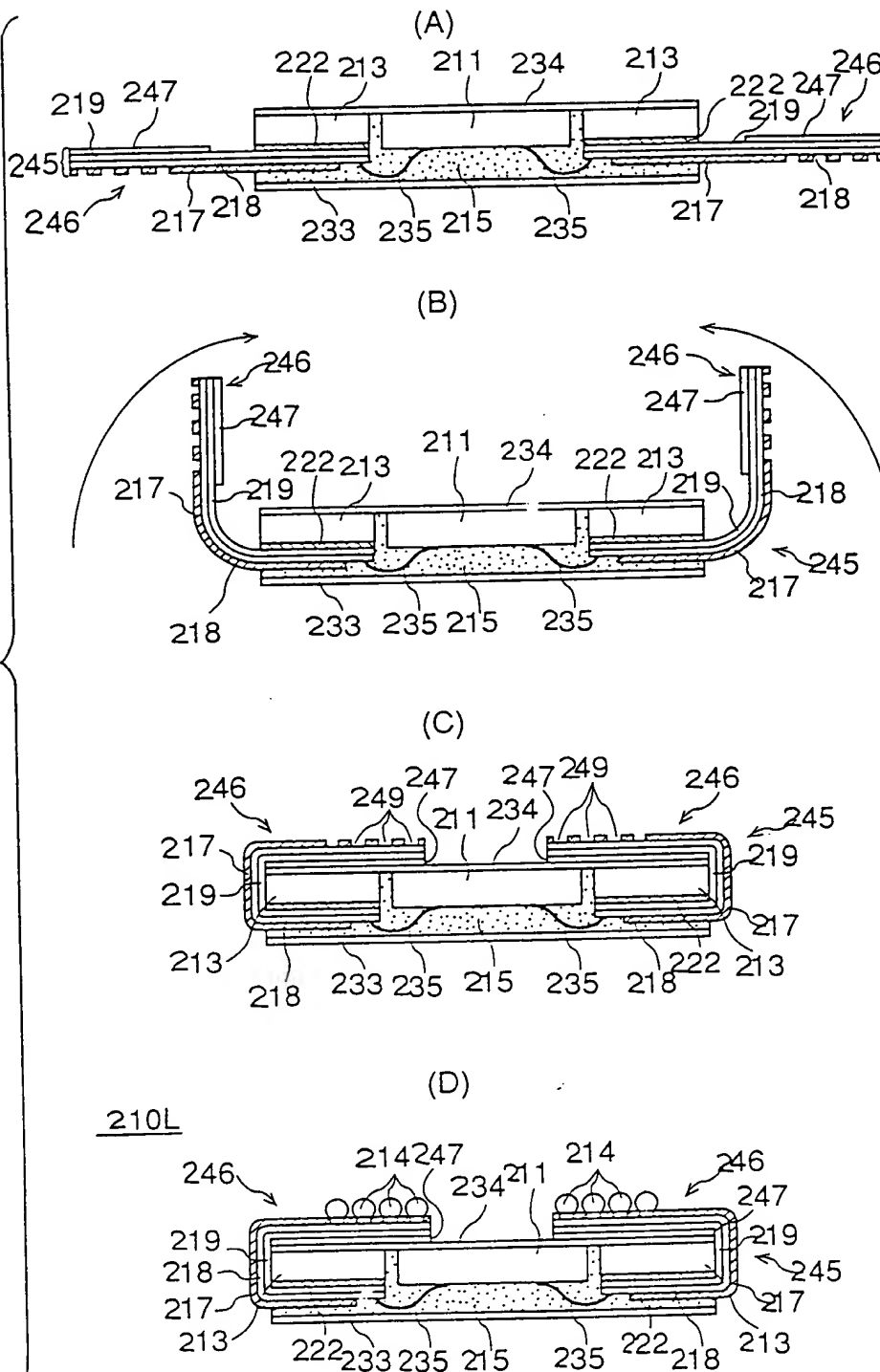


FIG. 98

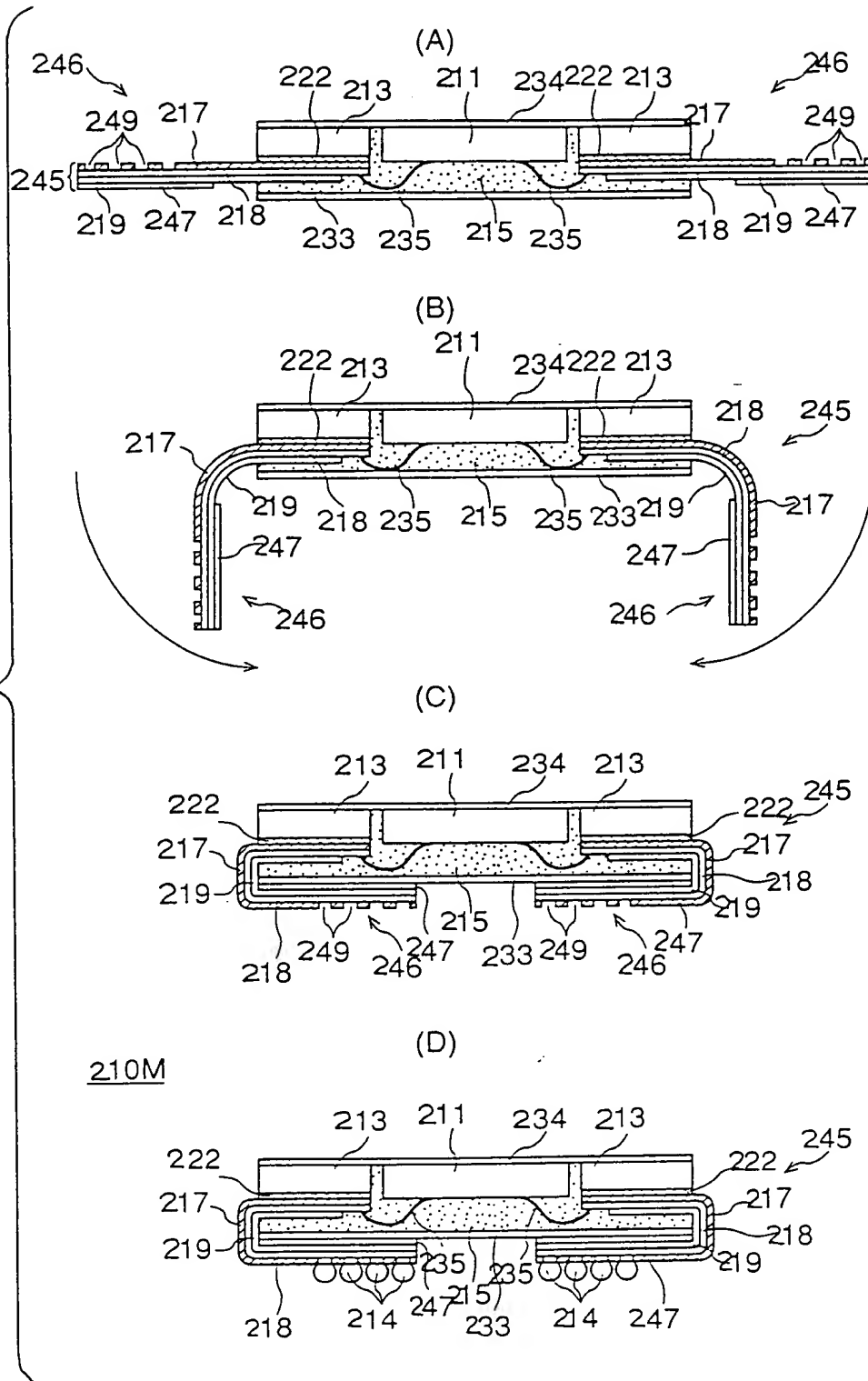


FIG. 99

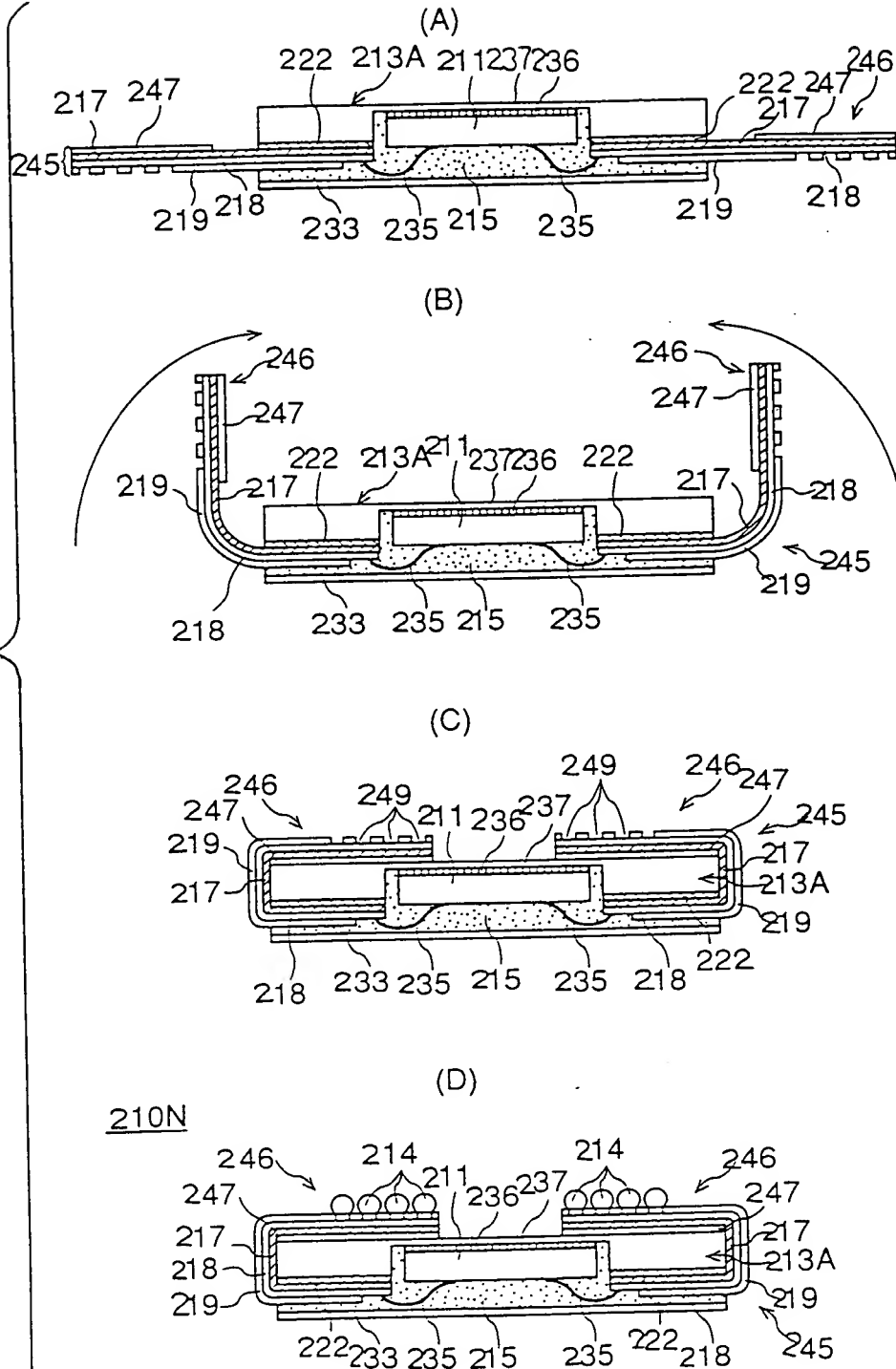


FIG. 100

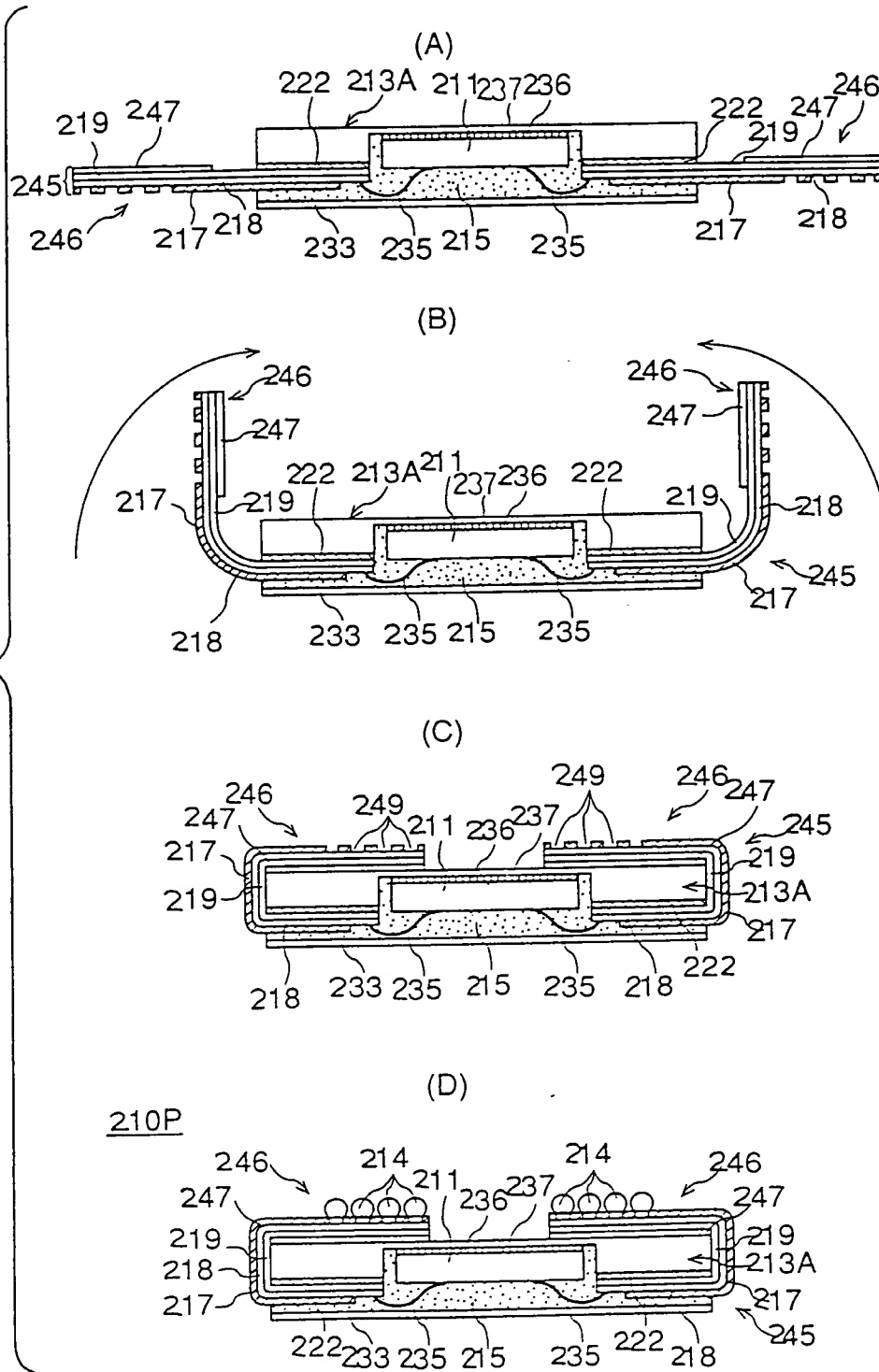


FIG. 101

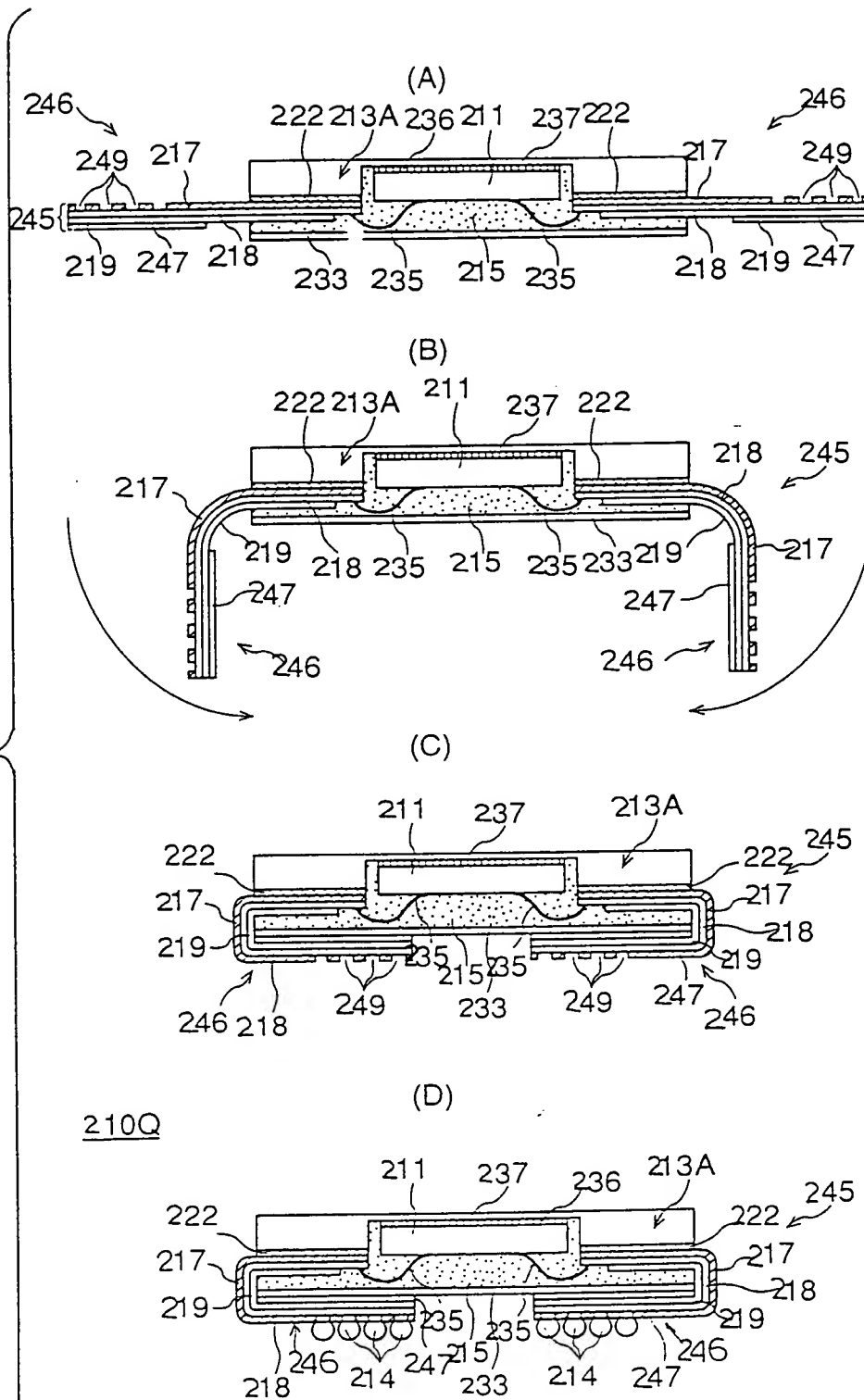


FIG. 102

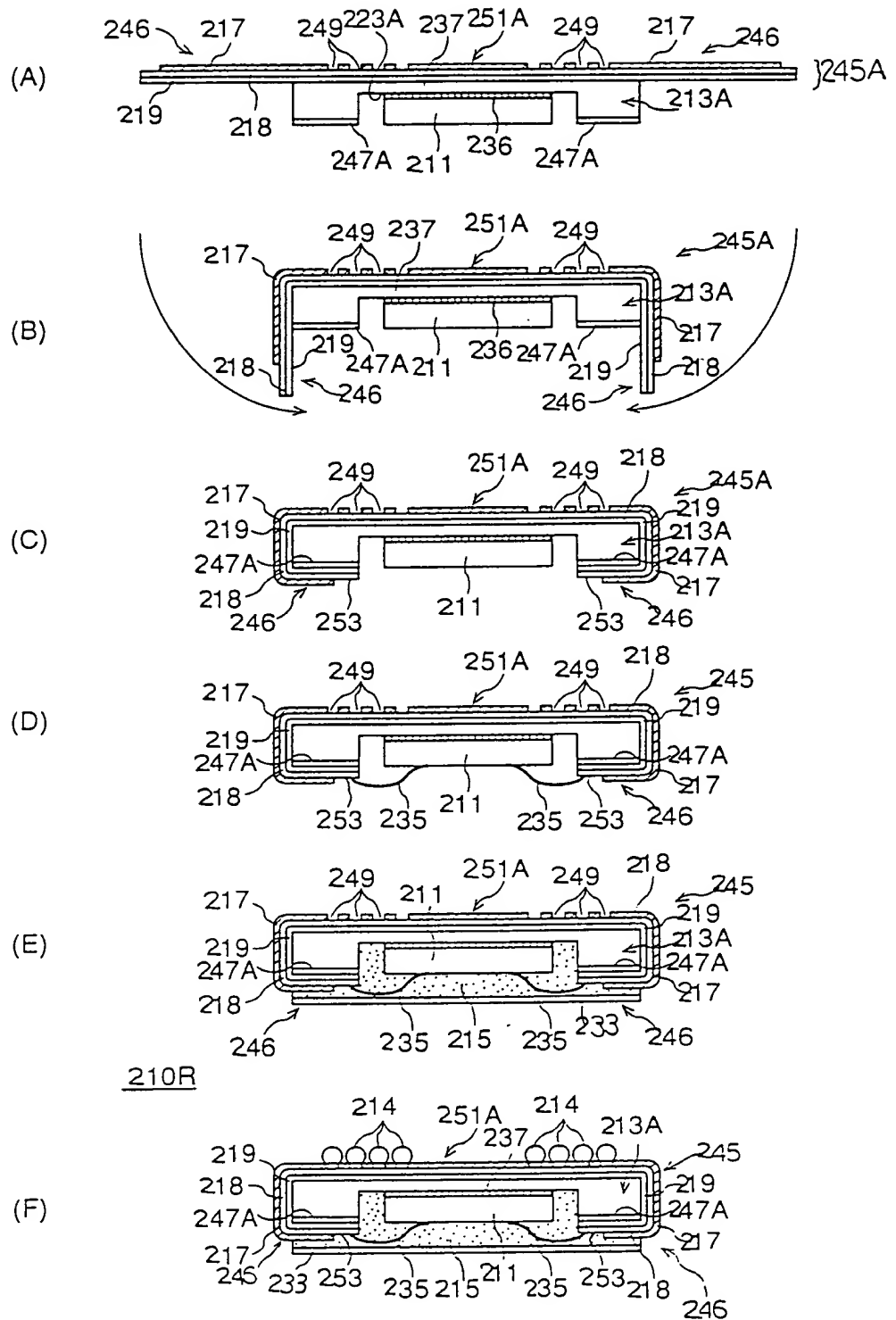


FIG. 103

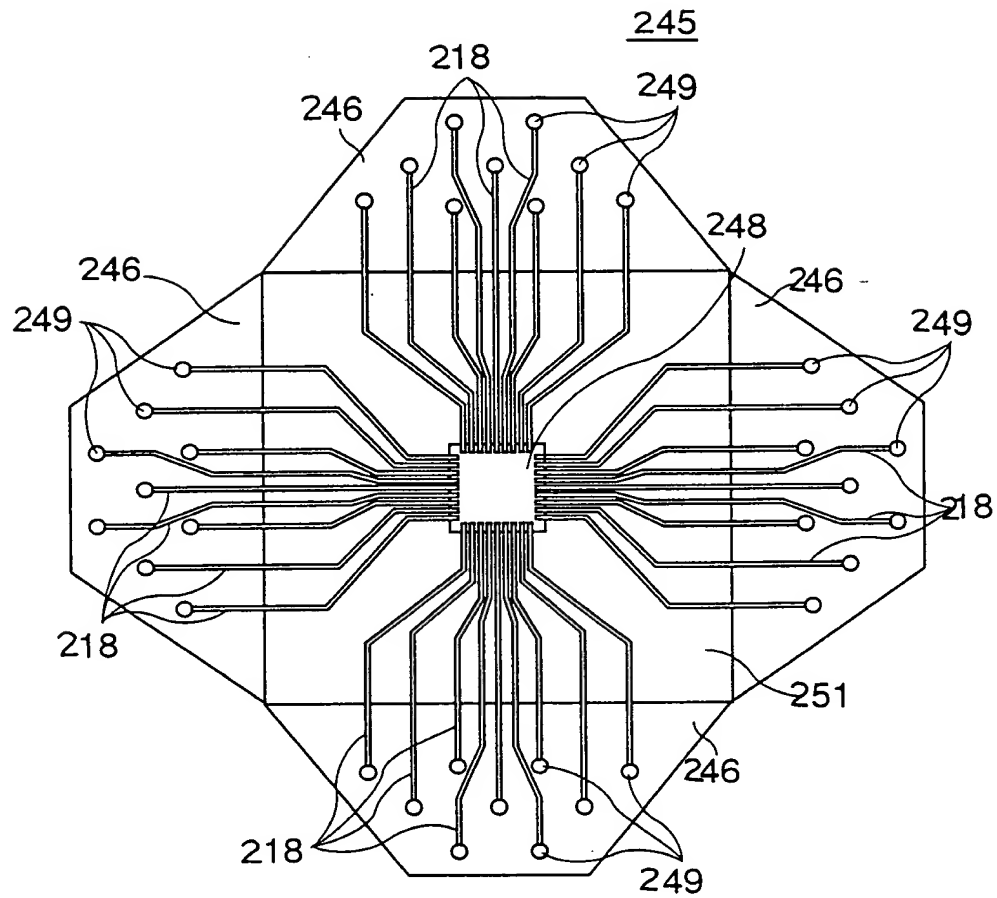


FIG. 104

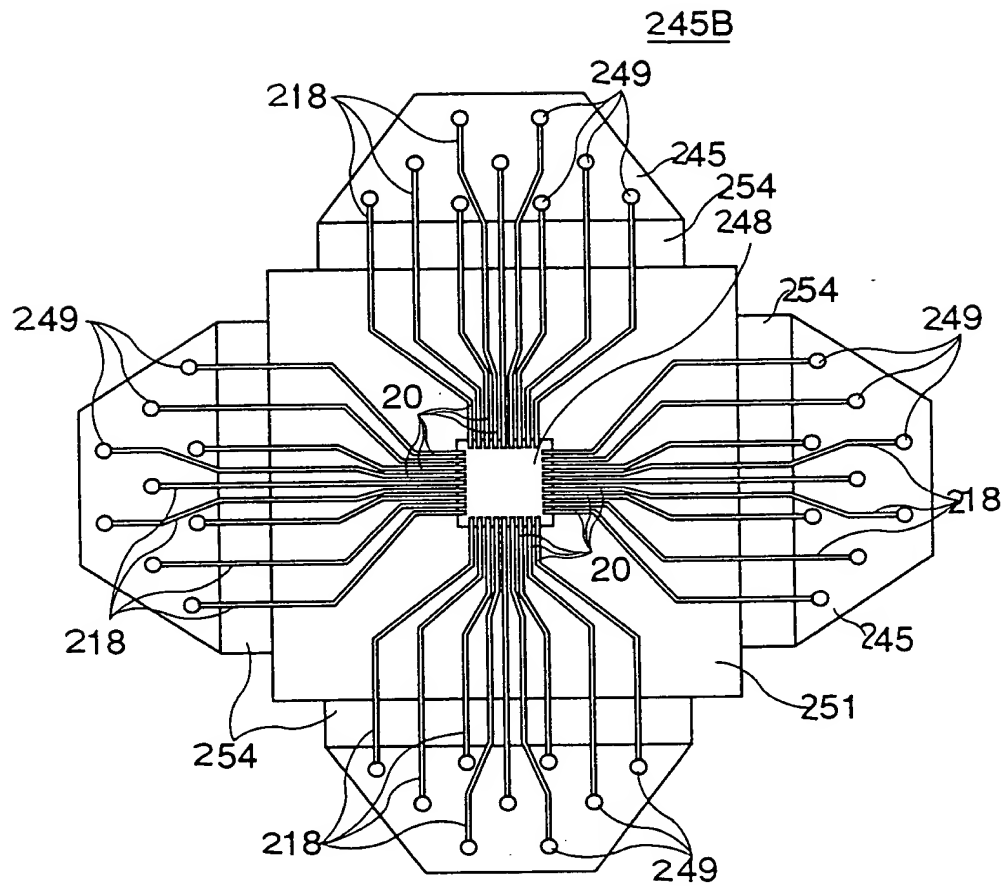


FIG. 105

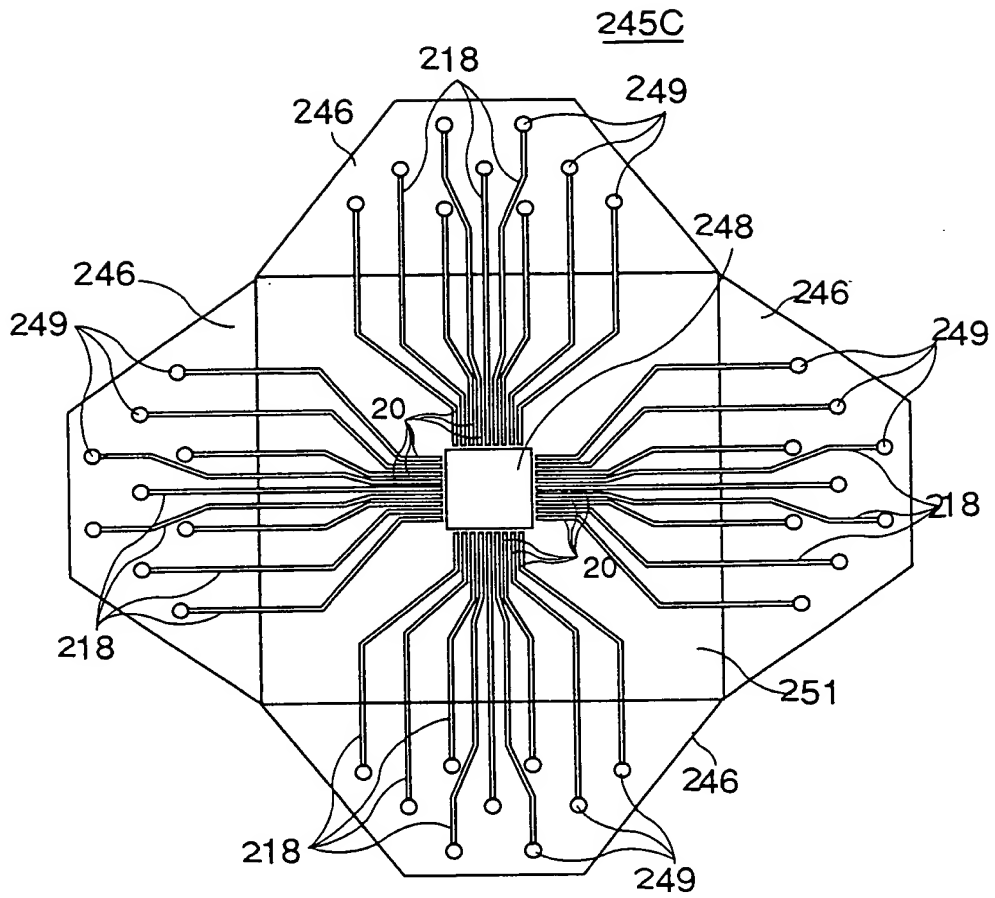


FIG. 106

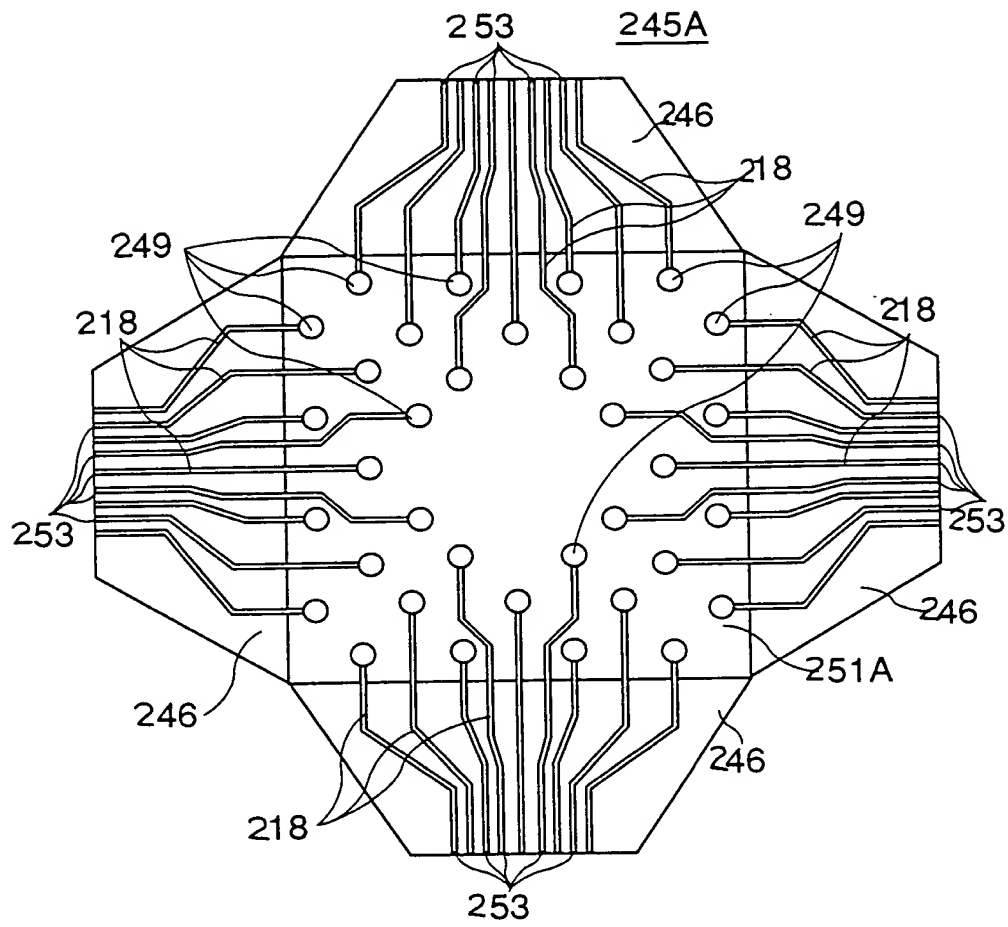


FIG. 107

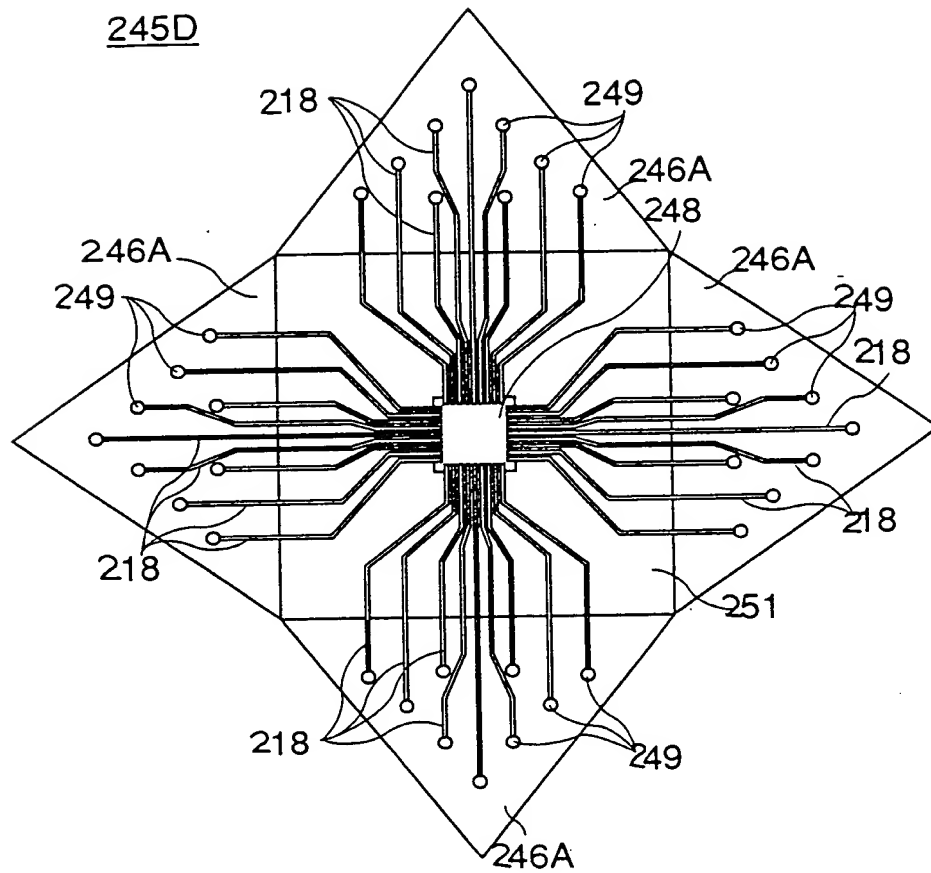


FIG. 108

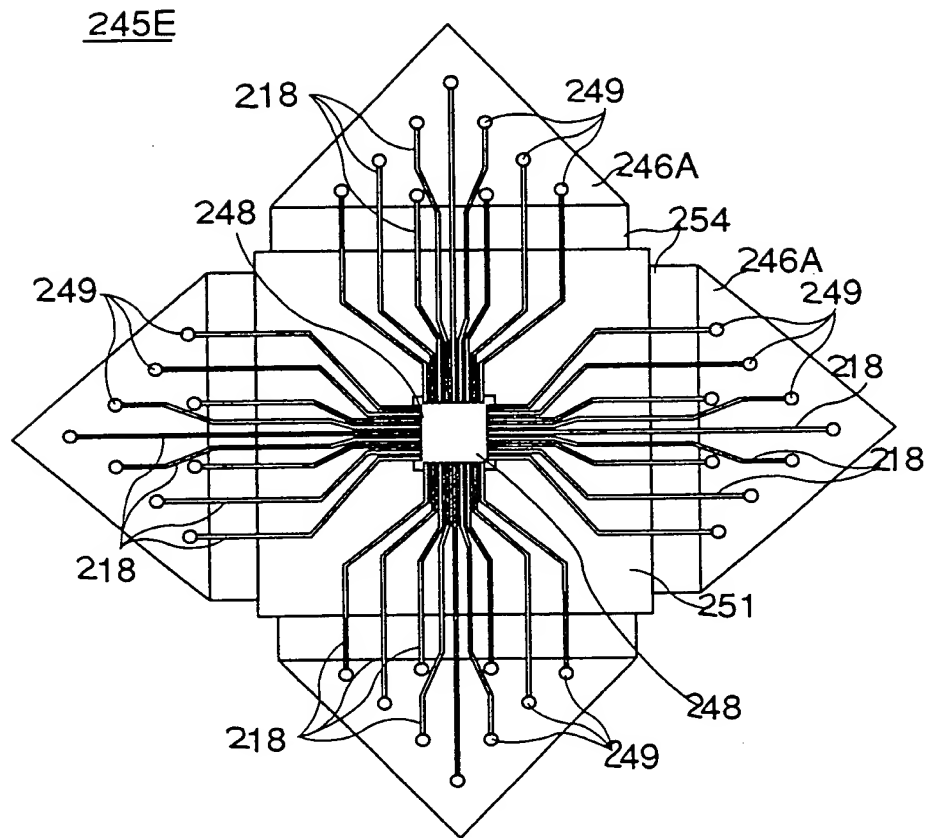


FIG. 109

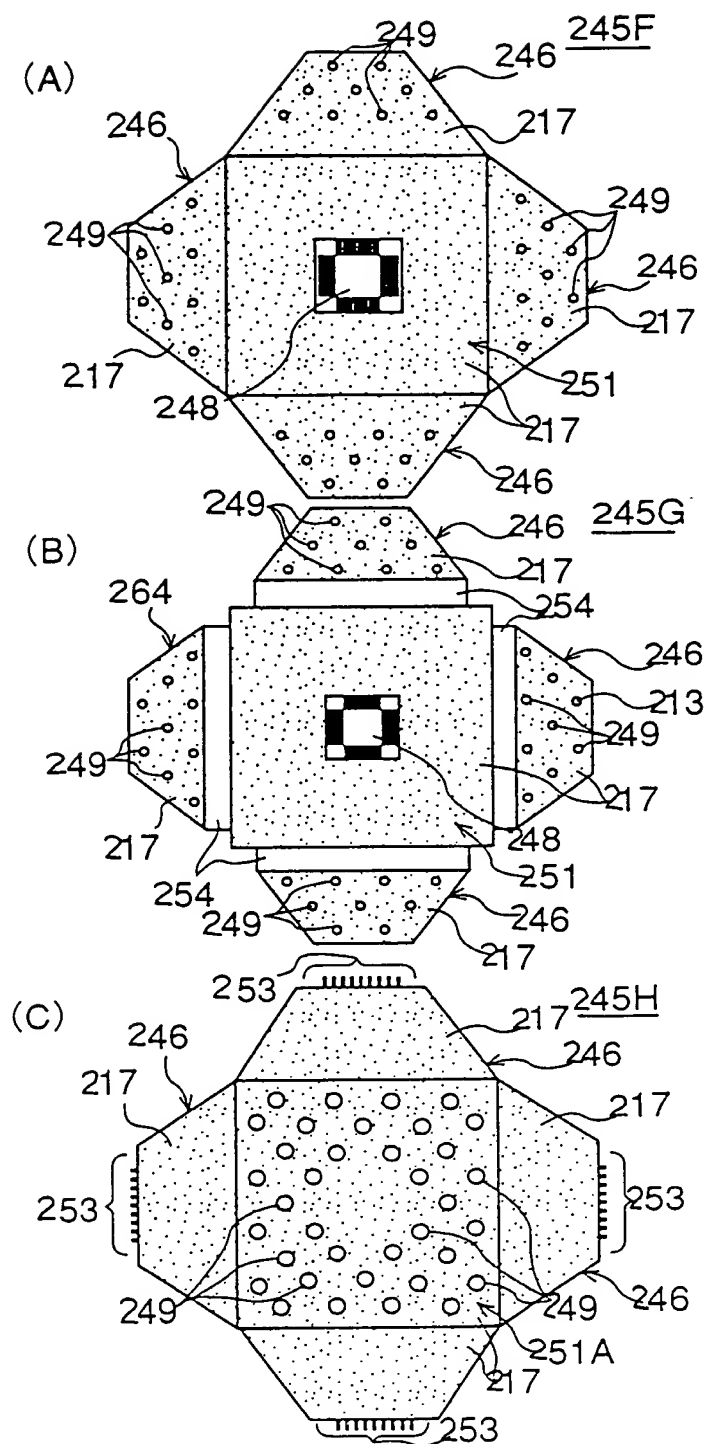


FIG. 110

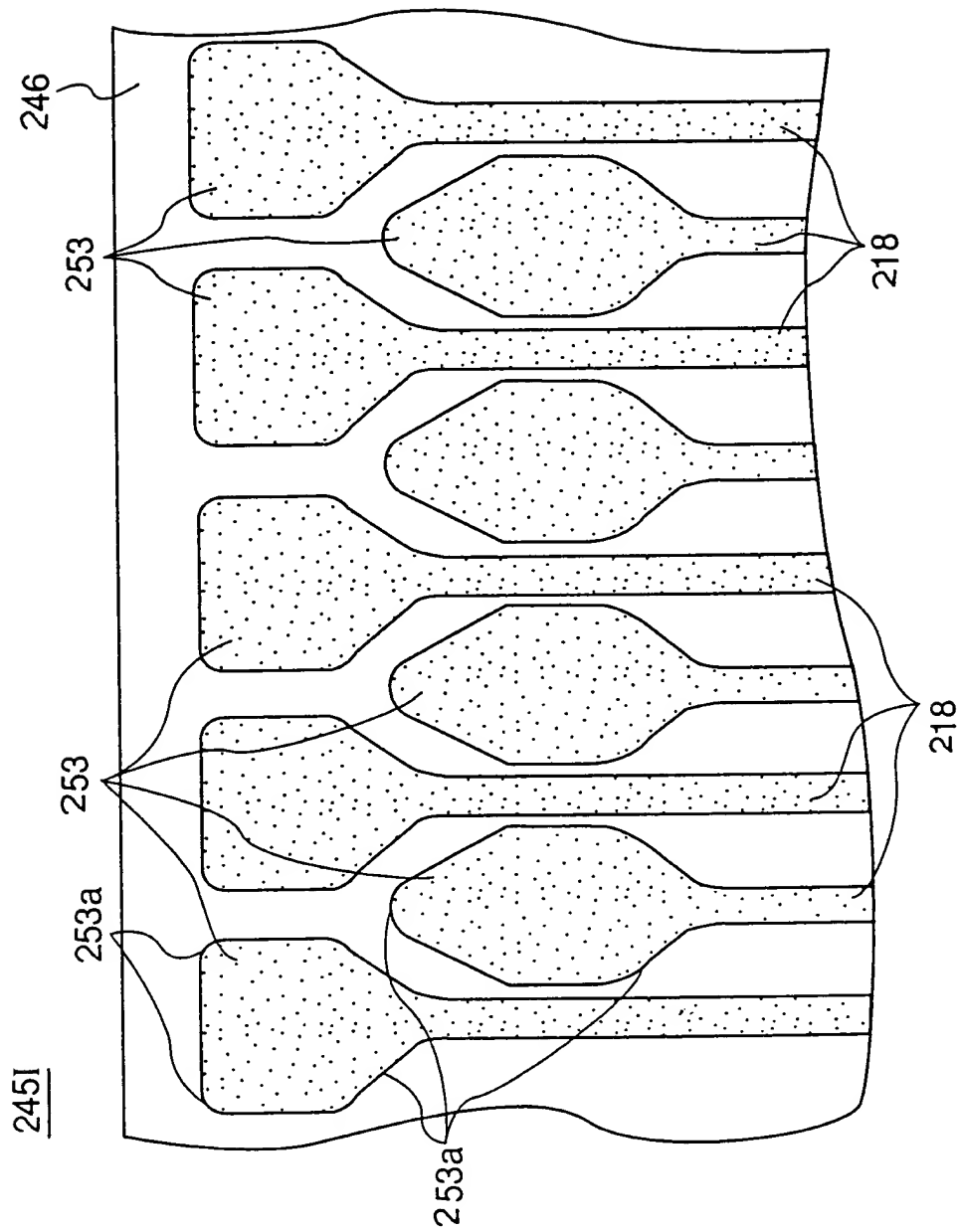


FIG. 111

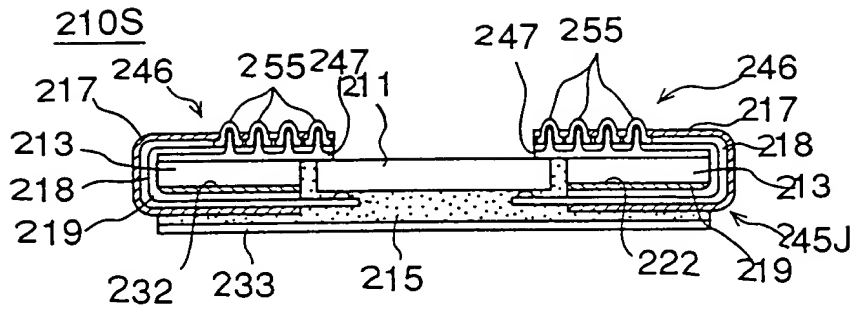




FIG. 113

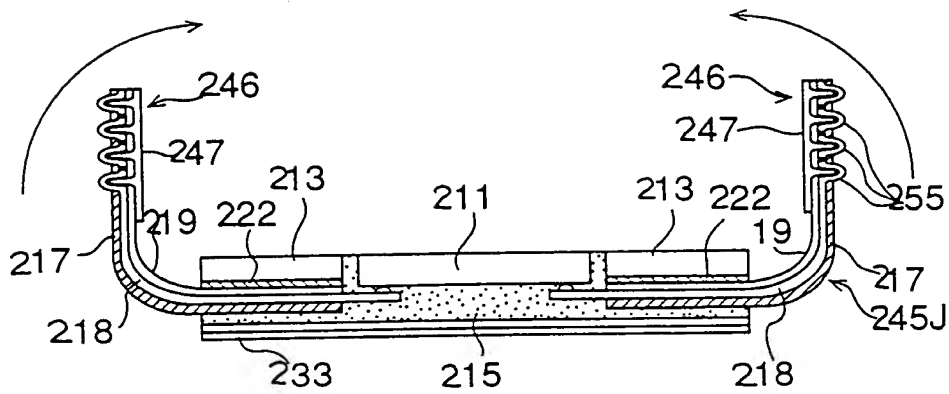


FIG. 114

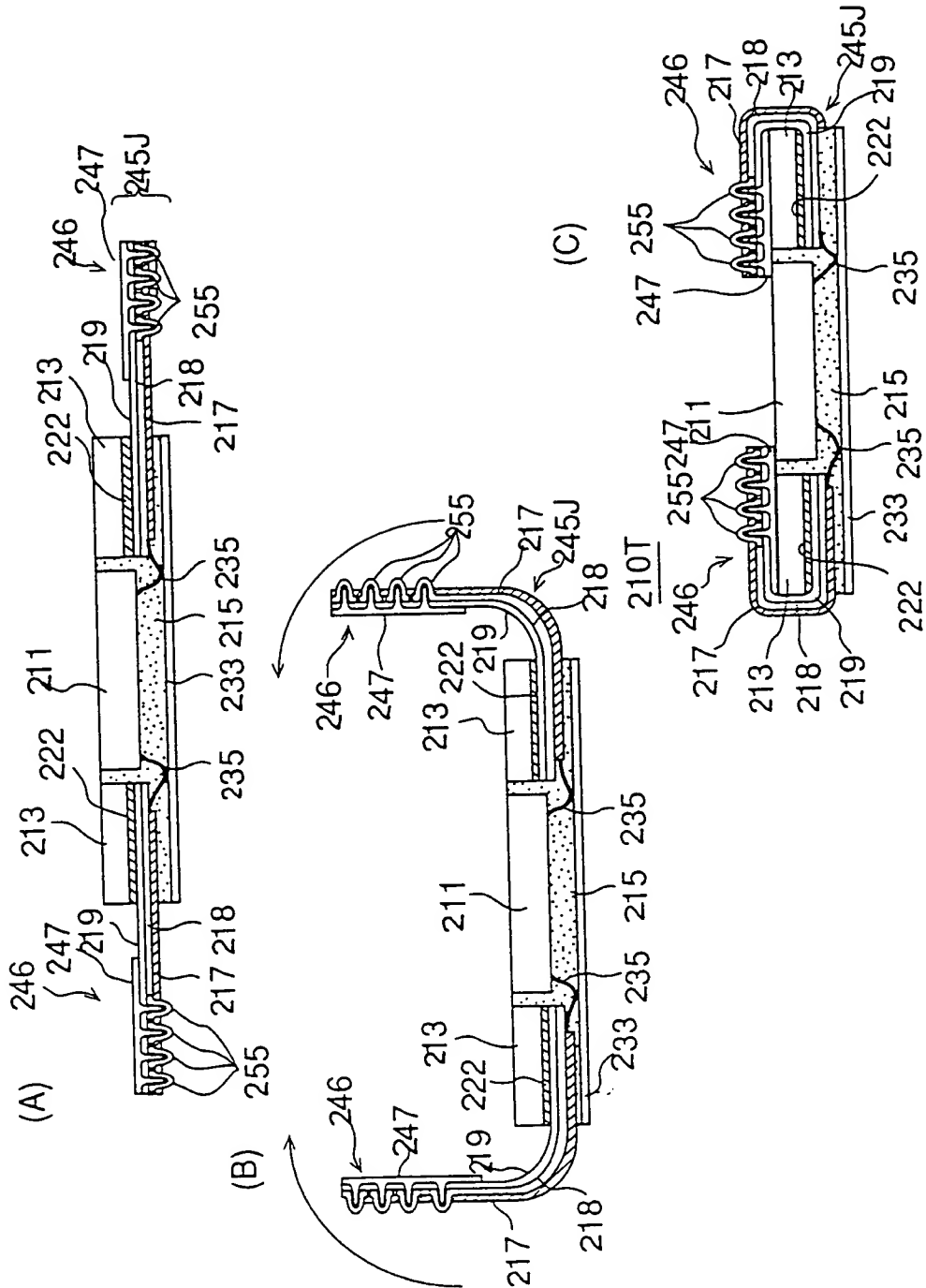


FIG. 115

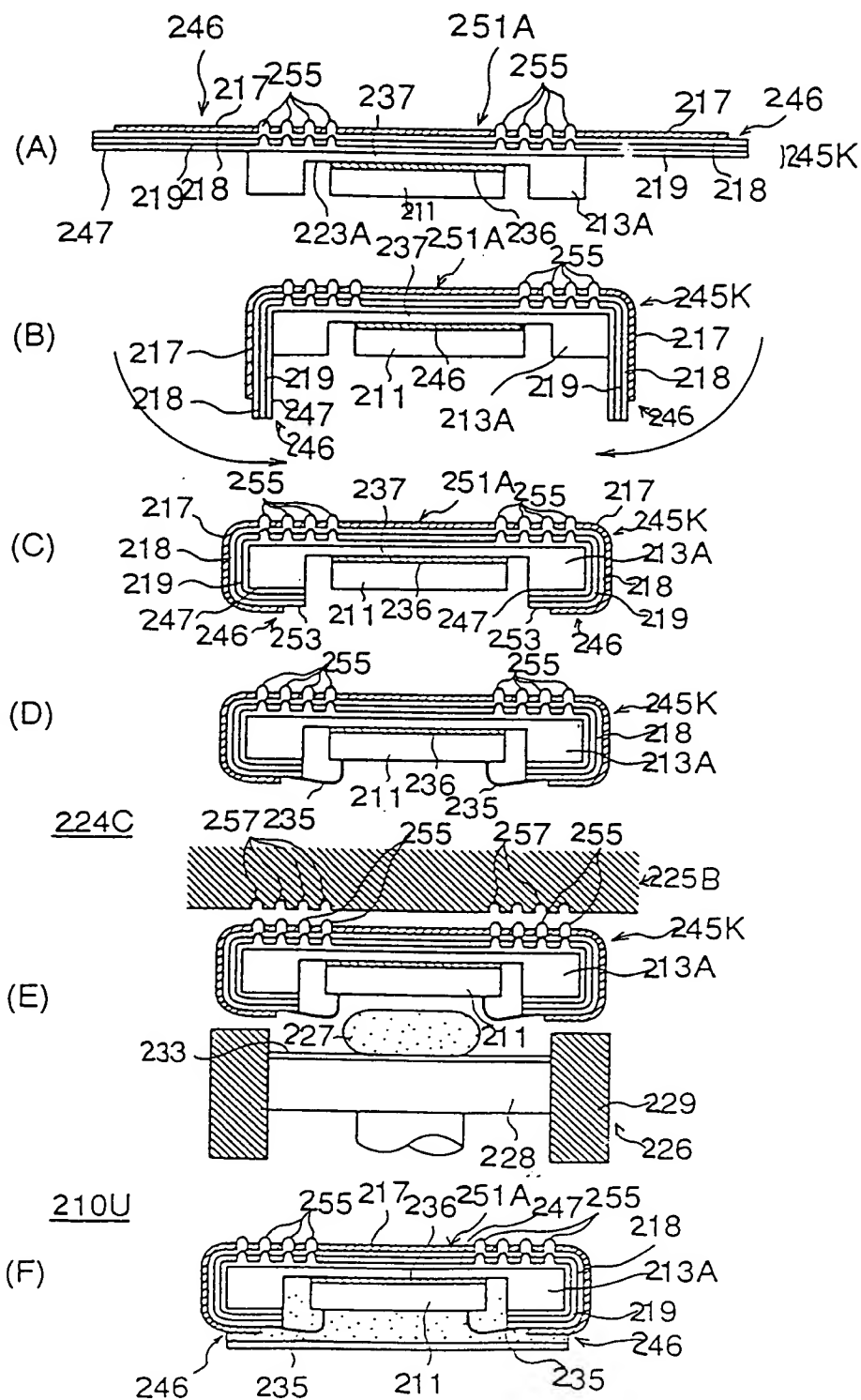


FIG. 116

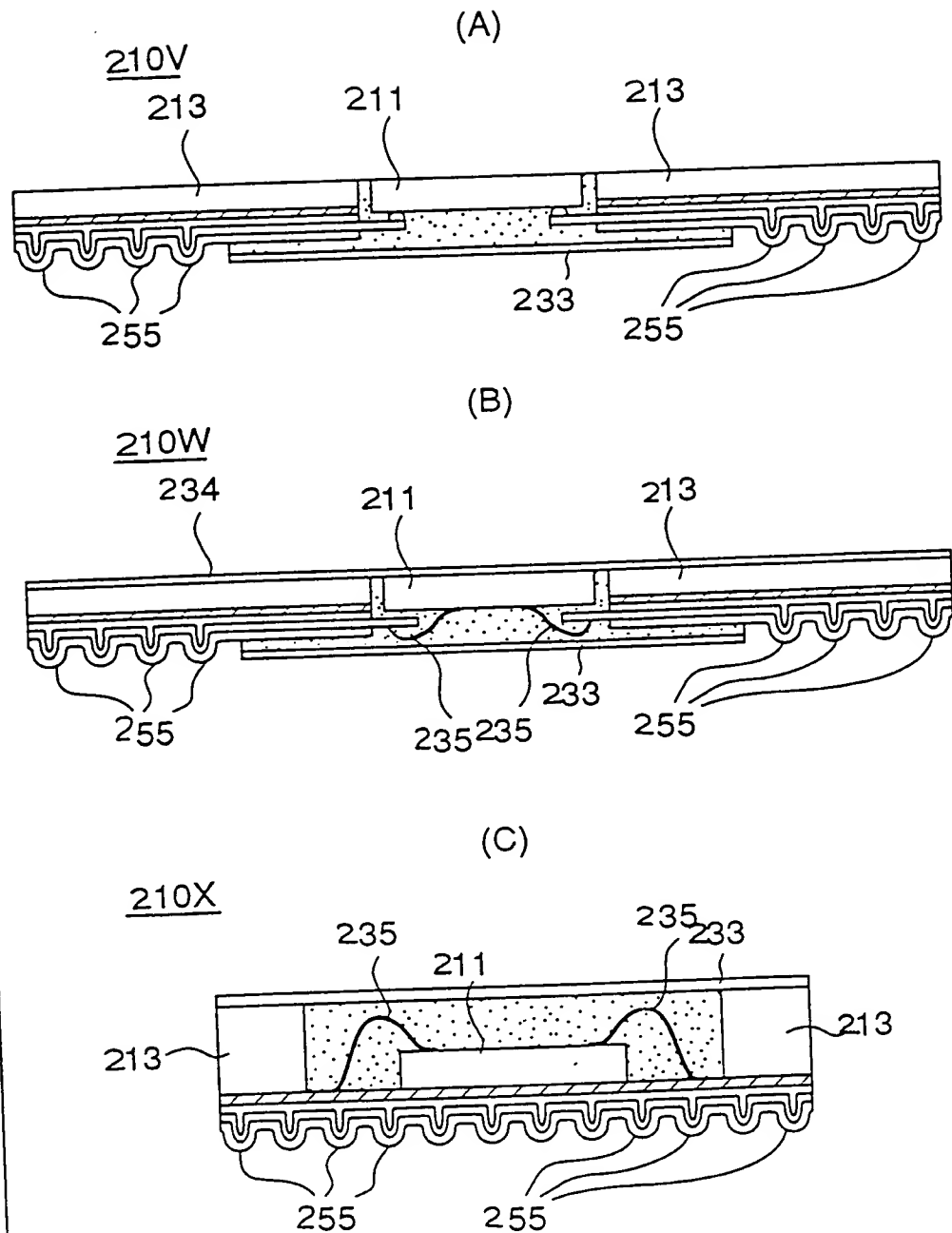


FIG. 117

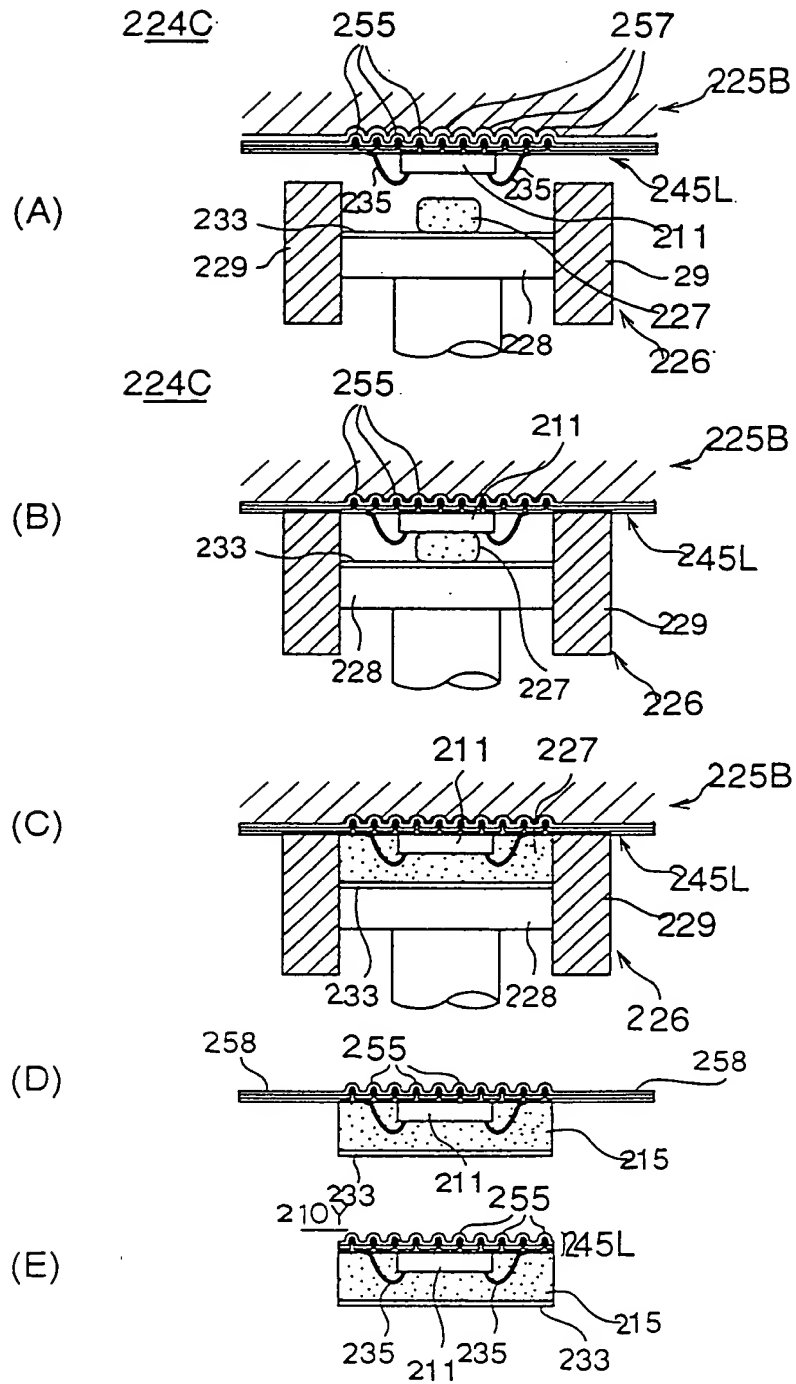


FIG. 118

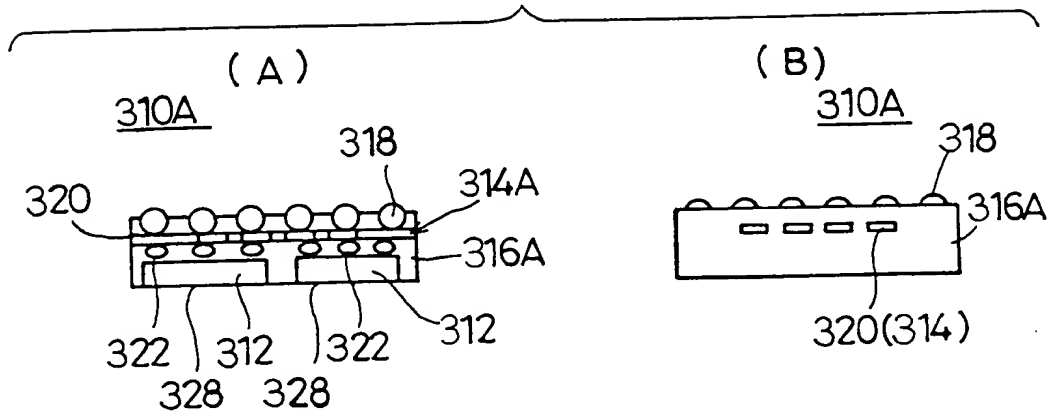


FIG. 119

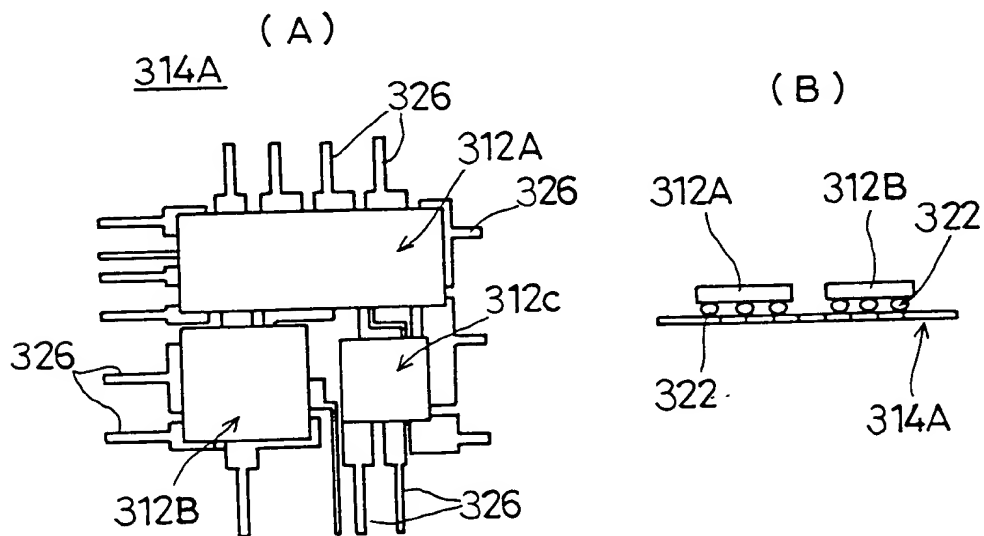


FIG. 120

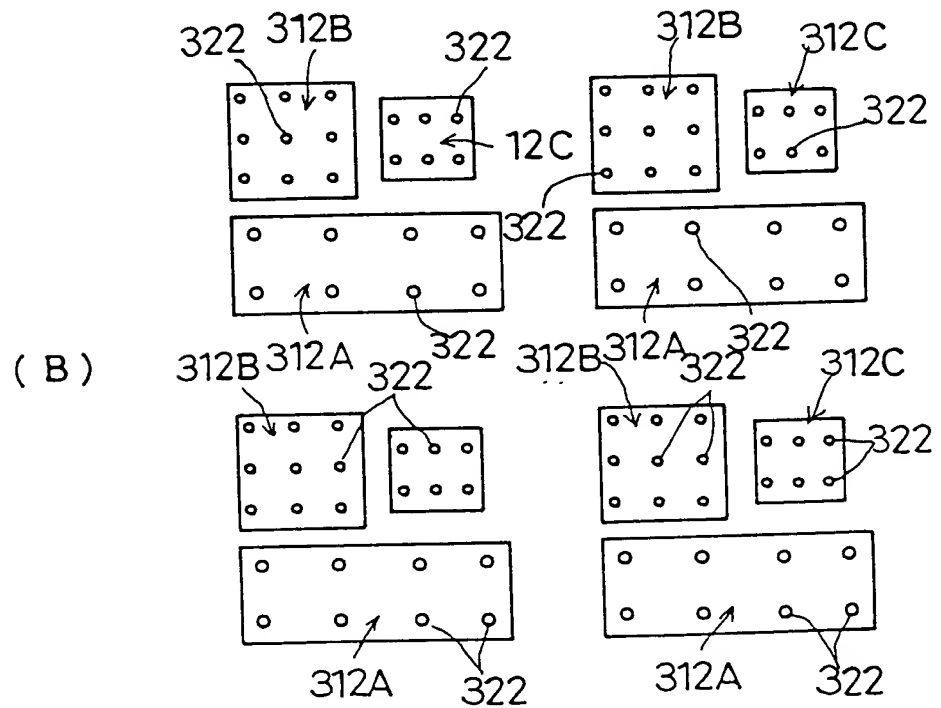
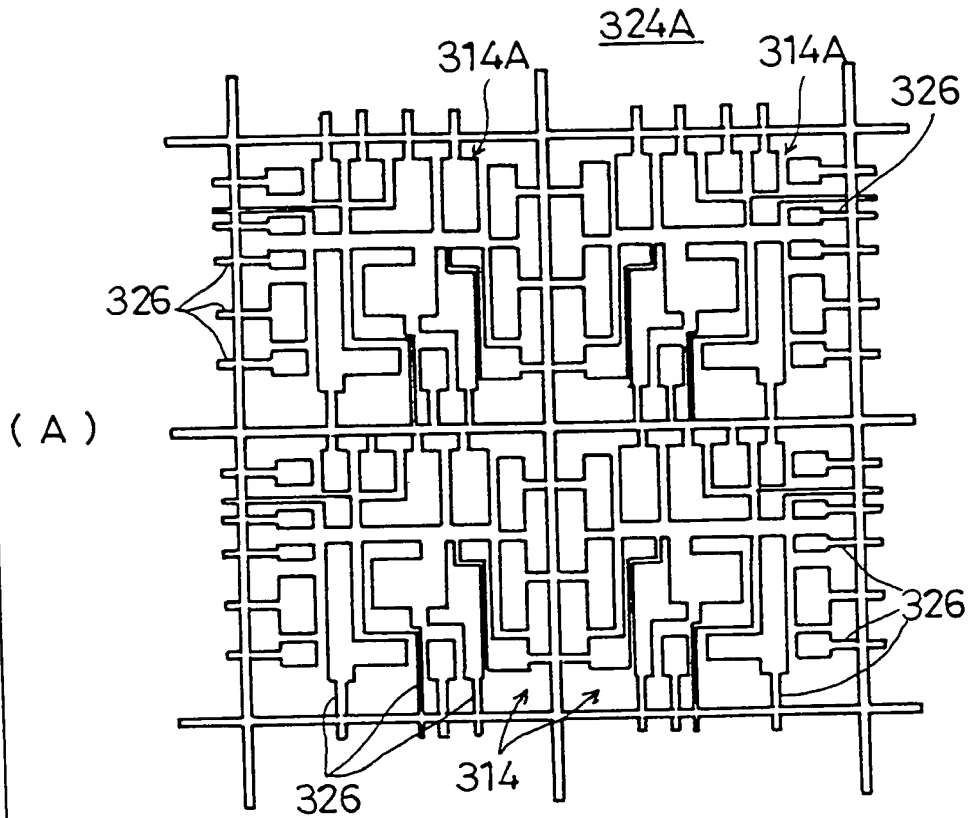


FIG. 121

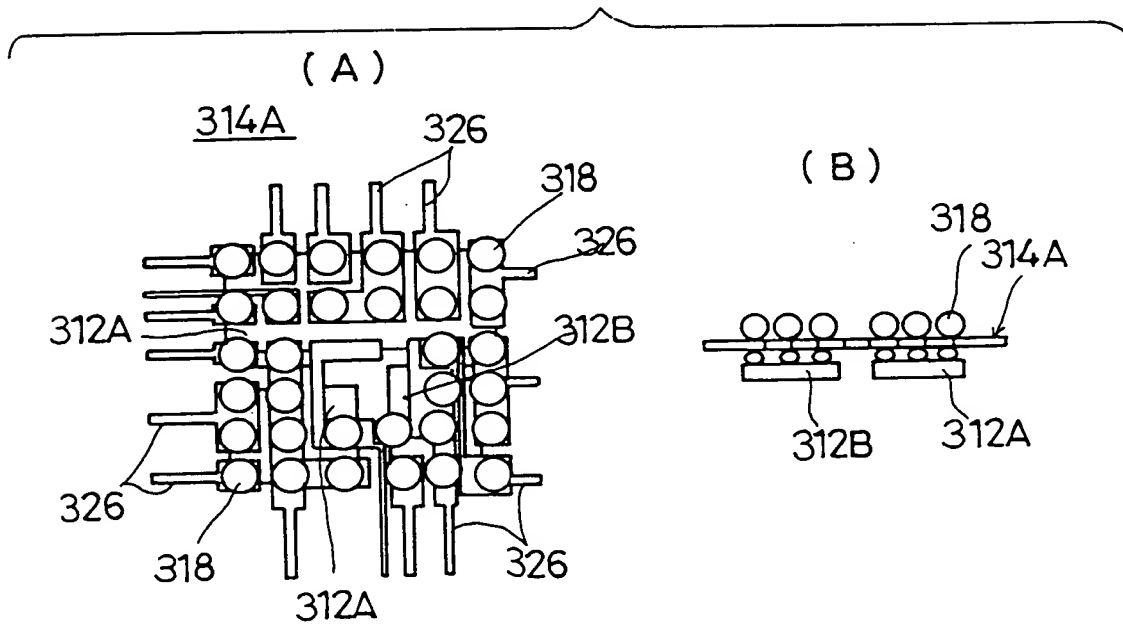


FIG. 122

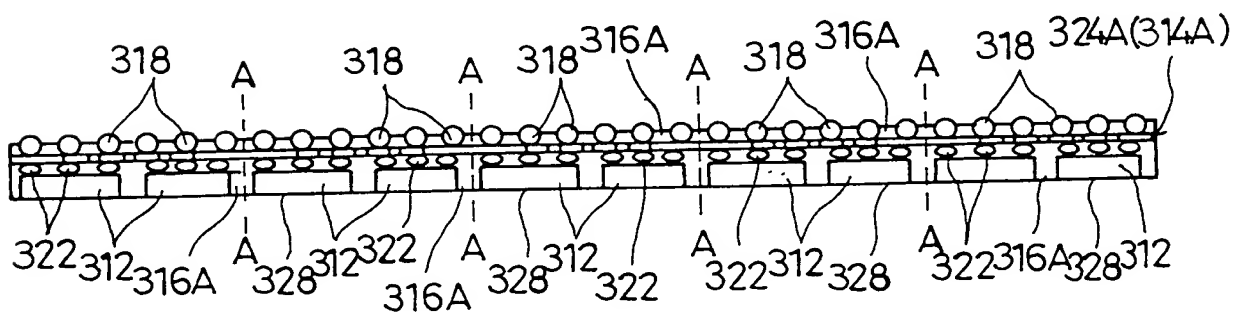


FIG. 123

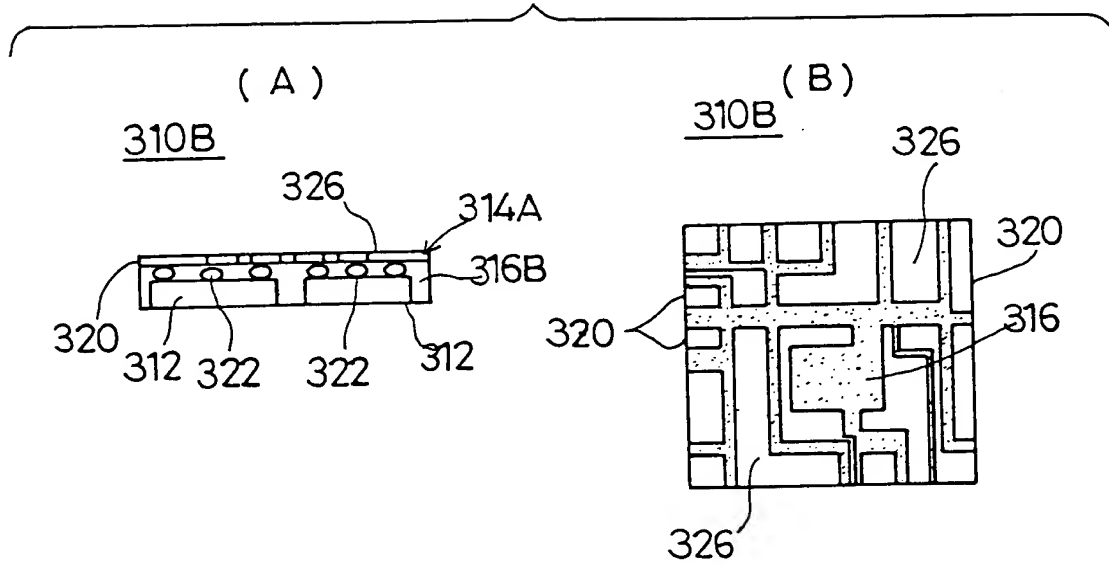


FIG. 124

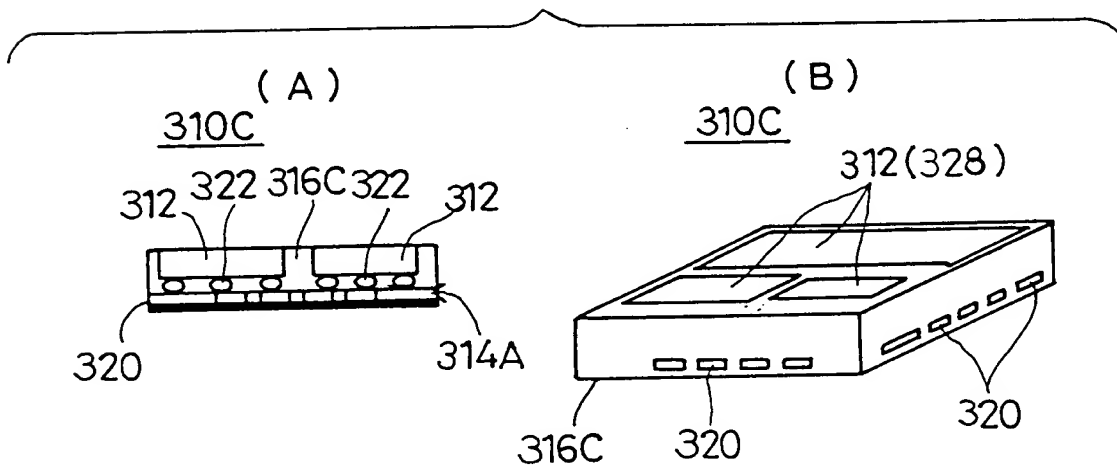


FIG. 125

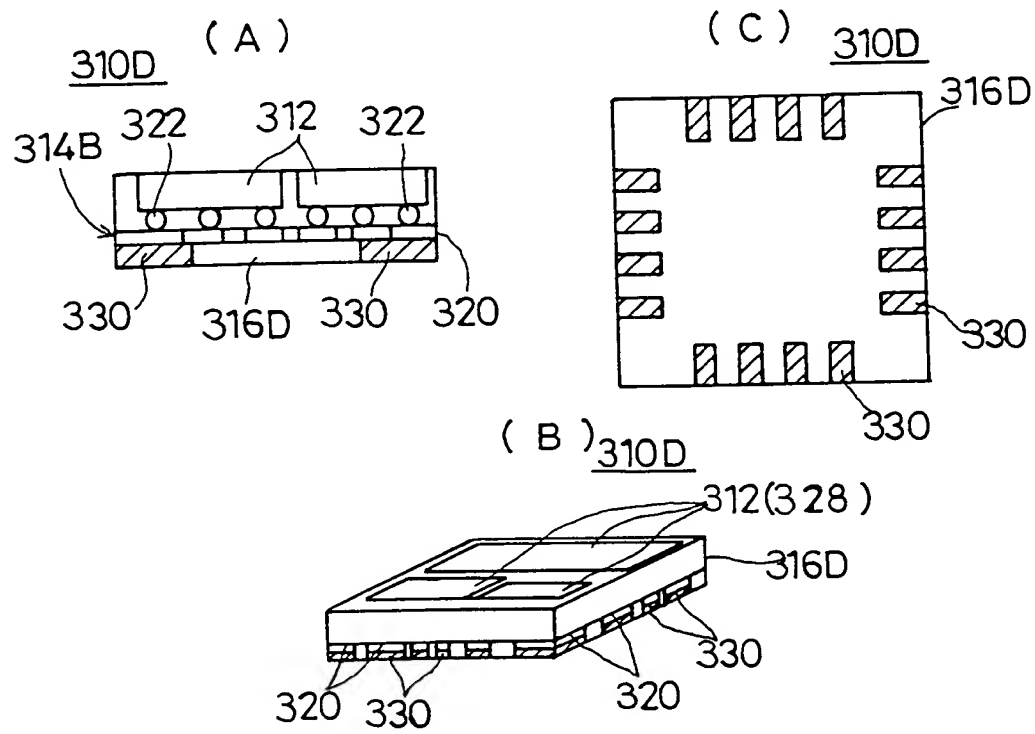
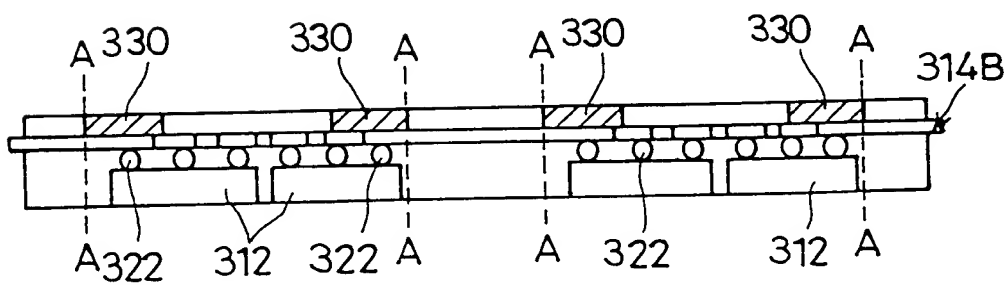


FIG. 126



324B

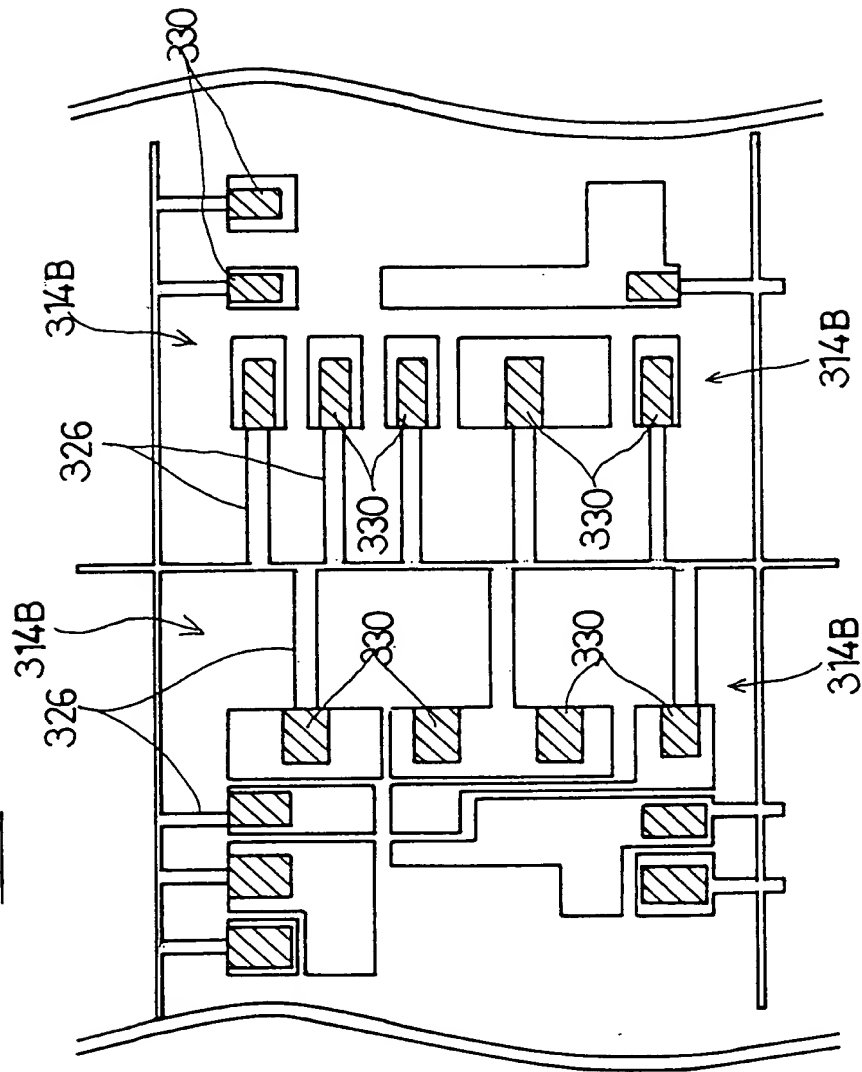


FIG. 128

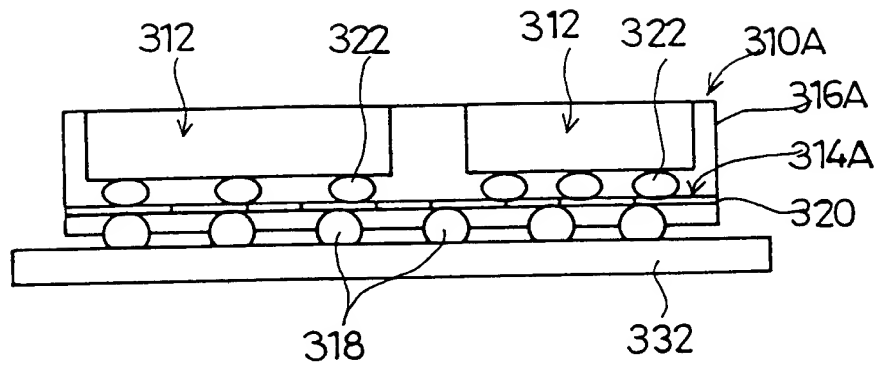


FIG. 129

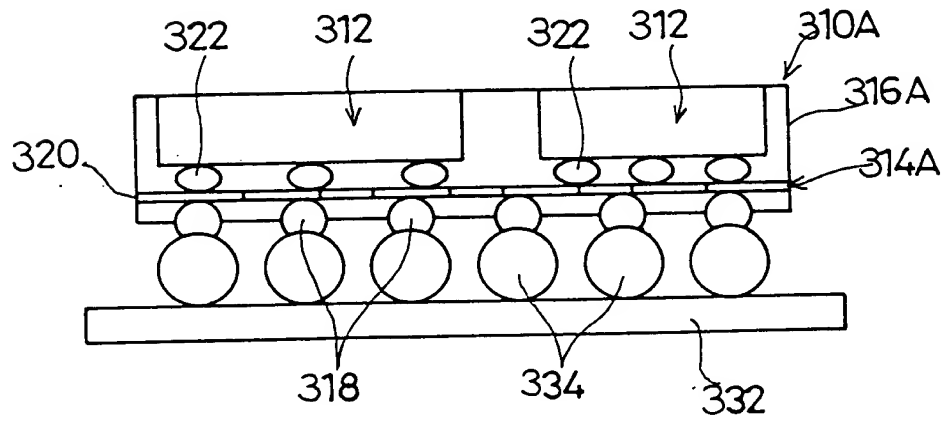


FIG. 130

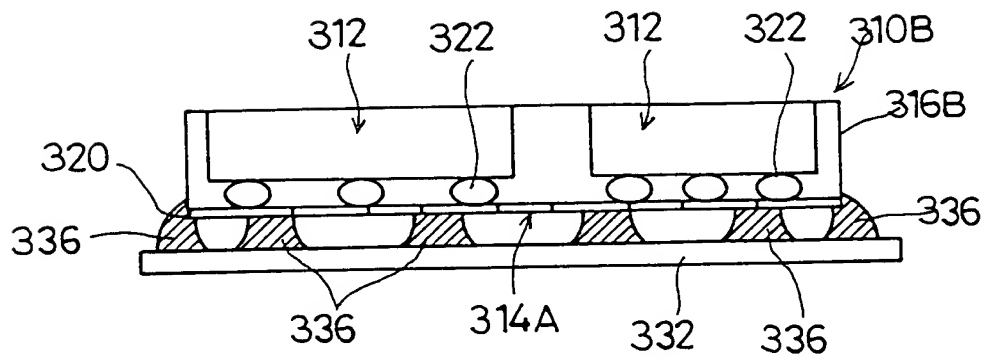


FIG. 131

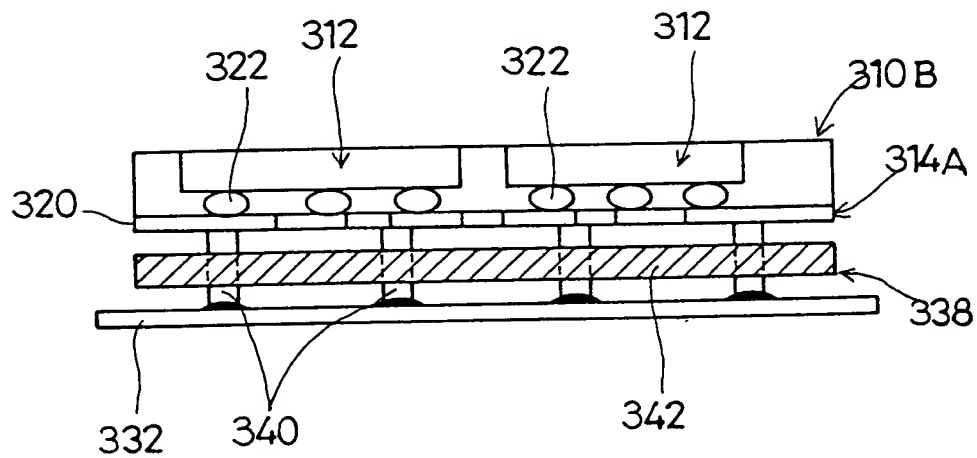


FIG. 132

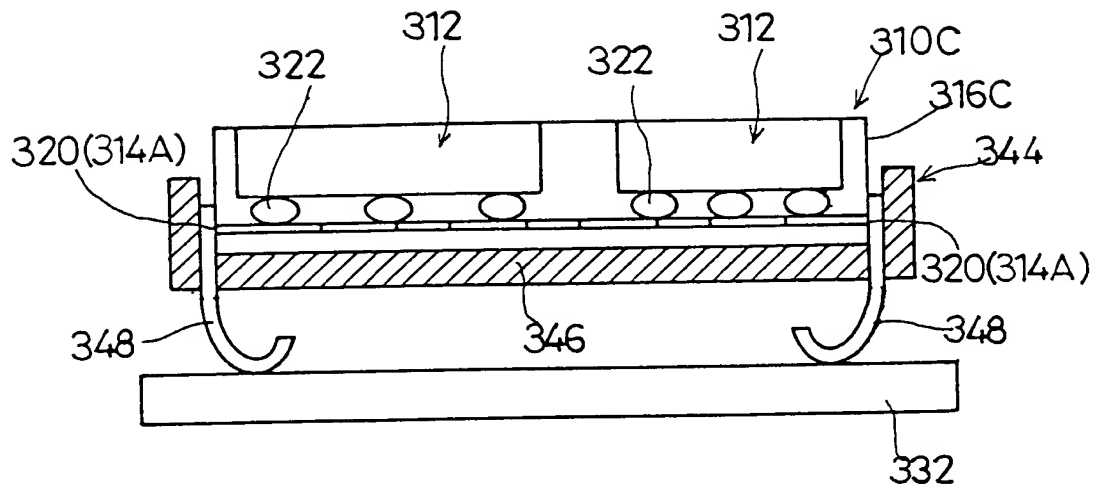


FIG. 133

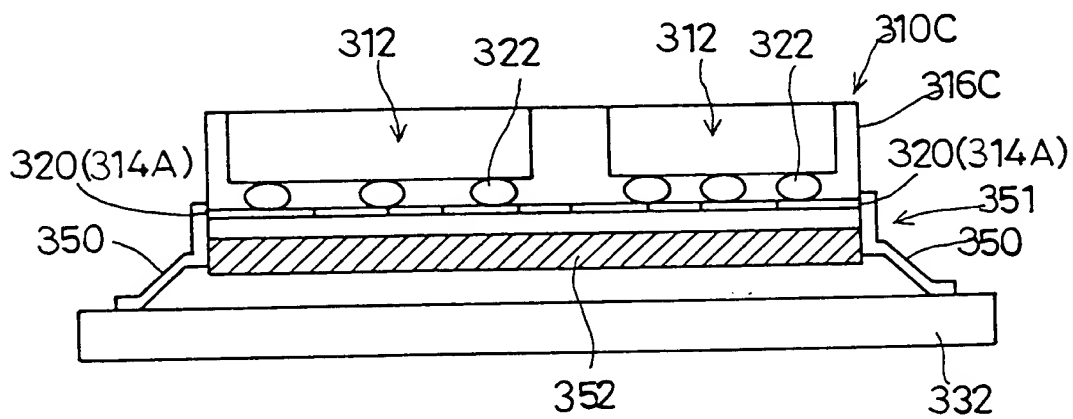


FIG. 134

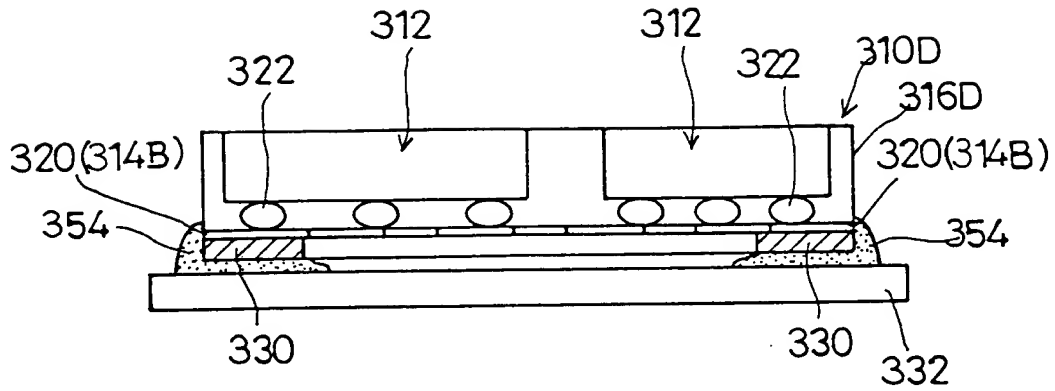


FIG. 135

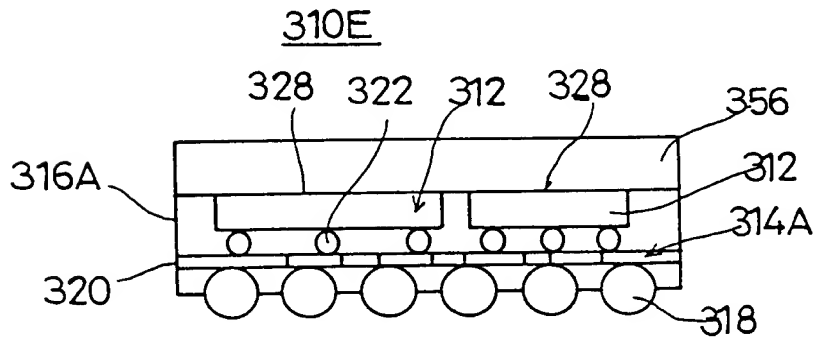


FIG. 136

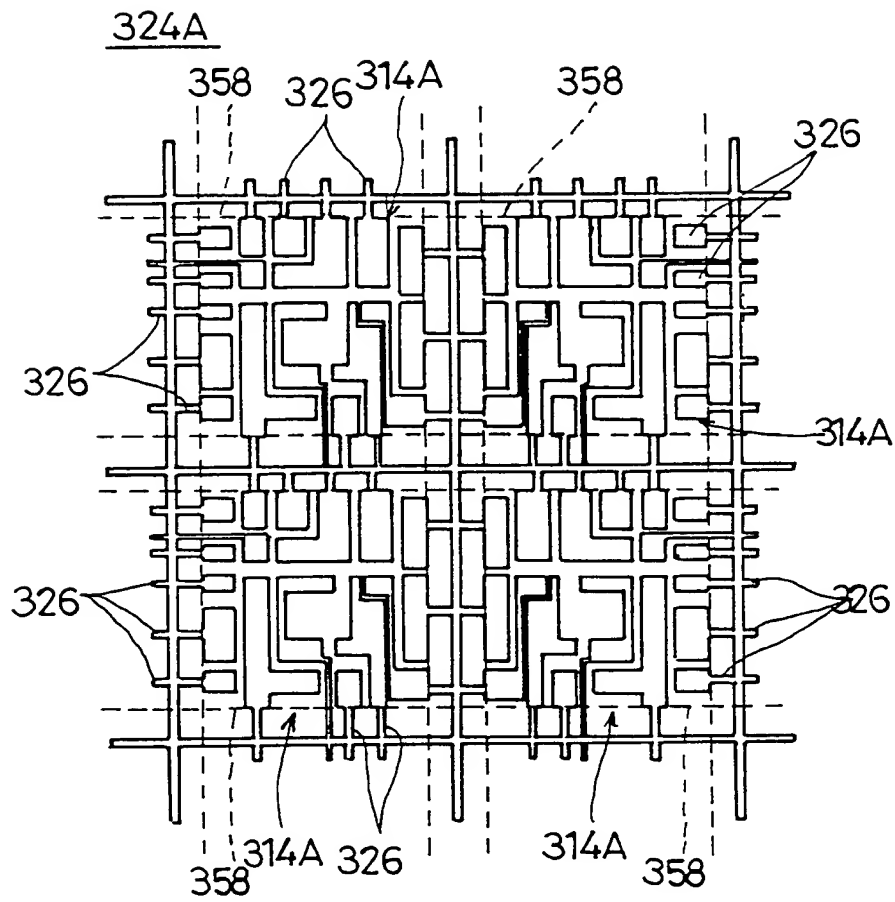


FIG. 137

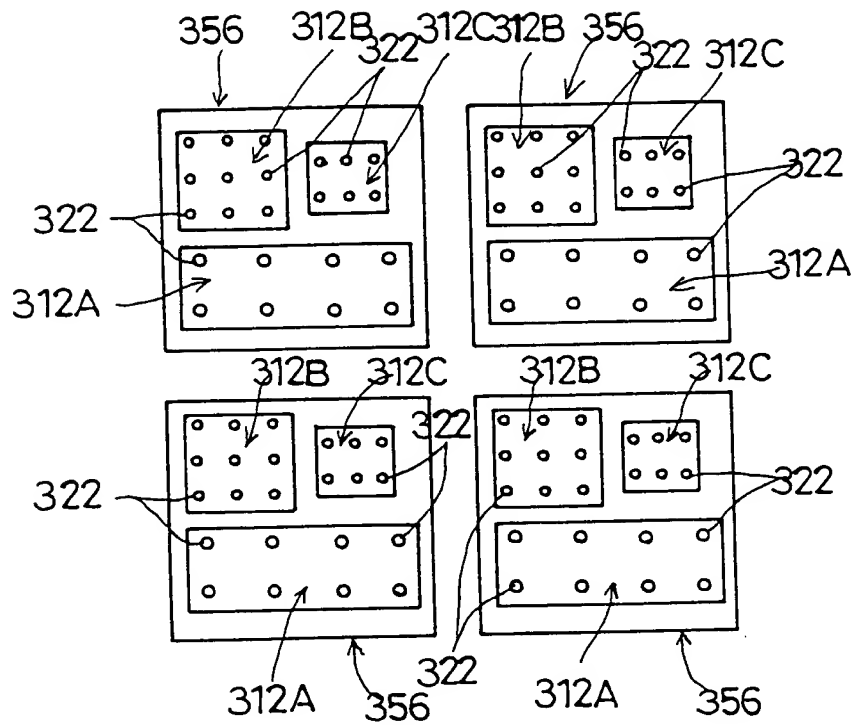


FIG. 138

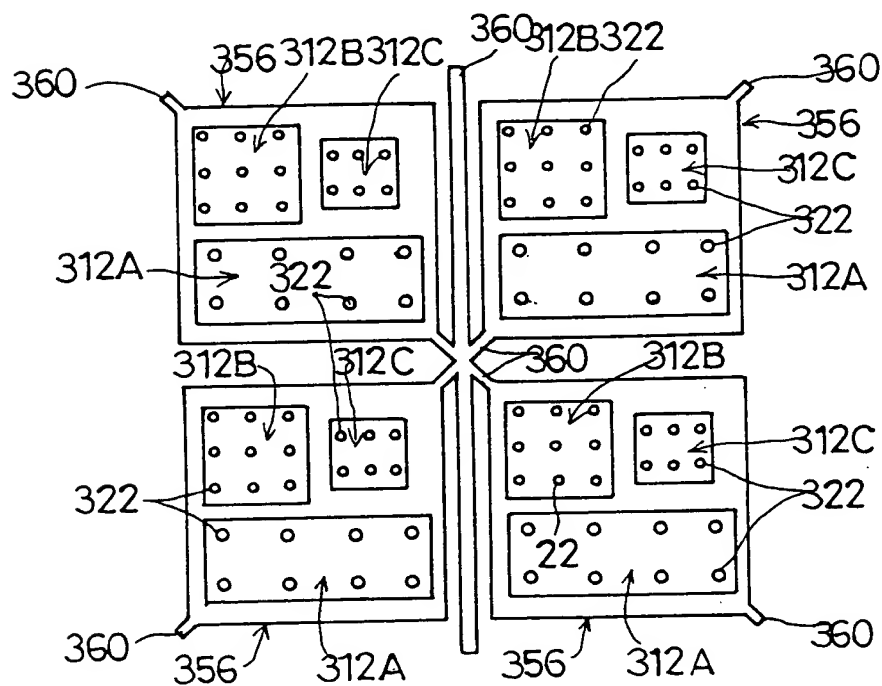


FIG. 139

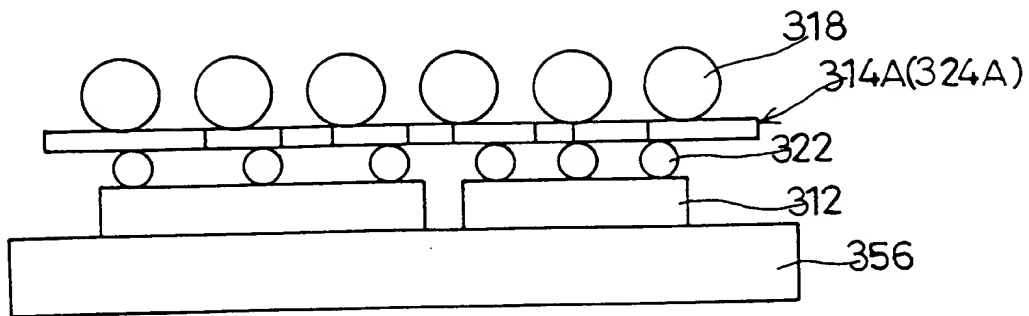


FIG. 140

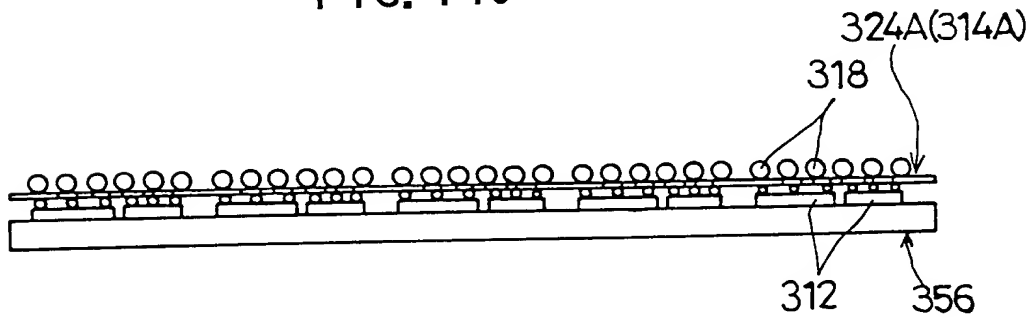


FIG. 141



FIG. 142

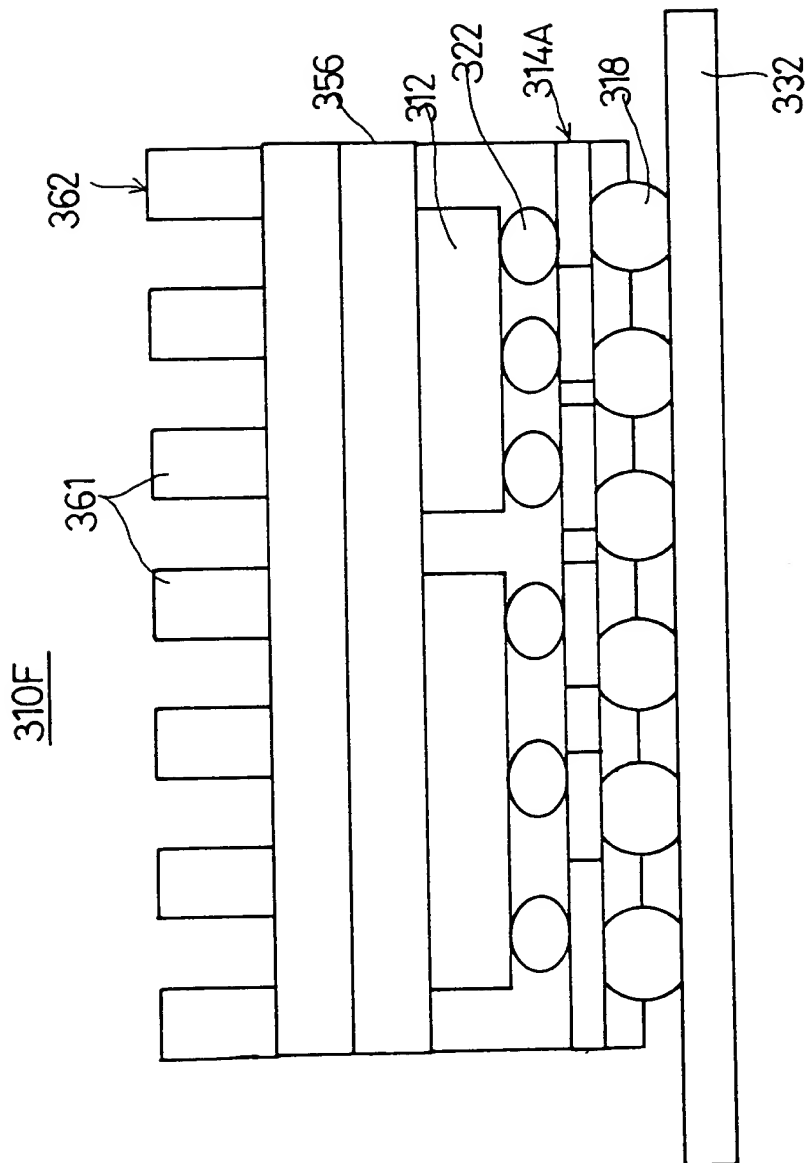


FIG. 143

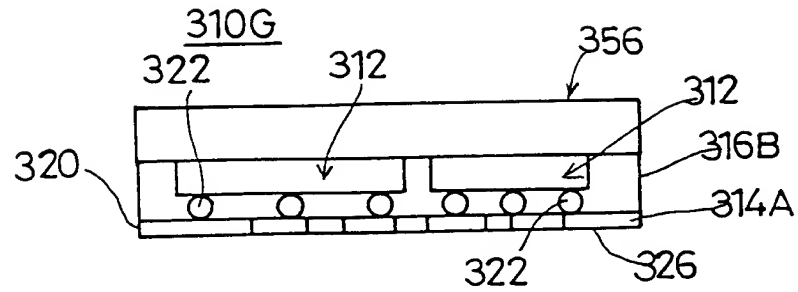


FIG. 144

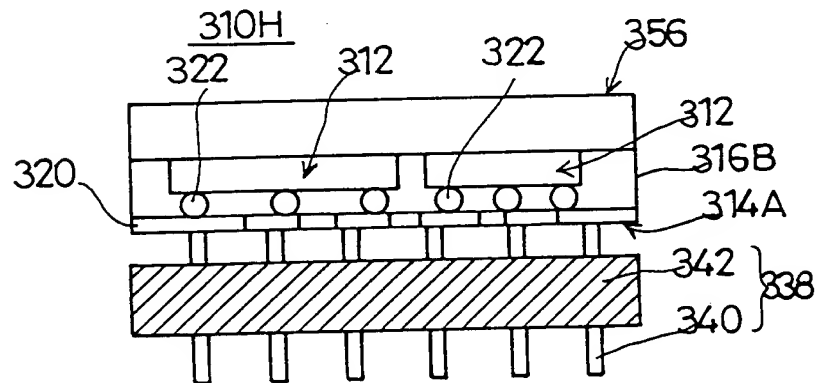


FIG. 145

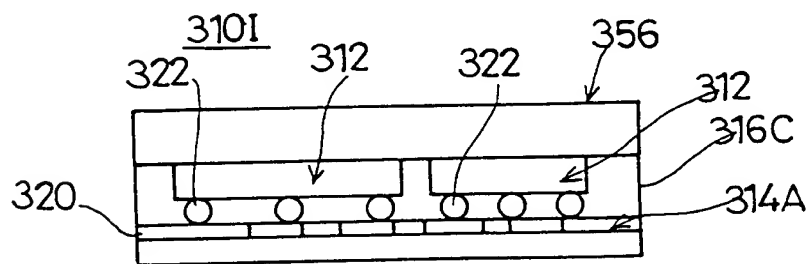


FIG. 146

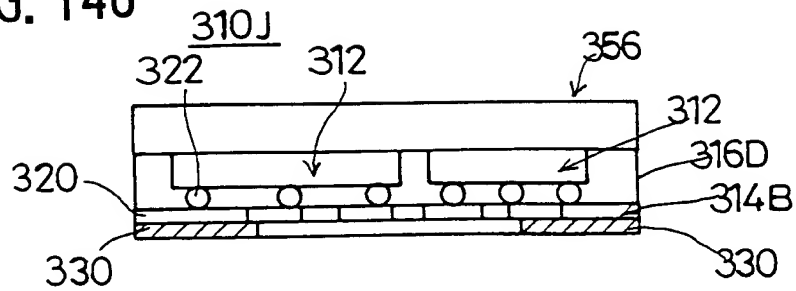


FIG. 147

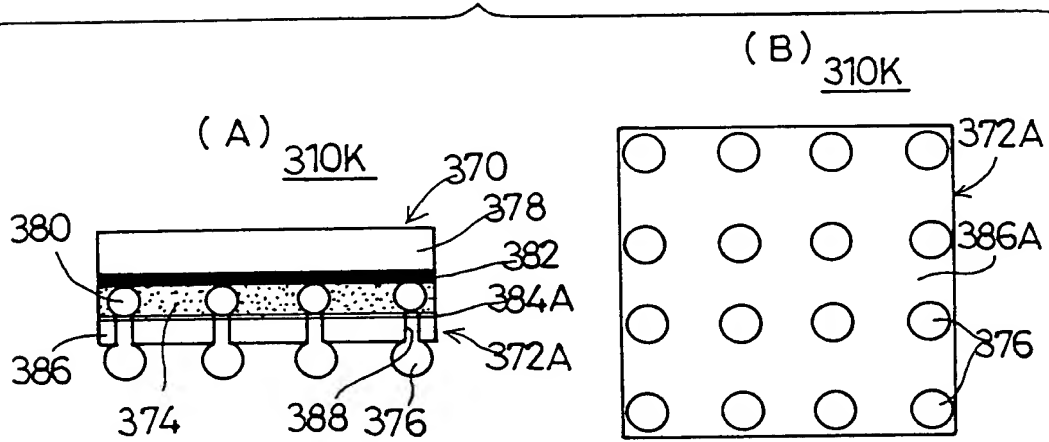


FIG. 148

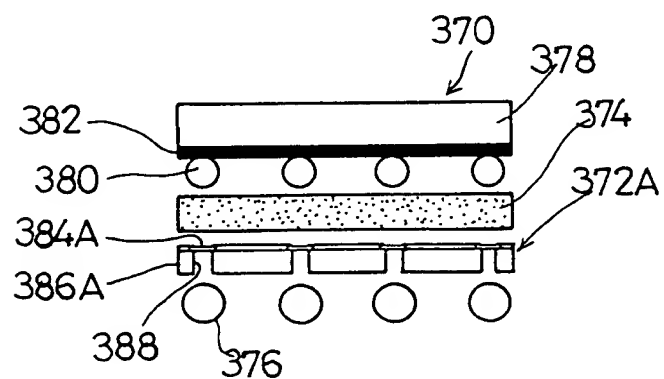


FIG. 149

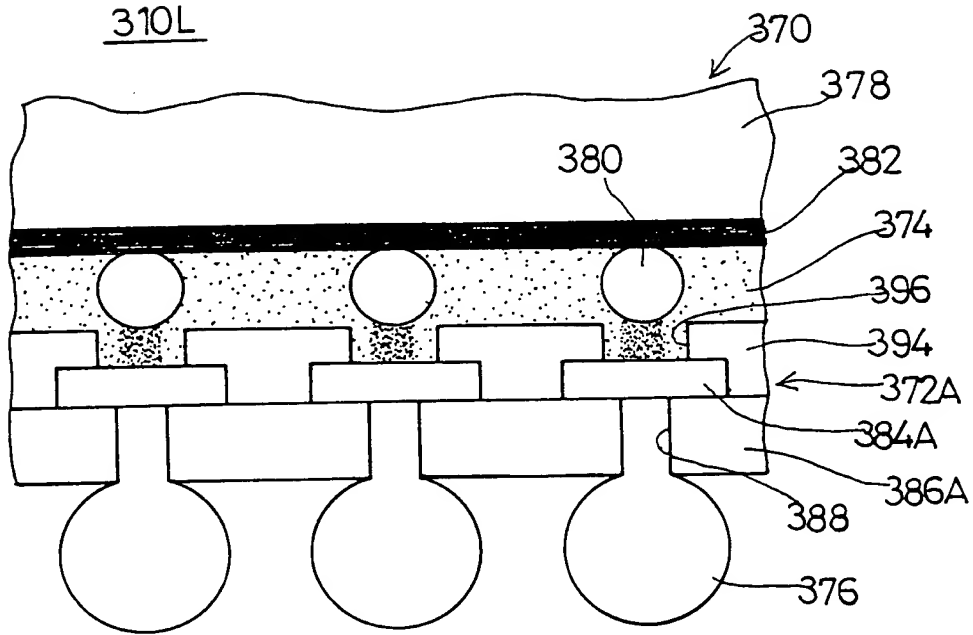


FIG. 150

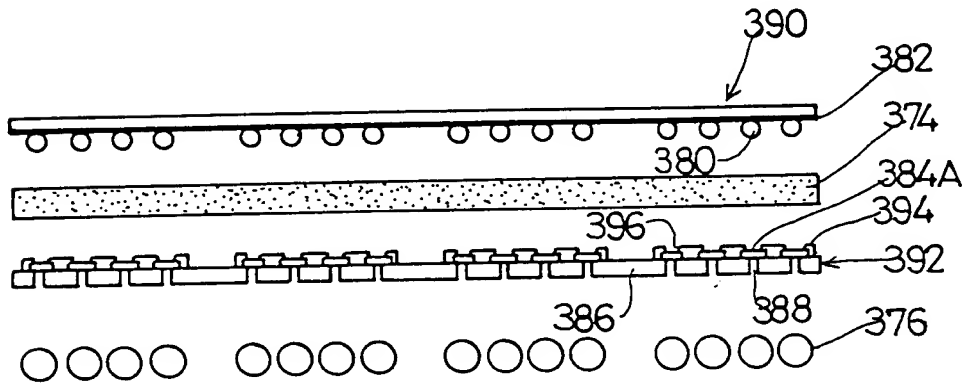


FIG. 151

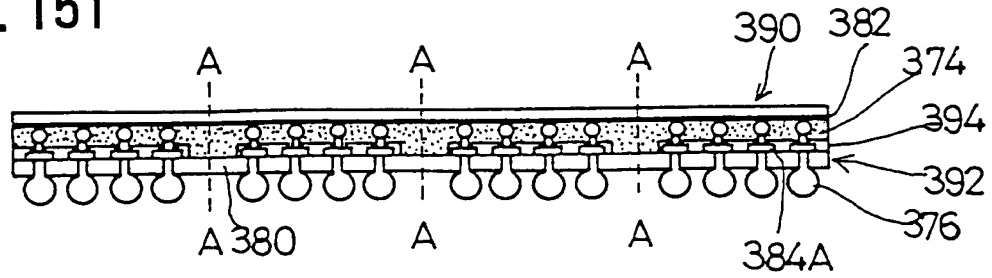


FIG. 152

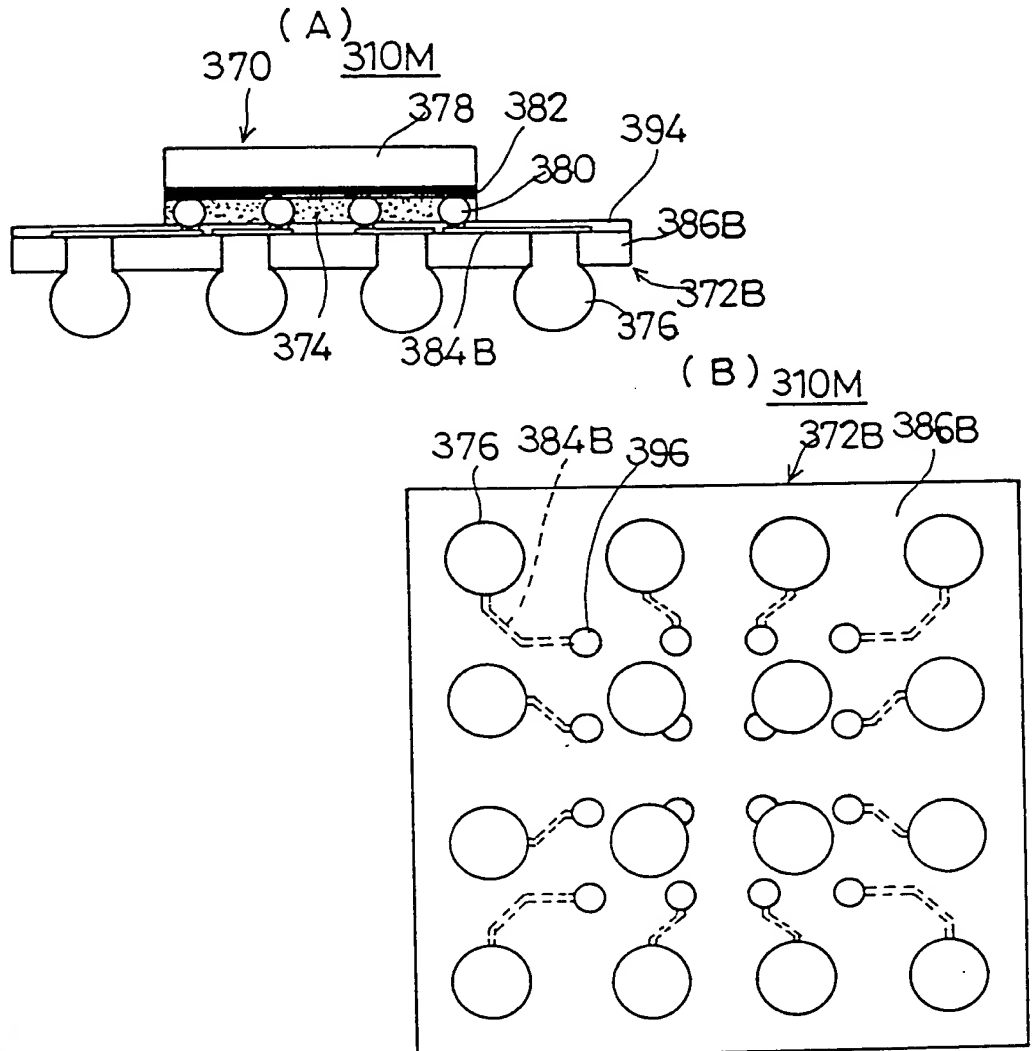


FIG. 153

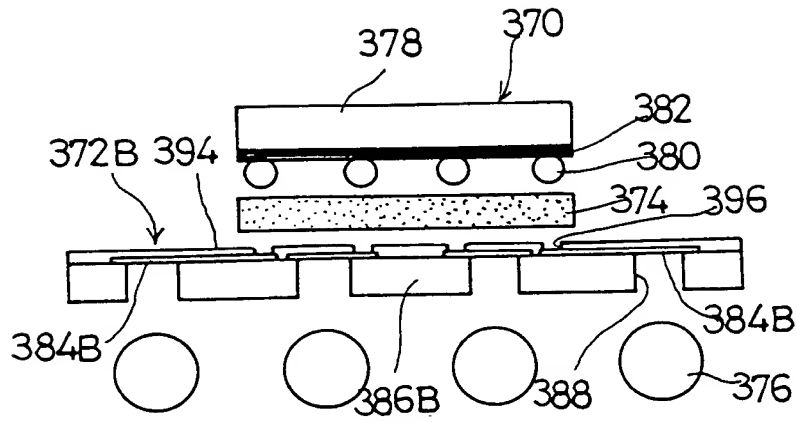


FIG. 154

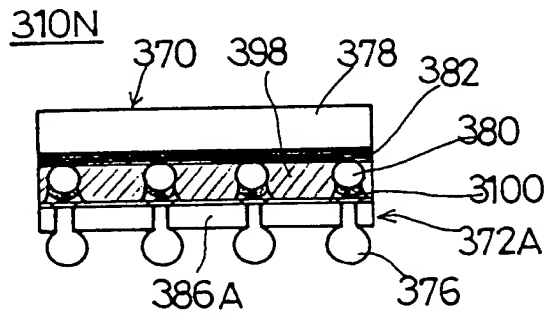
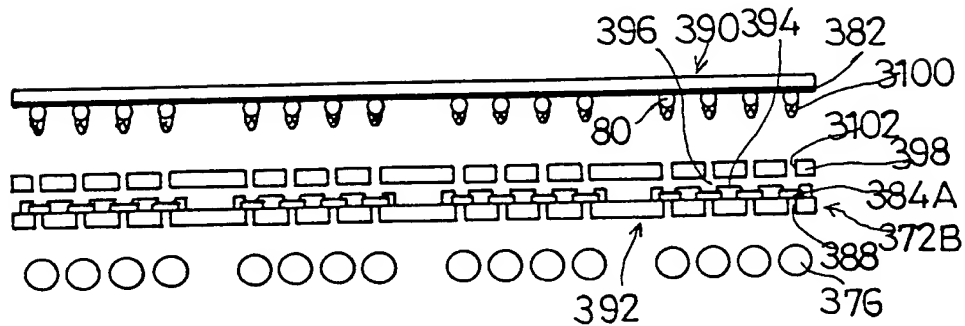


FIG. 155



A cross-sectional view of a multi-layered structure. It features a top layer (380) with a series of circular elements (376) arranged in a row. Below these elements is a layer (372B) containing a series of rectangular blocks (384A). The entire structure is supported by a base layer (390). Vertical dashed lines labeled 'A' indicate cross-sections at different points along the length of the structure. Other labels include 398 and 3100.

A cross-sectional view of a semiconductor device 370. The device consists of a substrate 376 with a layer 386A on top. A series of rectangular blocks 372A are arranged in a row on layer 386A. Above these blocks is a layer 388. A layer 398 is positioned above layer 388, with small rectangular features 384A located between the blocks 372A. A layer 3100 is above layer 398, and a layer 382 is above layer 3100. Four circular features 380 are located on the top surface of layer 382. A layer 378 is on the top surface of the substrate 376.

FIG. 159

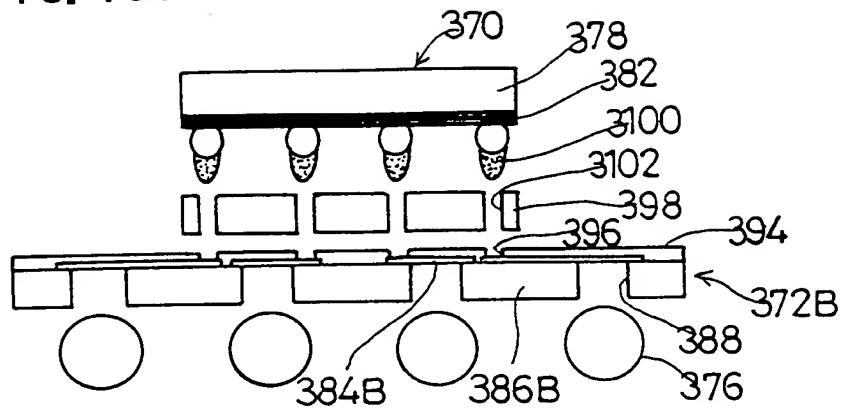


FIG. 160

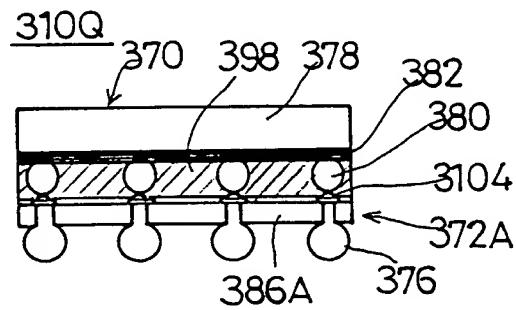


FIG. 161

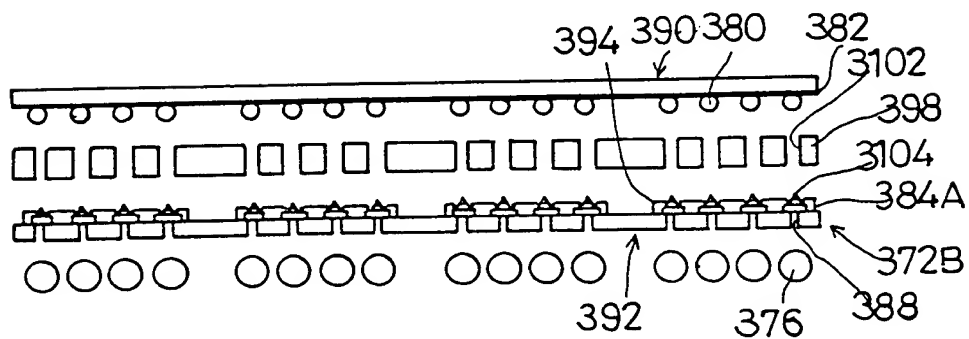


FIG. 162

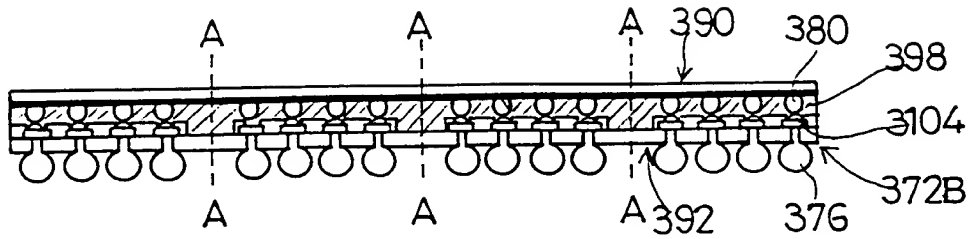


FIG. 163

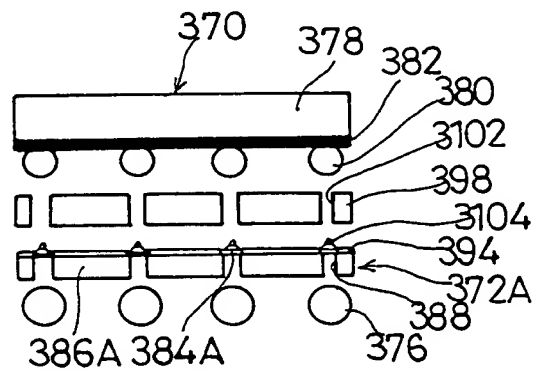


FIG. 164

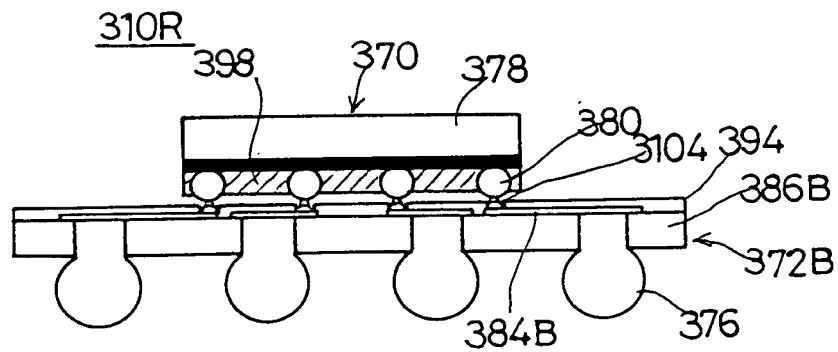


FIG. 165

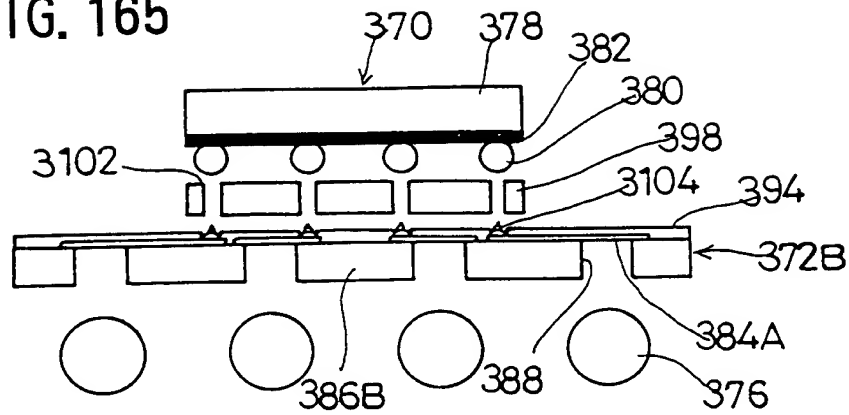


FIG. 166

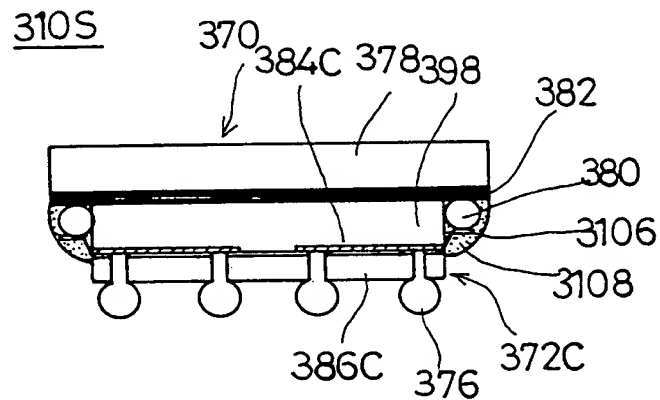


FIG. 167

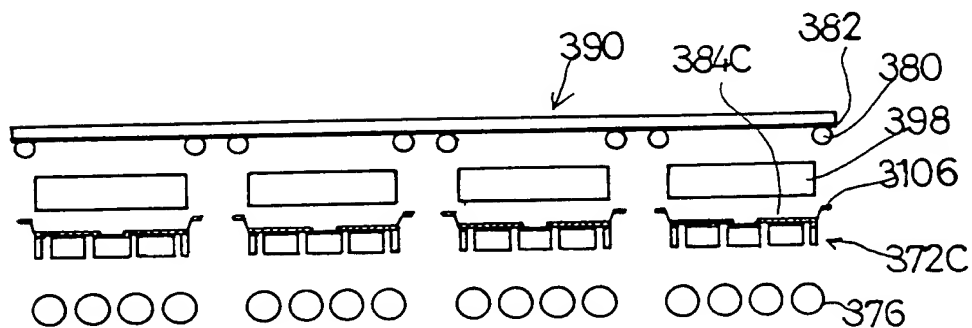


FIG. 168

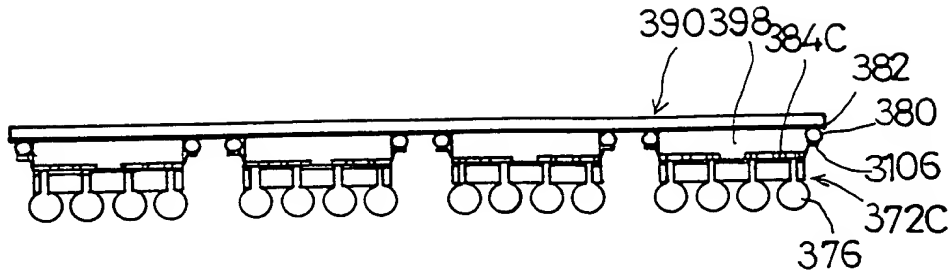


FIG. 169

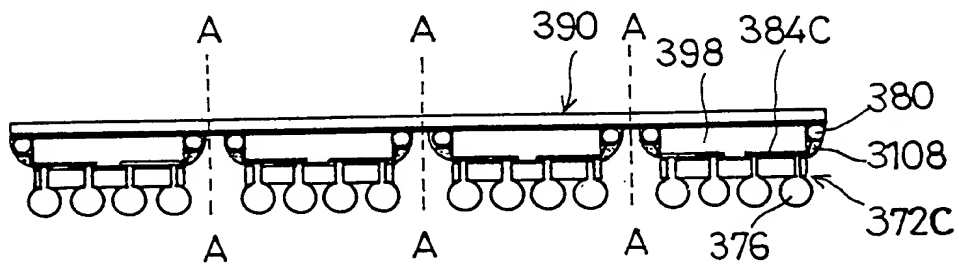


FIG. 170

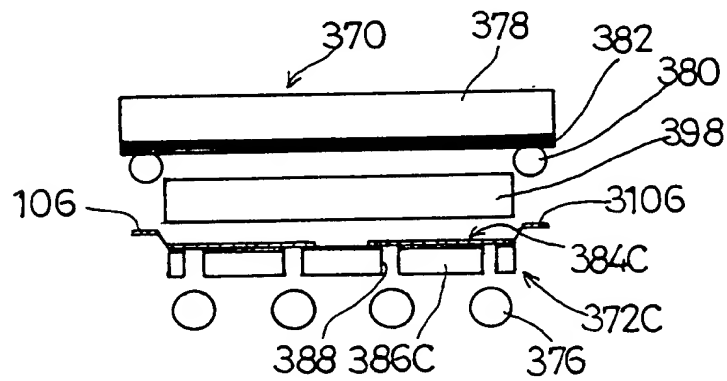


FIG. 171

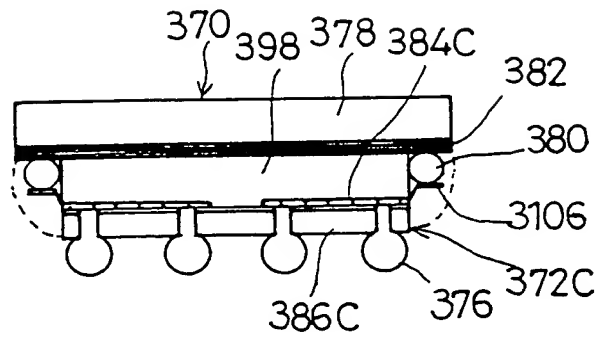
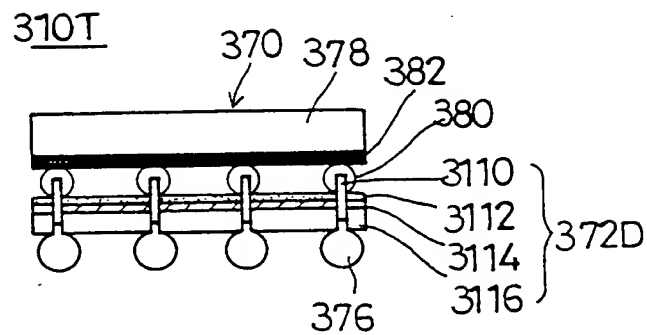


FIG. 172

( A )



( B )

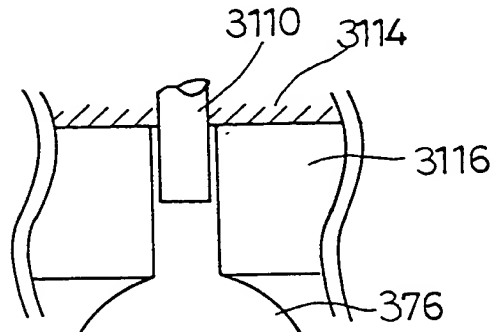


FIG. 173

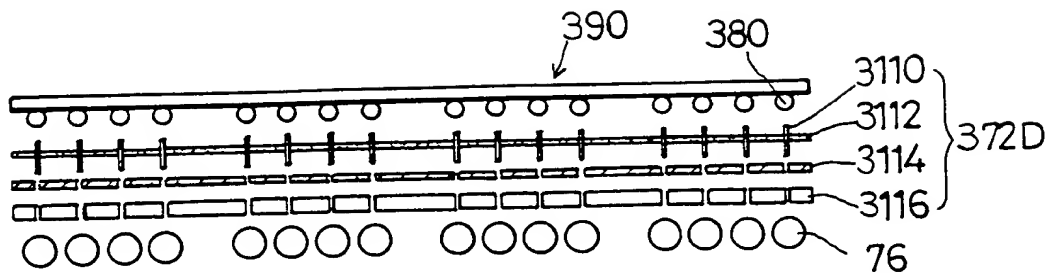


FIG. 174

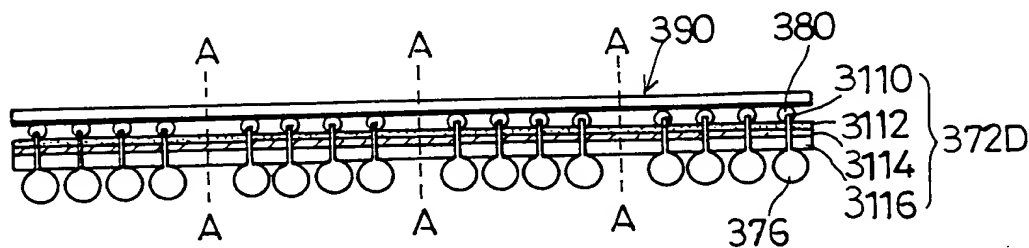


FIG. 175

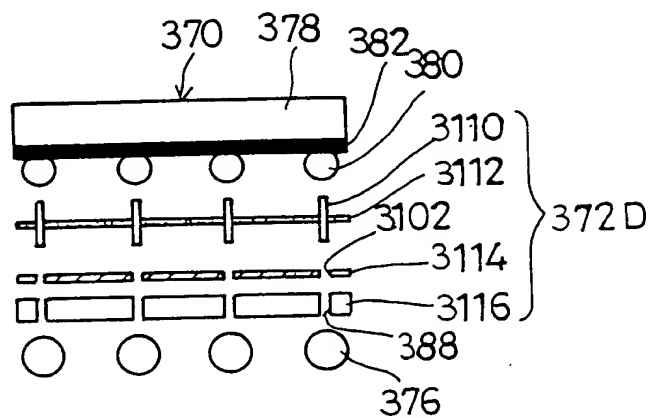


FIG. 176

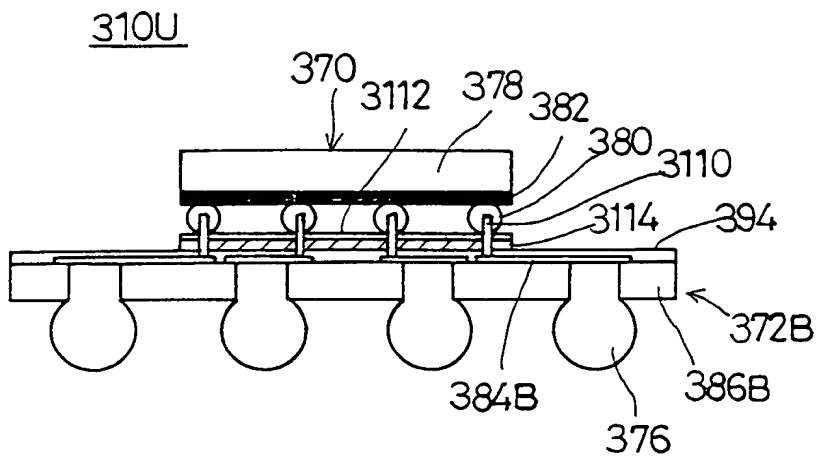


FIG. 177

